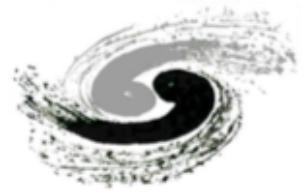


Performance of IHEP-IME LGAD sensors before and after irradiation

Xuewei Jia
on behalf of IHEP HGTD sensor group
2022/06/23



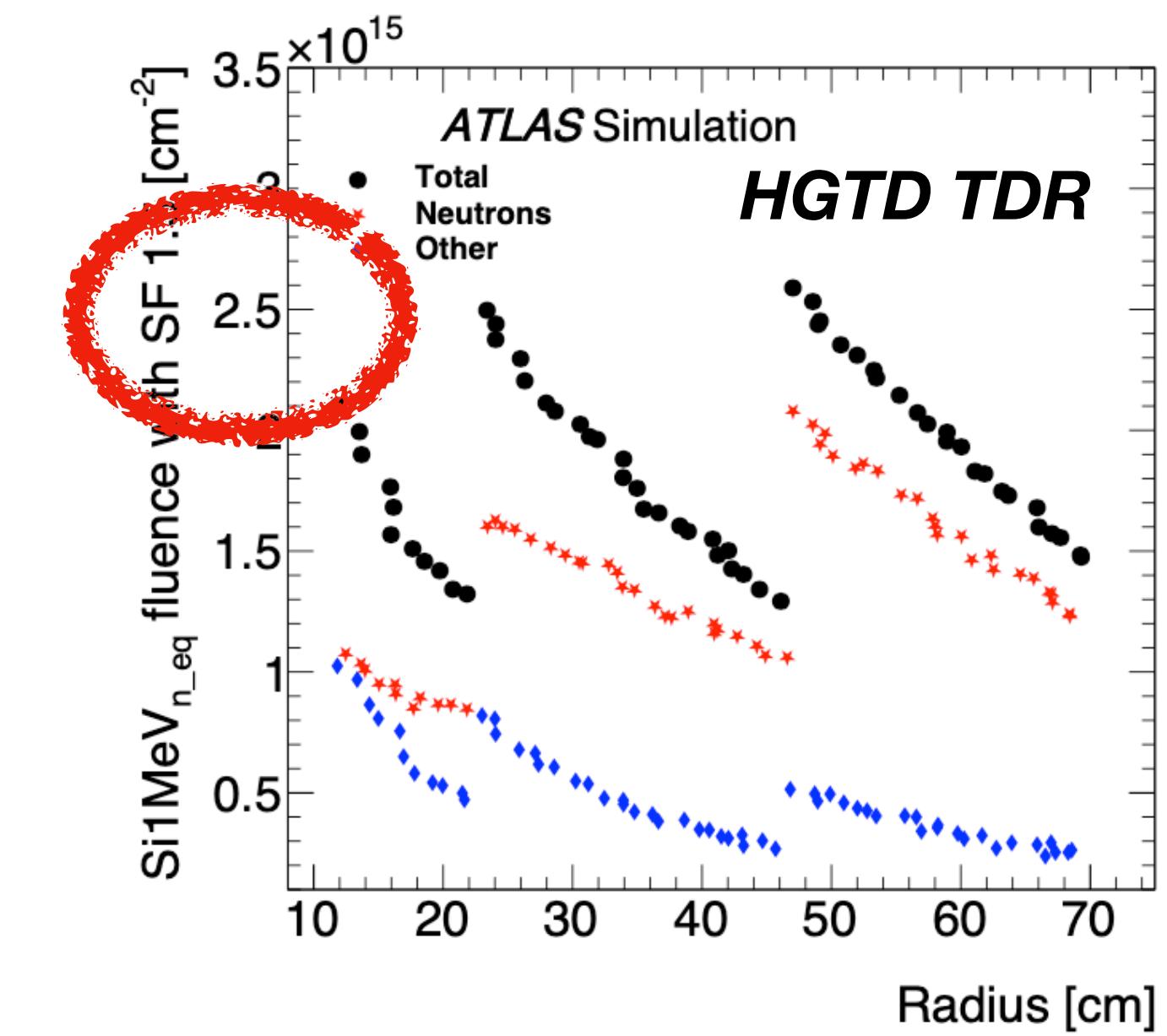
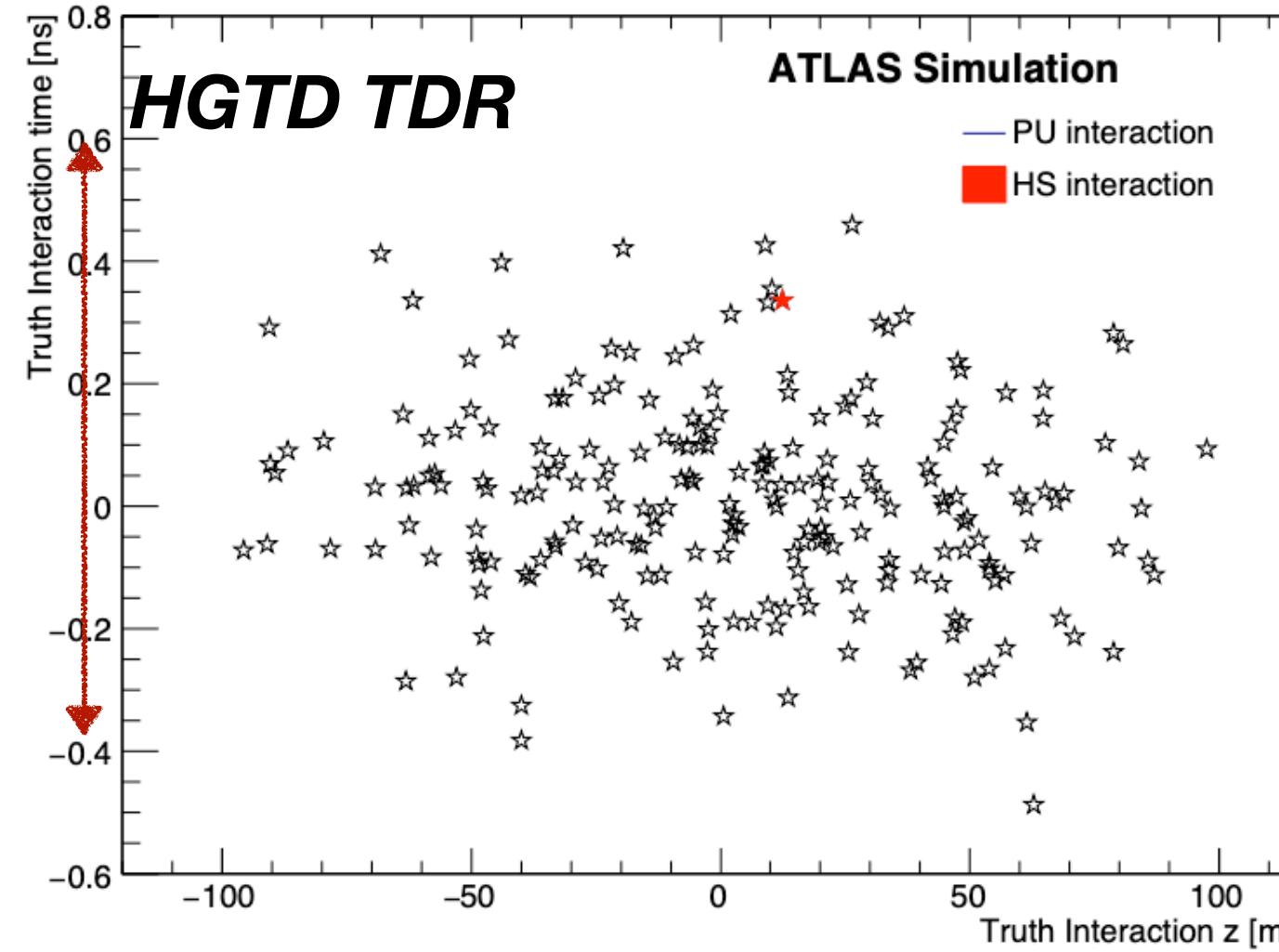
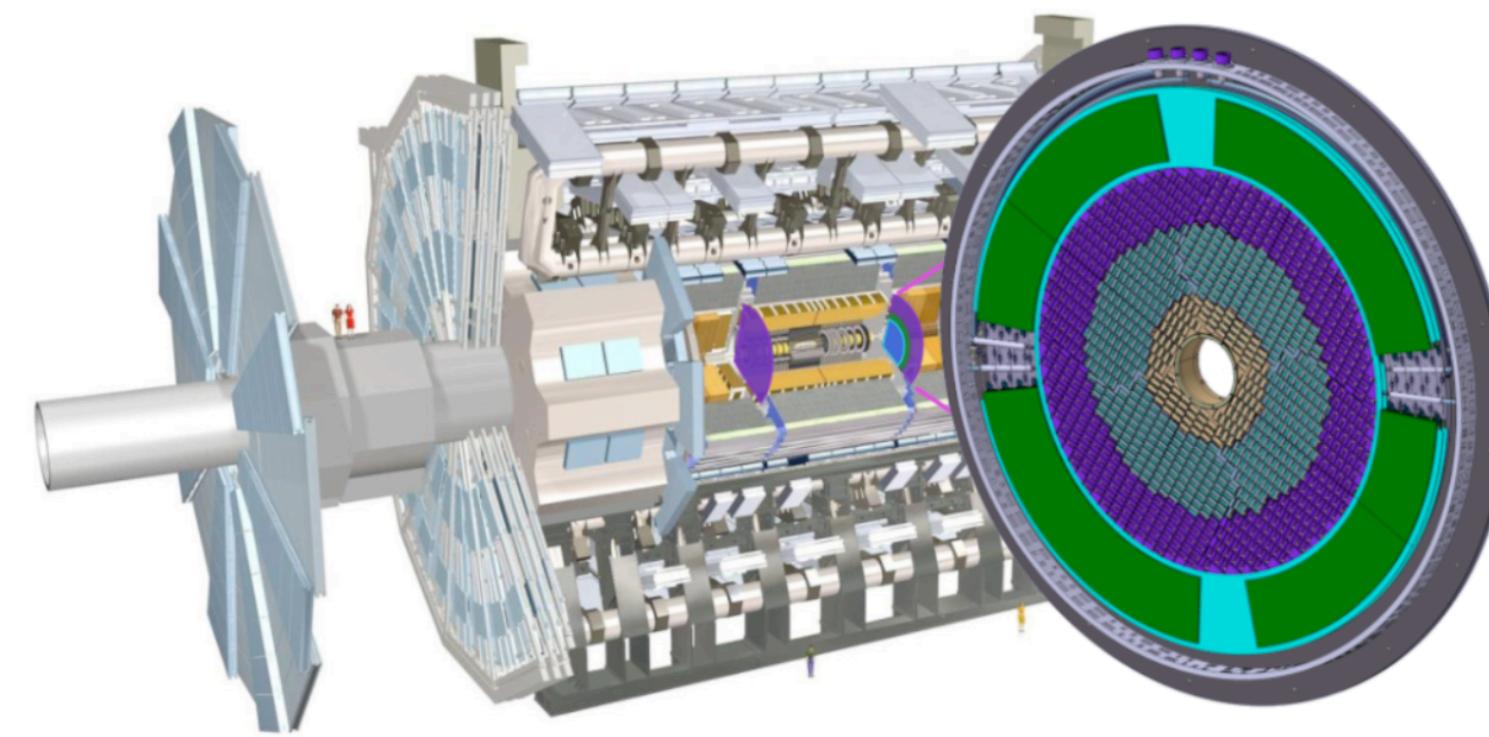
Outline

- 1. IHEP-IME LGAD for the ATLAS HGTD
- 2. IHEP-IME LGAD sensor performance
 - Before radiation
 - After radiation
- 3. Summary



HGTD introduction and sensor requirements

- High-Granularity Timing Detector(HGTD): proposed for ATLAS phase II upgrade, to reduce the pile-up effect. Better time resolution to resolve primary vertex.
- Aiming at 30~50 ps per track.
- LGAD will be used as its sensing technology to provide the good time resolution, segmented into $1.3 \times 1.3 \text{ mm}^2$ pads, with a total of 15x15 pads per sensor. The sensor need survive in high irradiation environment.



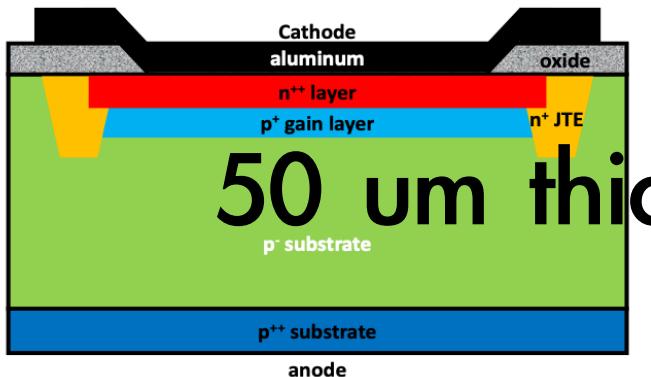
Introduction of IHEP-IME LGAD



- **IHEP-IME**: Designed by IHEP, fabricated by the Institute of Microelectronics of Chinese Academy of Sciences (IME) for the HGTD project
- So far three versions of IHEP-IME has been produced.
 - IHEP-IMEv1 was submitted in May 2020, finished in September
 - **IHEP-IMEv2** was produced in January 2021 finished June 2021, outstanding results, especially on the radiation hardness.
 - IHEP-IMEv3 first batch was produced in March 2022, to further confirm and repeat what we achieved



Introduction of IHEP-IME LGAD



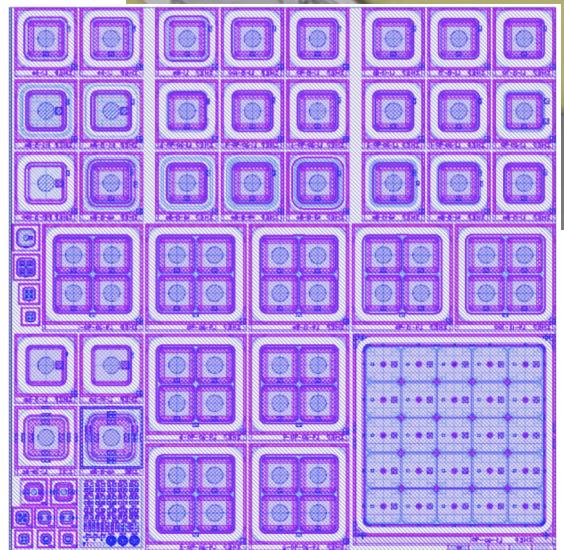
50 μm thick LGAD

p++ substrate
anode

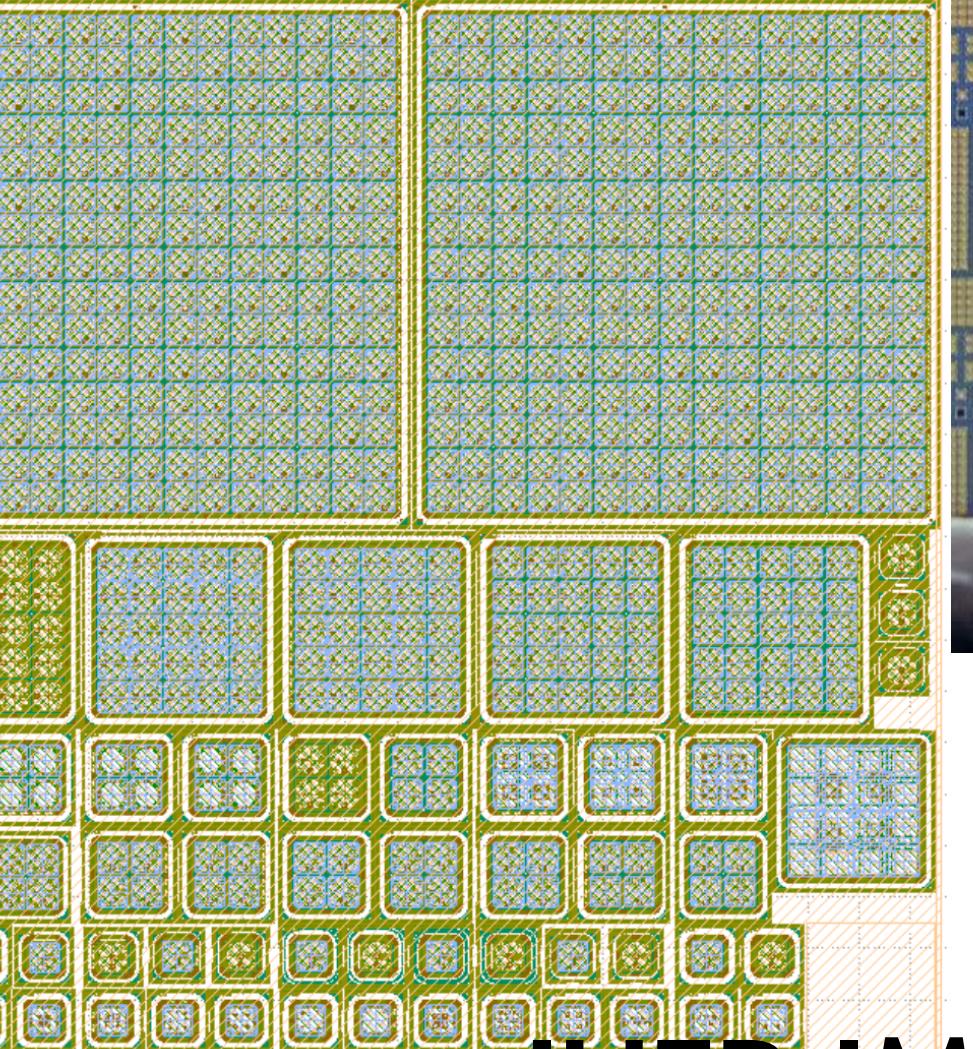
cathode
aluminum
oxide
n++ layer
p+ gain layer
n+ JTE

8 inch wafer
2020

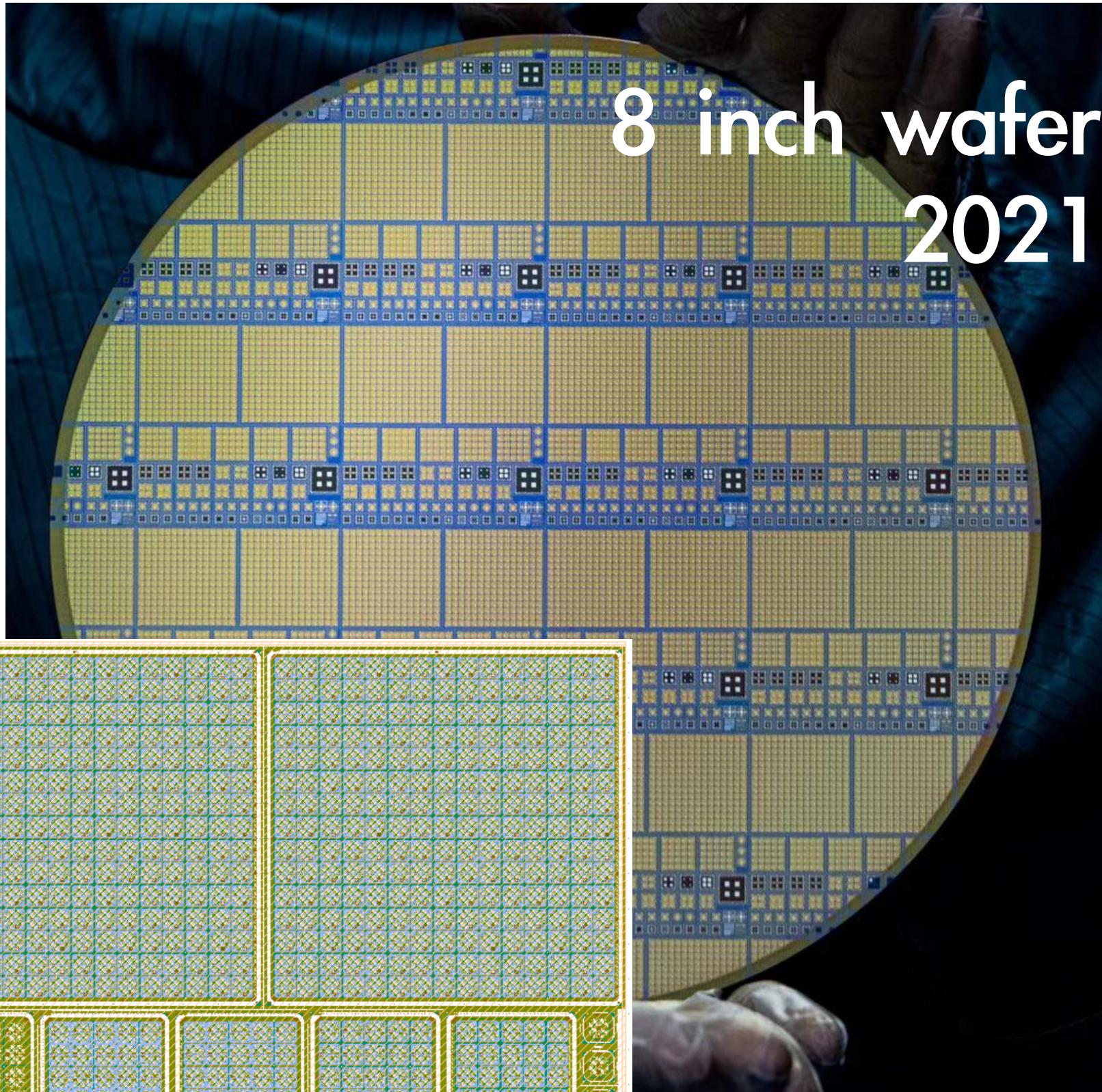
IV
I
III
II



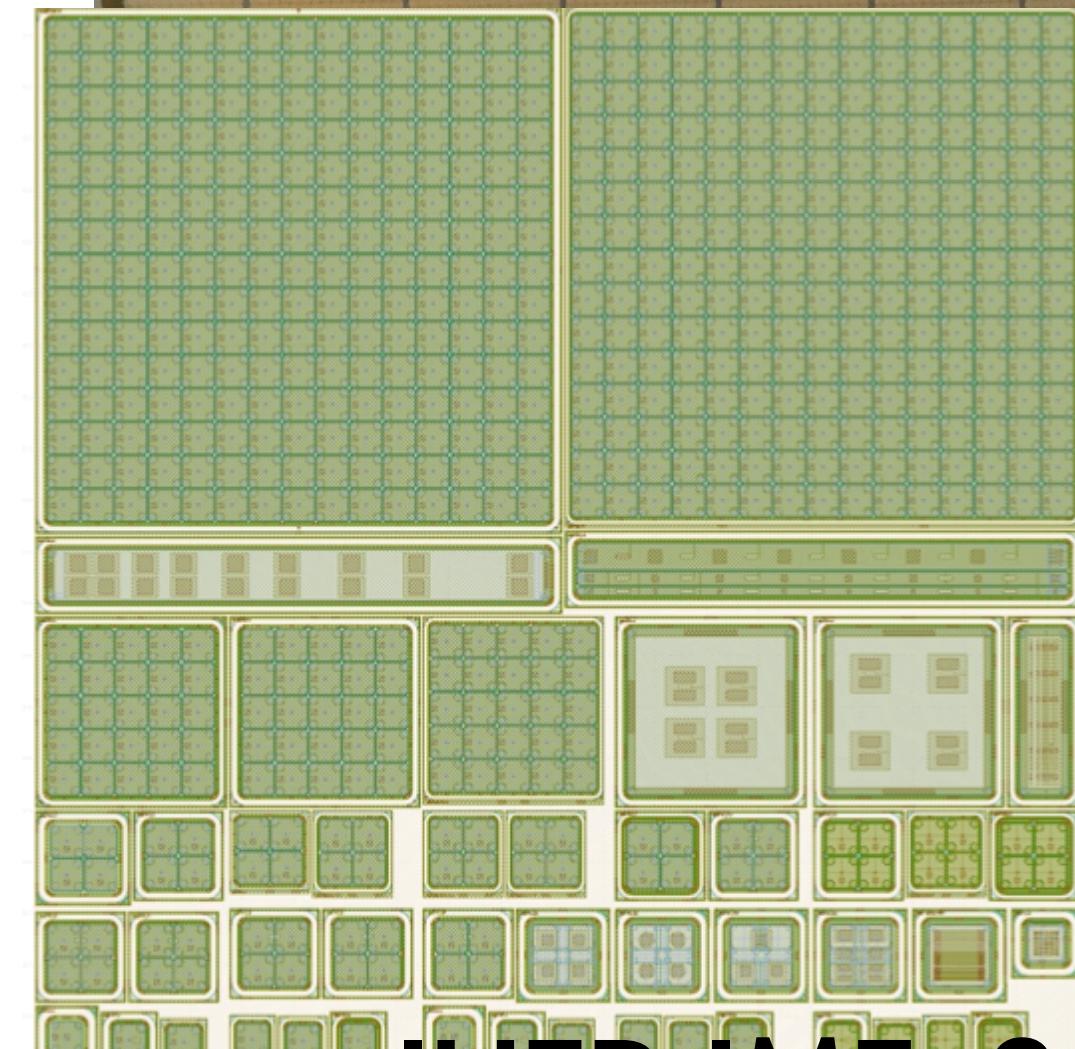
IHEP-IMEv1 layout



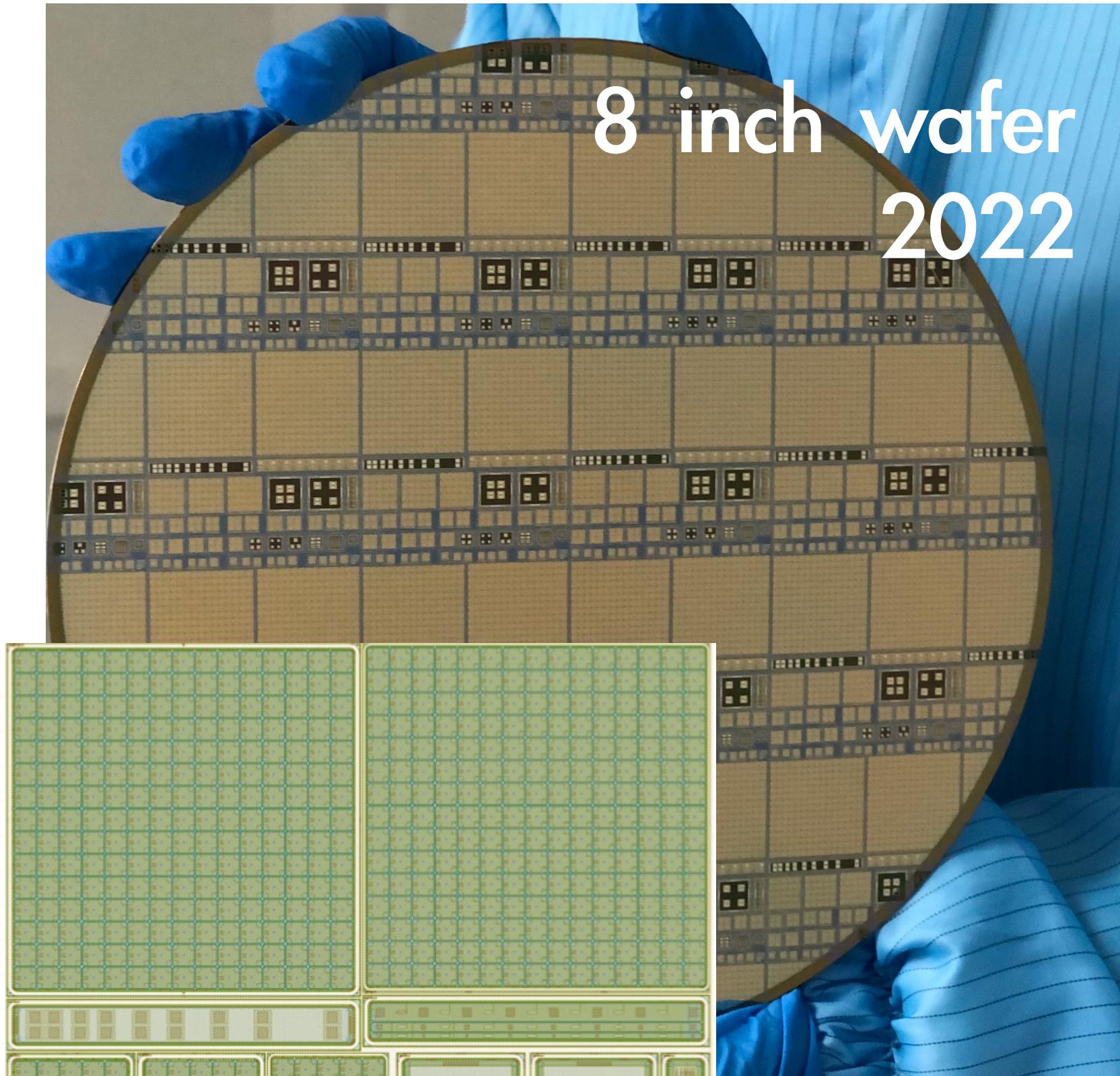
IHEP-IMEv2 layout



8 inch wafer
2021



IHEP-IMEv3 layout

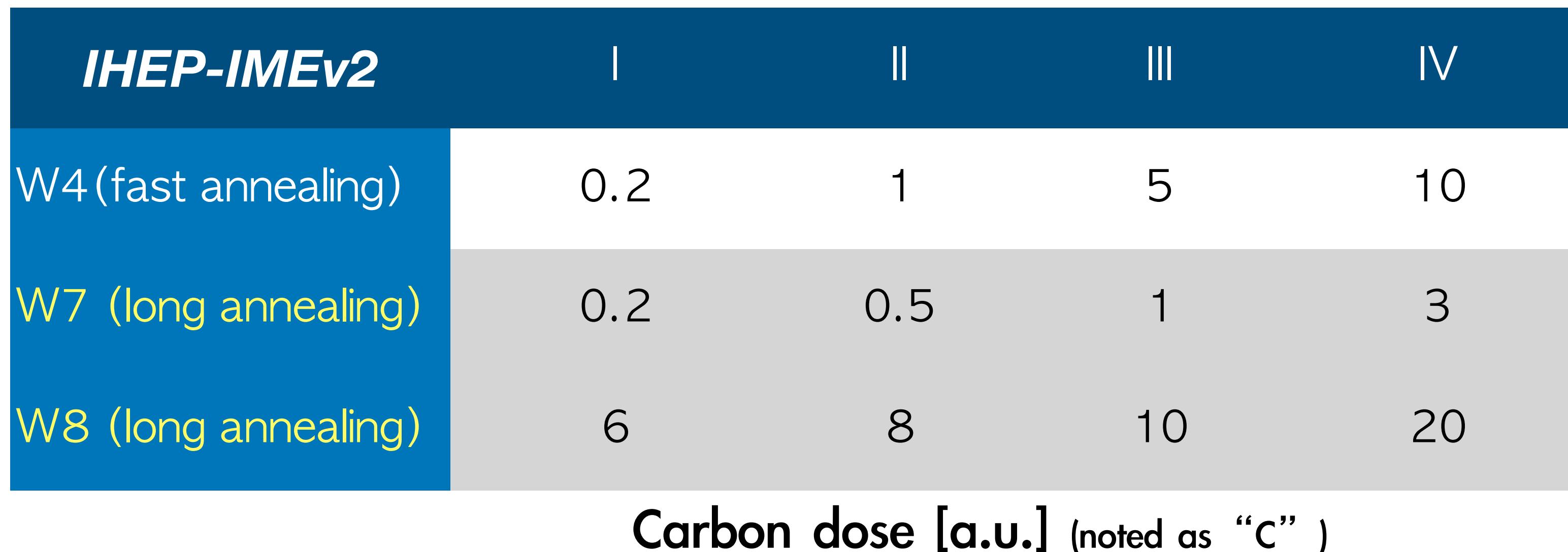
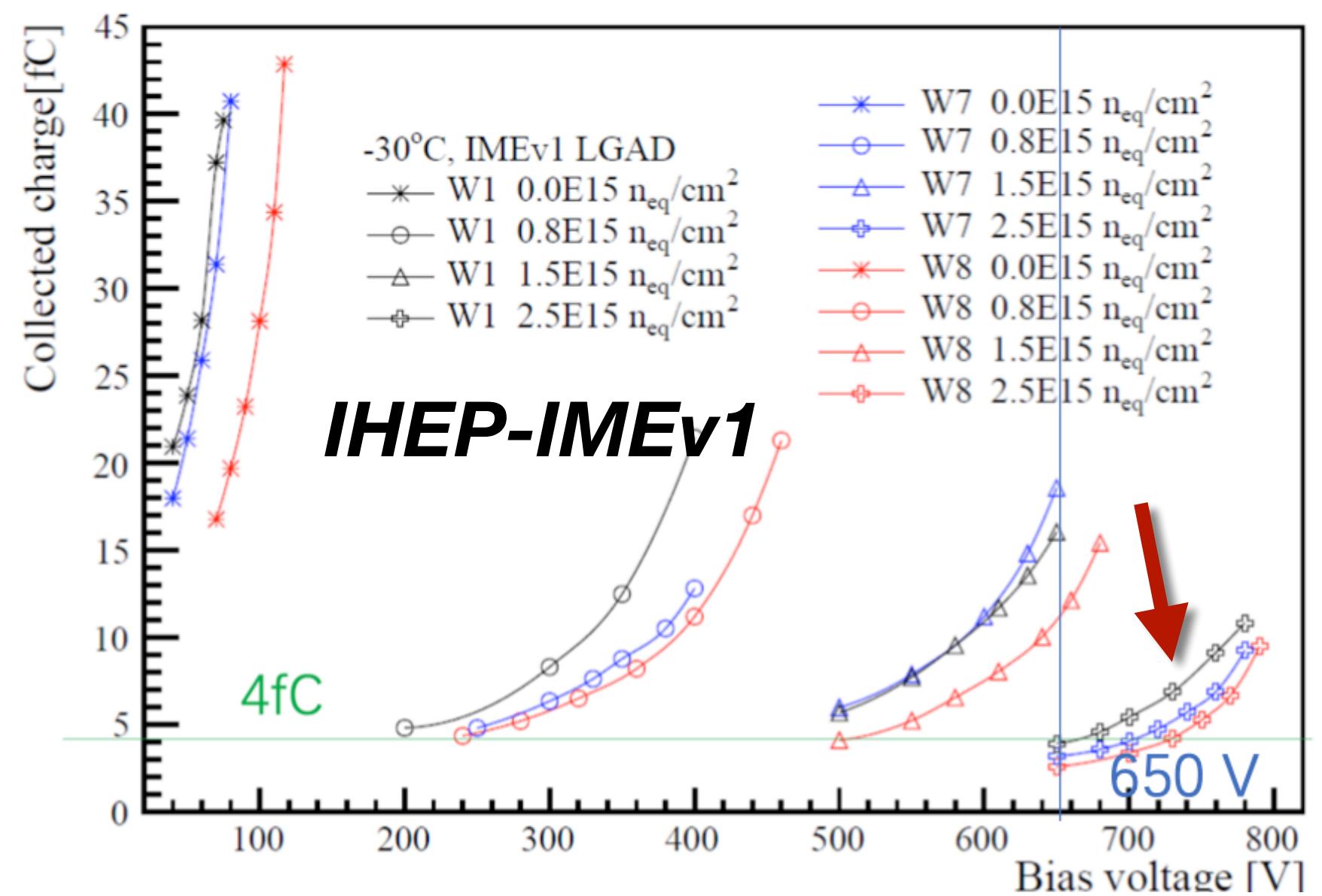


8 inch wafer
2022



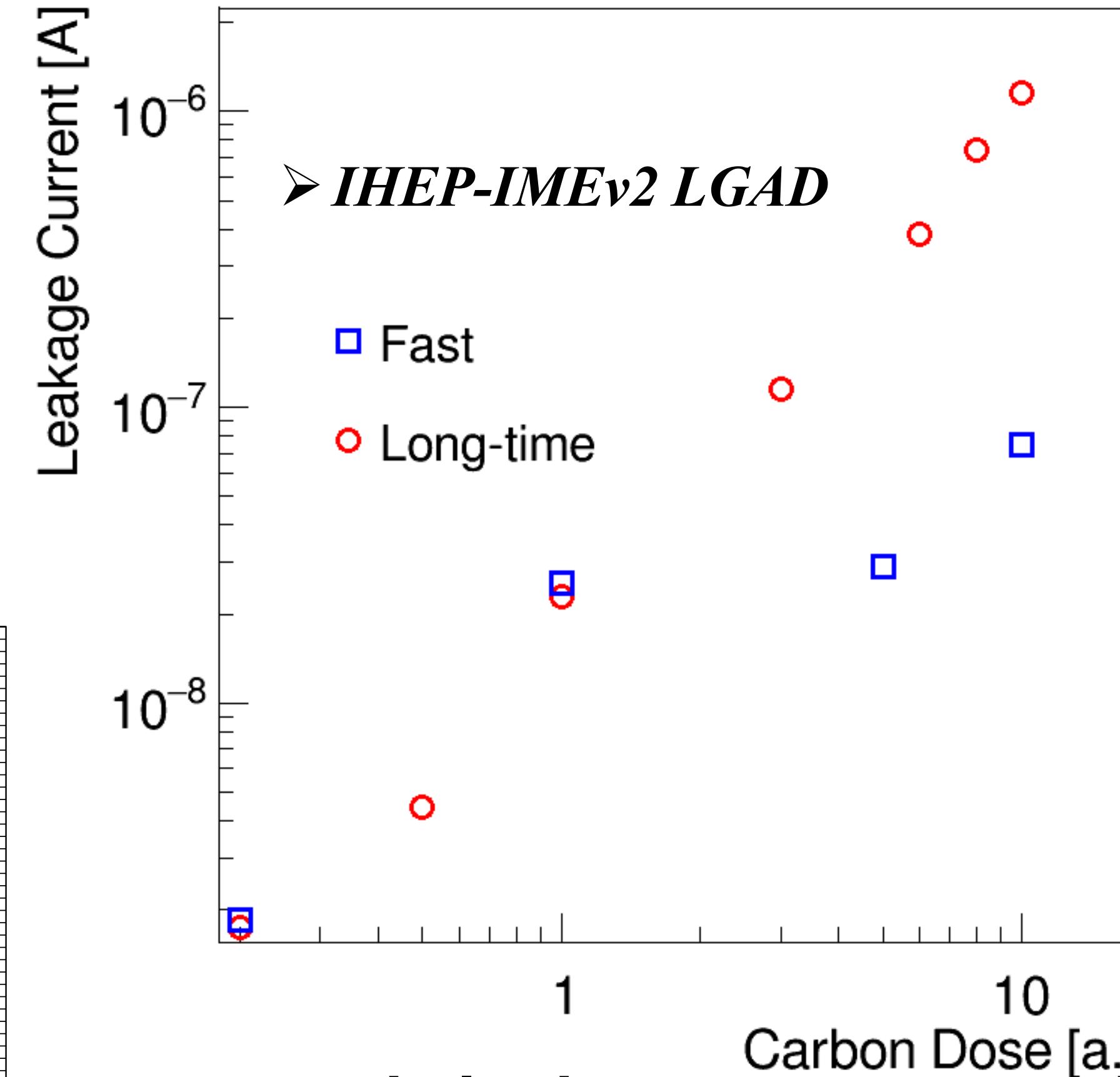
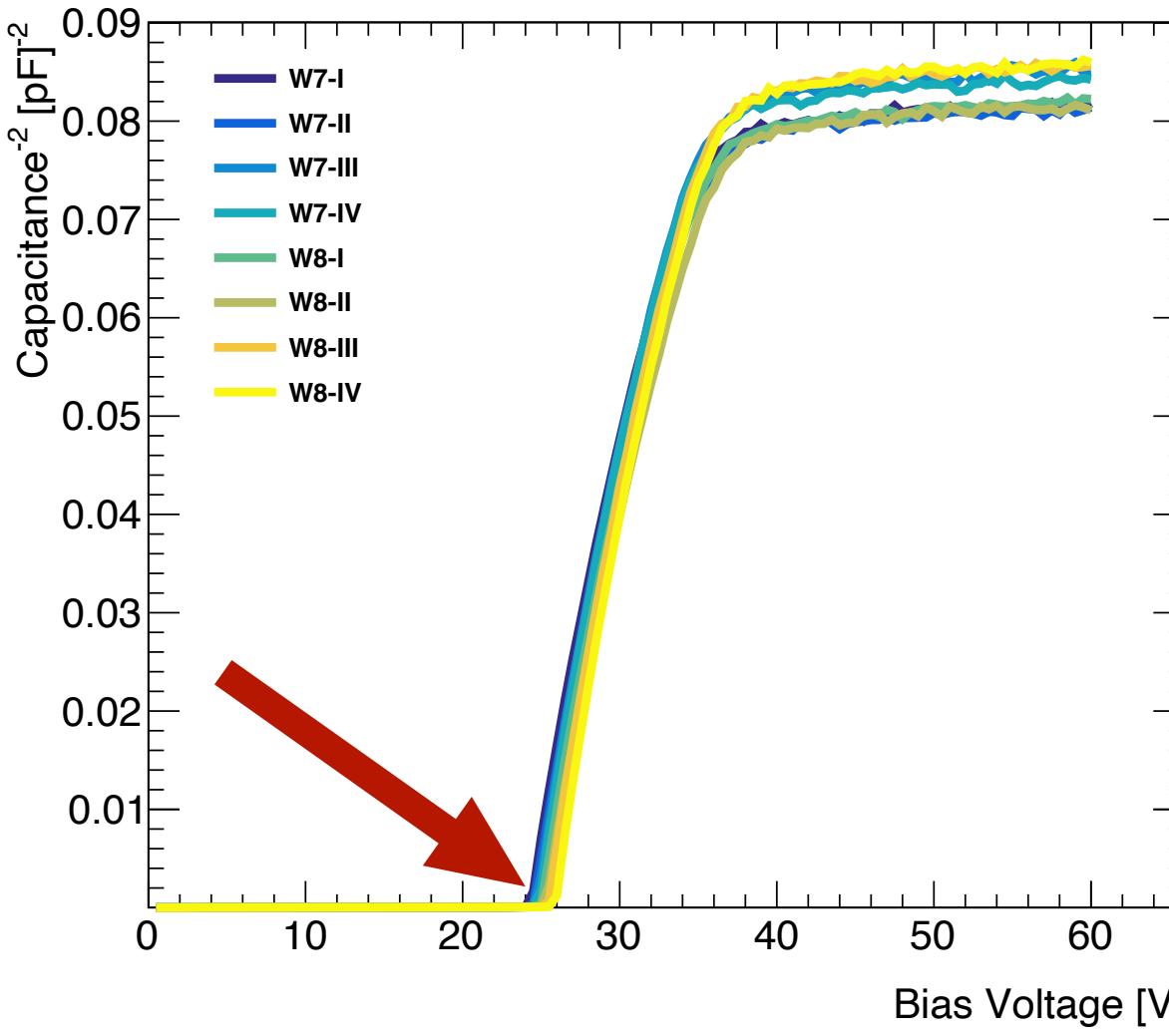
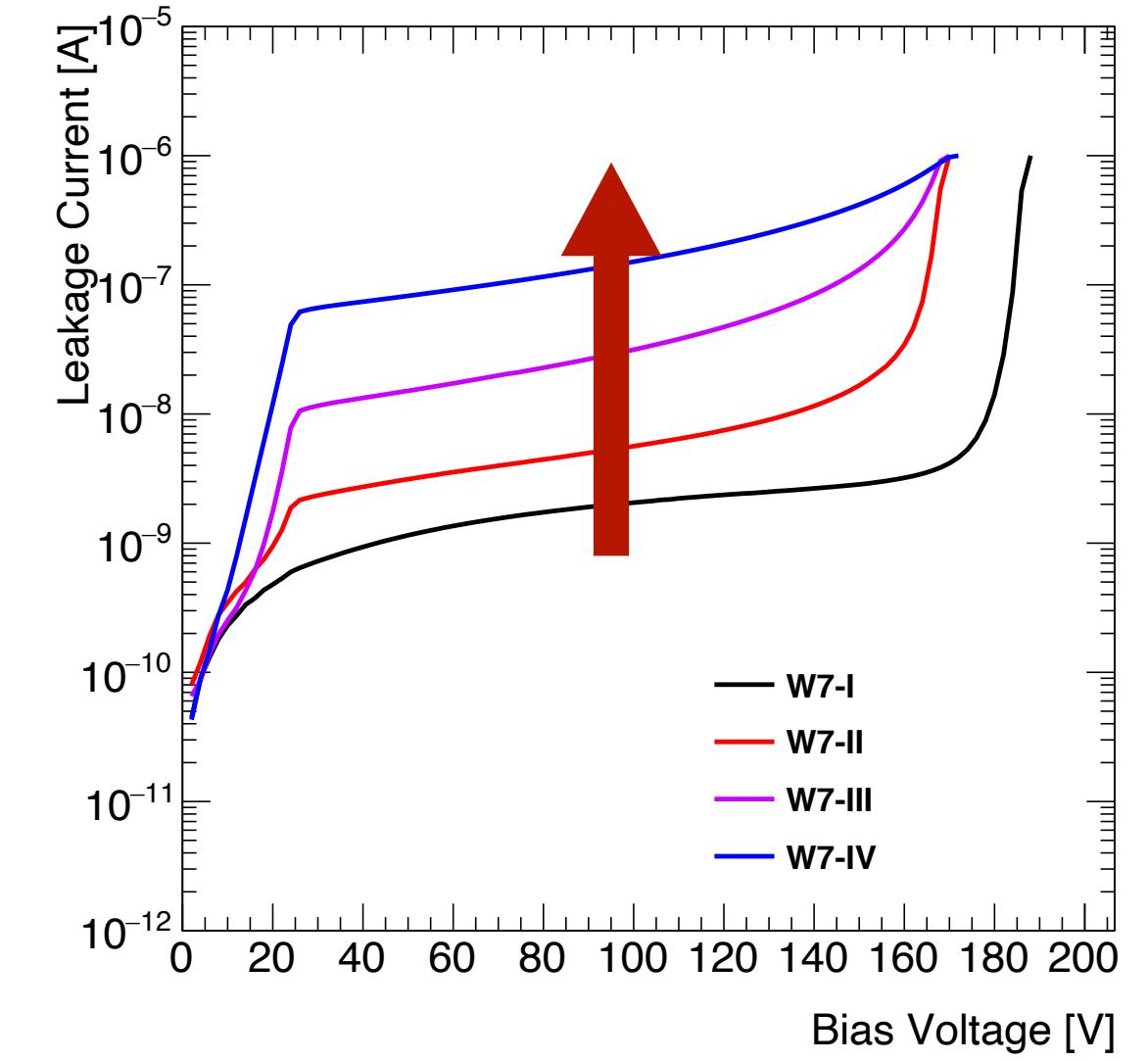
Carbon implantation

- In IHEP-IMEv1, Wafer 1 was implanted with carbon with low dose and low energy. Better radiation hardness observed than the ones without.
- In IHEP-IMEv2, various carbon dose and thermal process were studied to improve the sensors' radiation hardness.

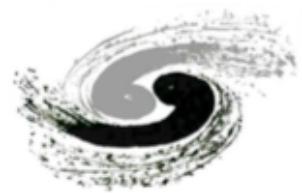




Before radiation - single pad

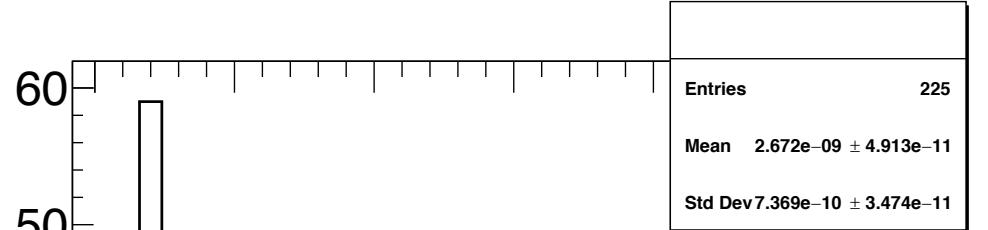
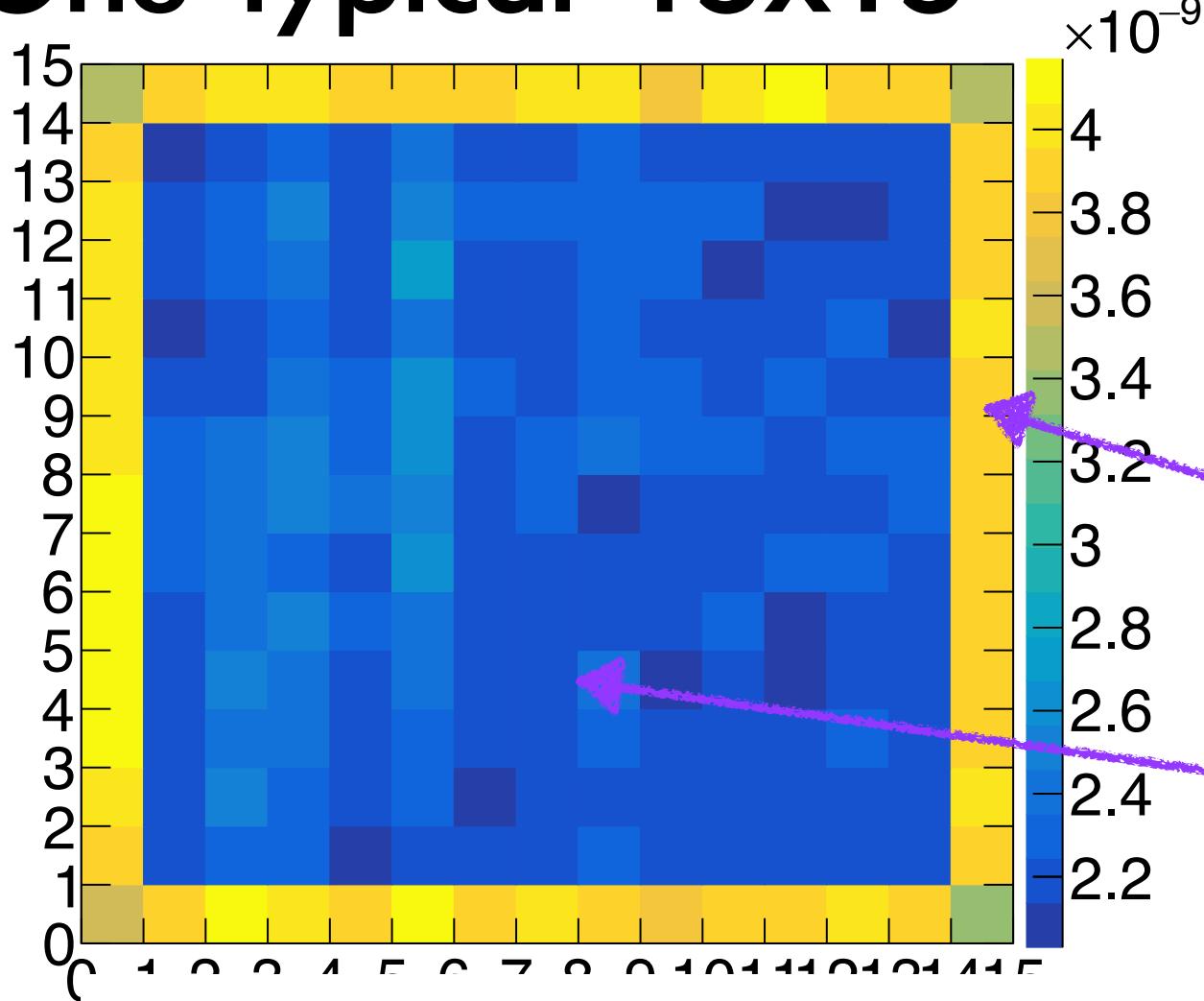


Both leakage current and gain layer depletion voltage increase with the carbon dose.



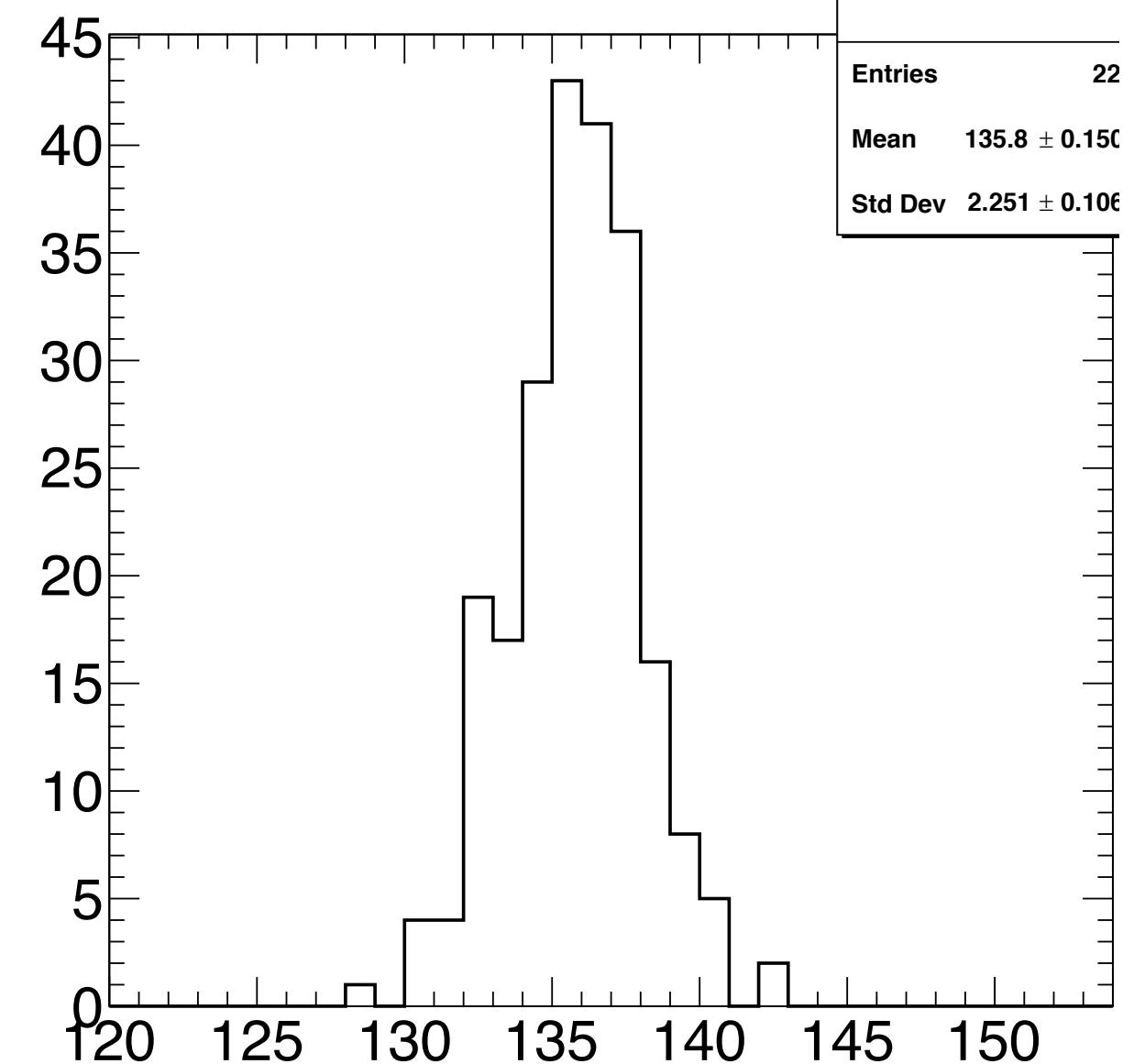
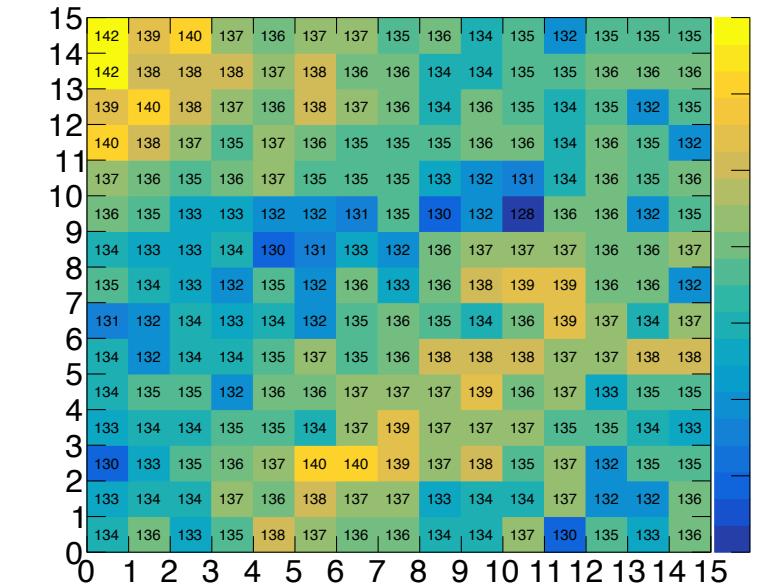
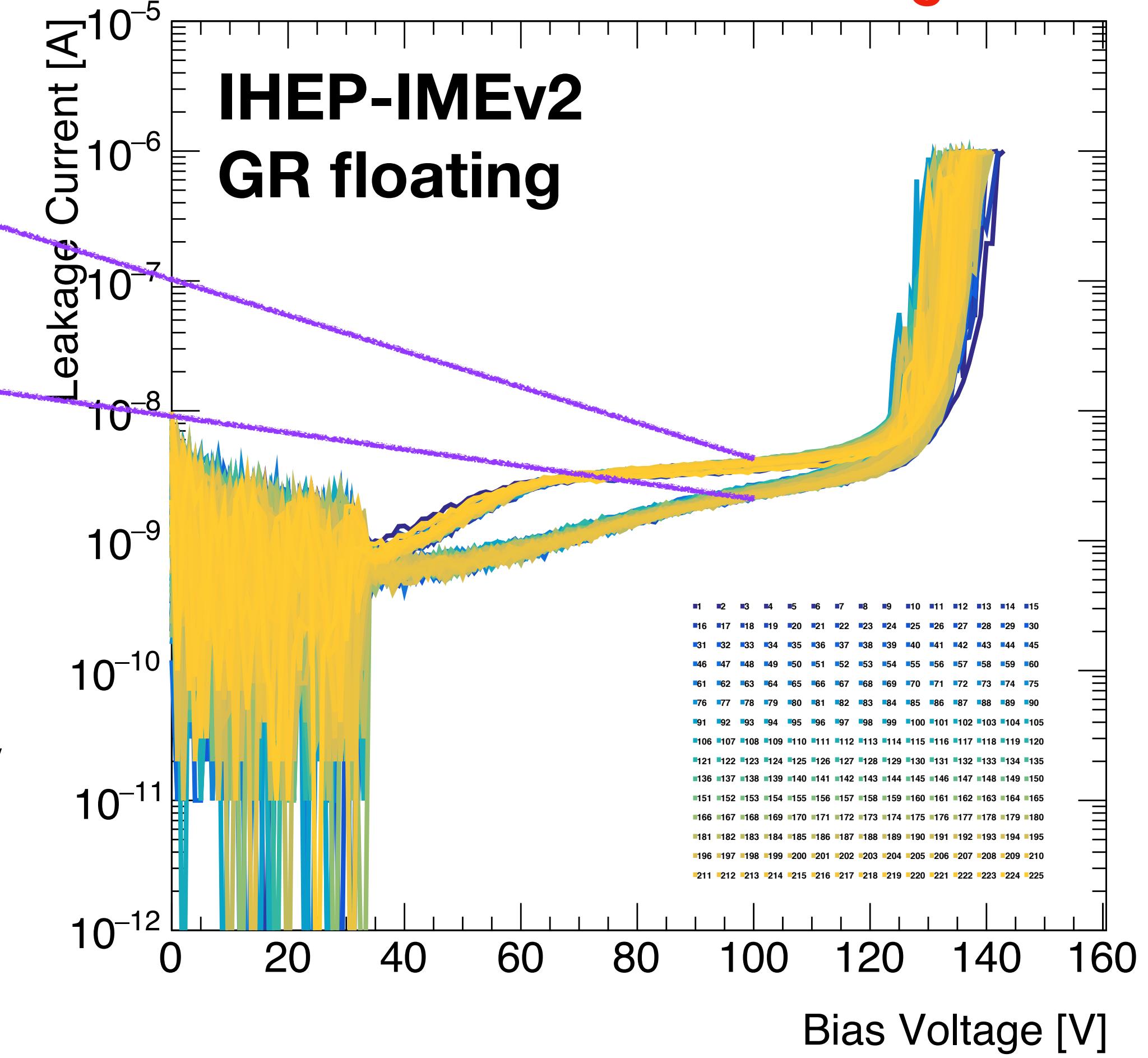
Large array sensor before radiation

One typical 15x15



Leakage current at 100 V

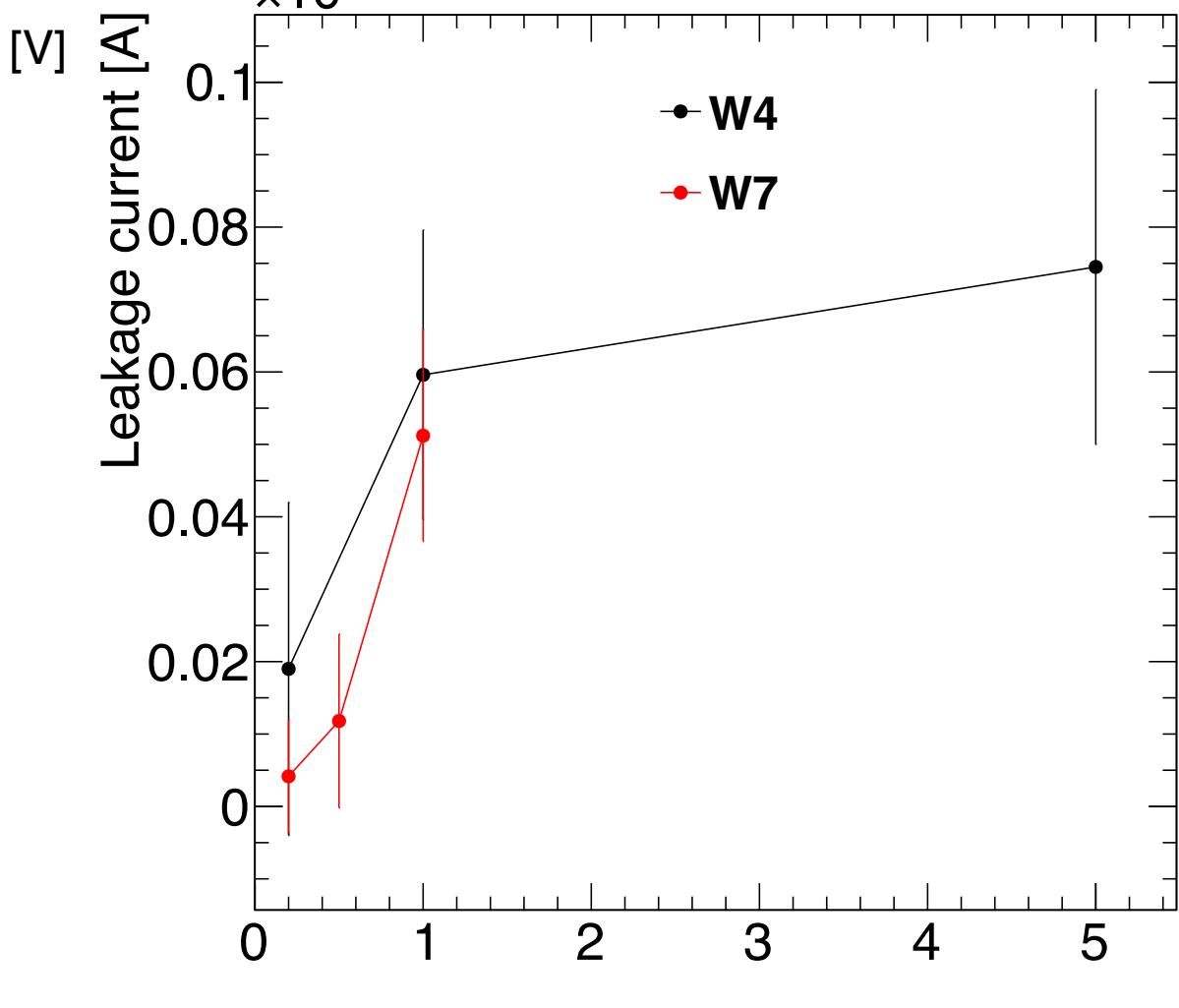
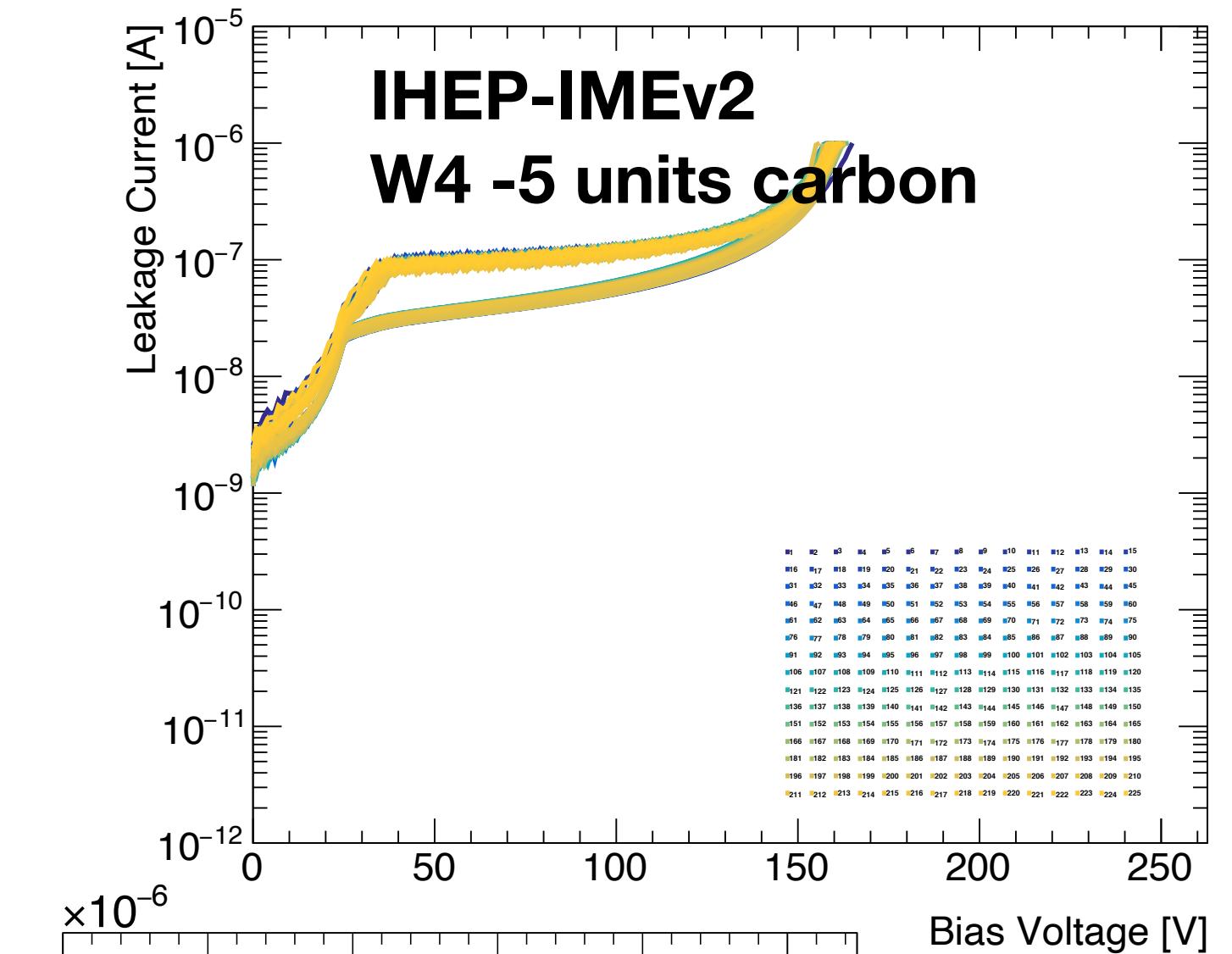
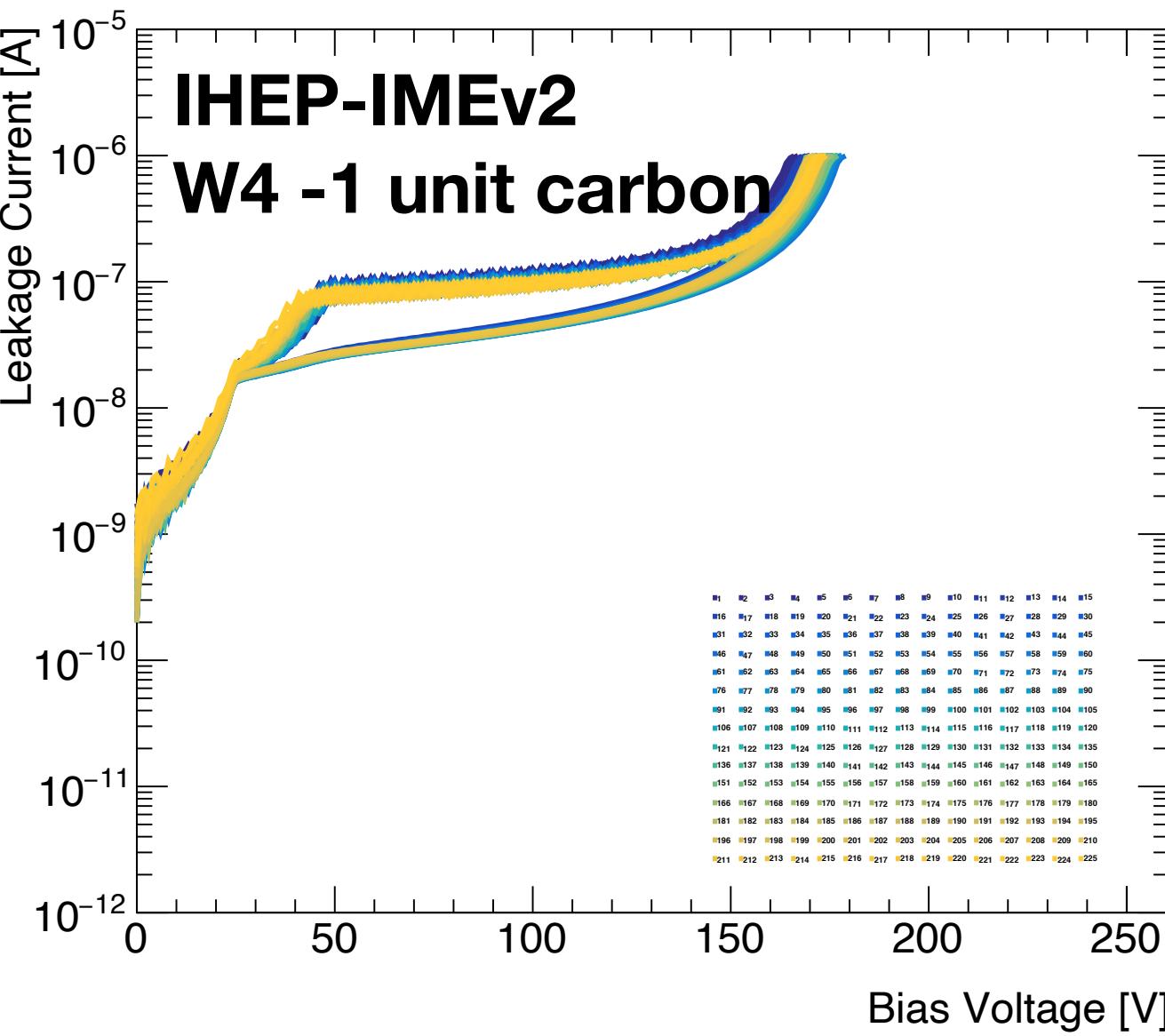
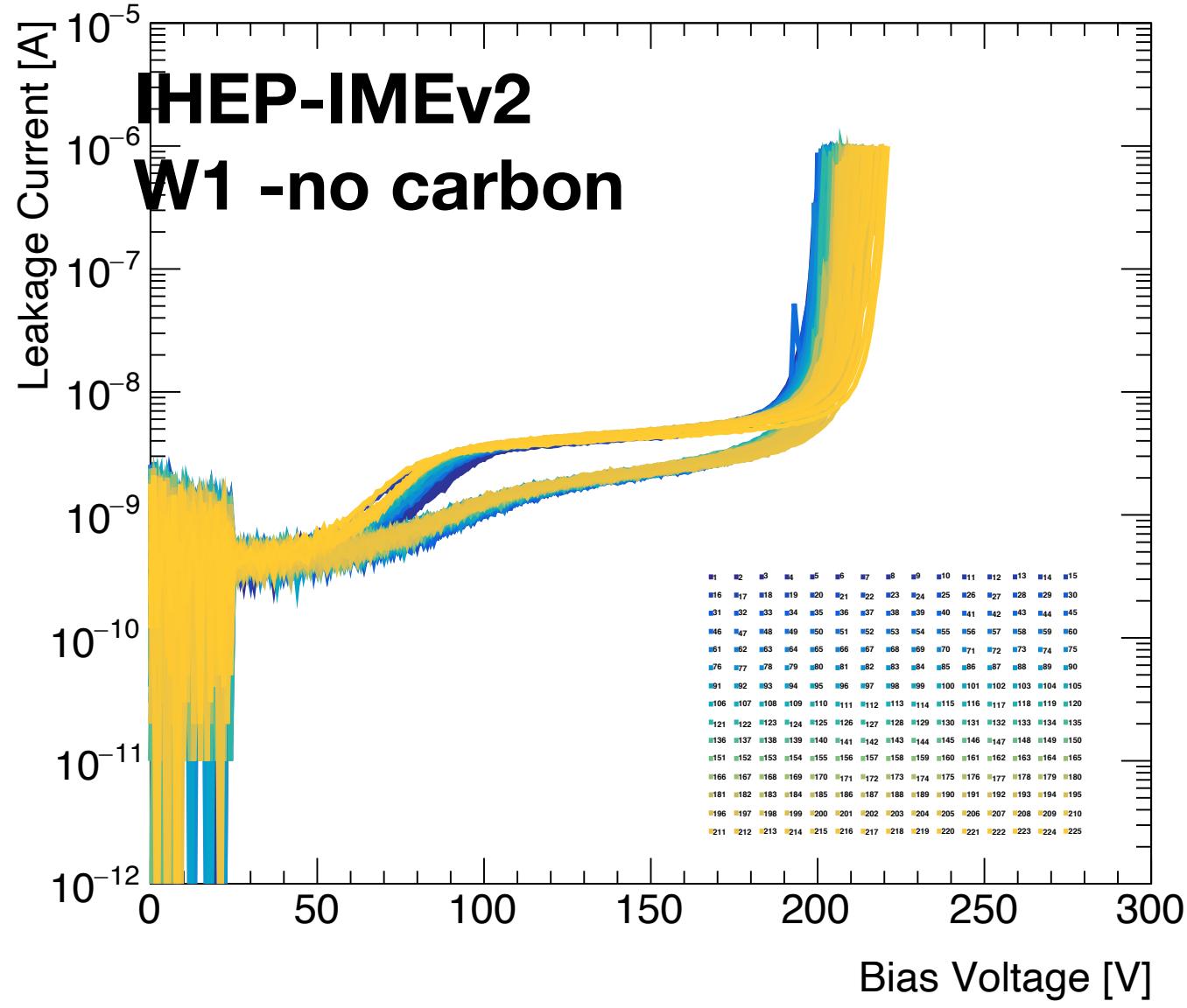
Breakdown voltage and leakage current
of full size sensor showed good uniformity





Large array sensor before radiation

Before irradiation 15x15:

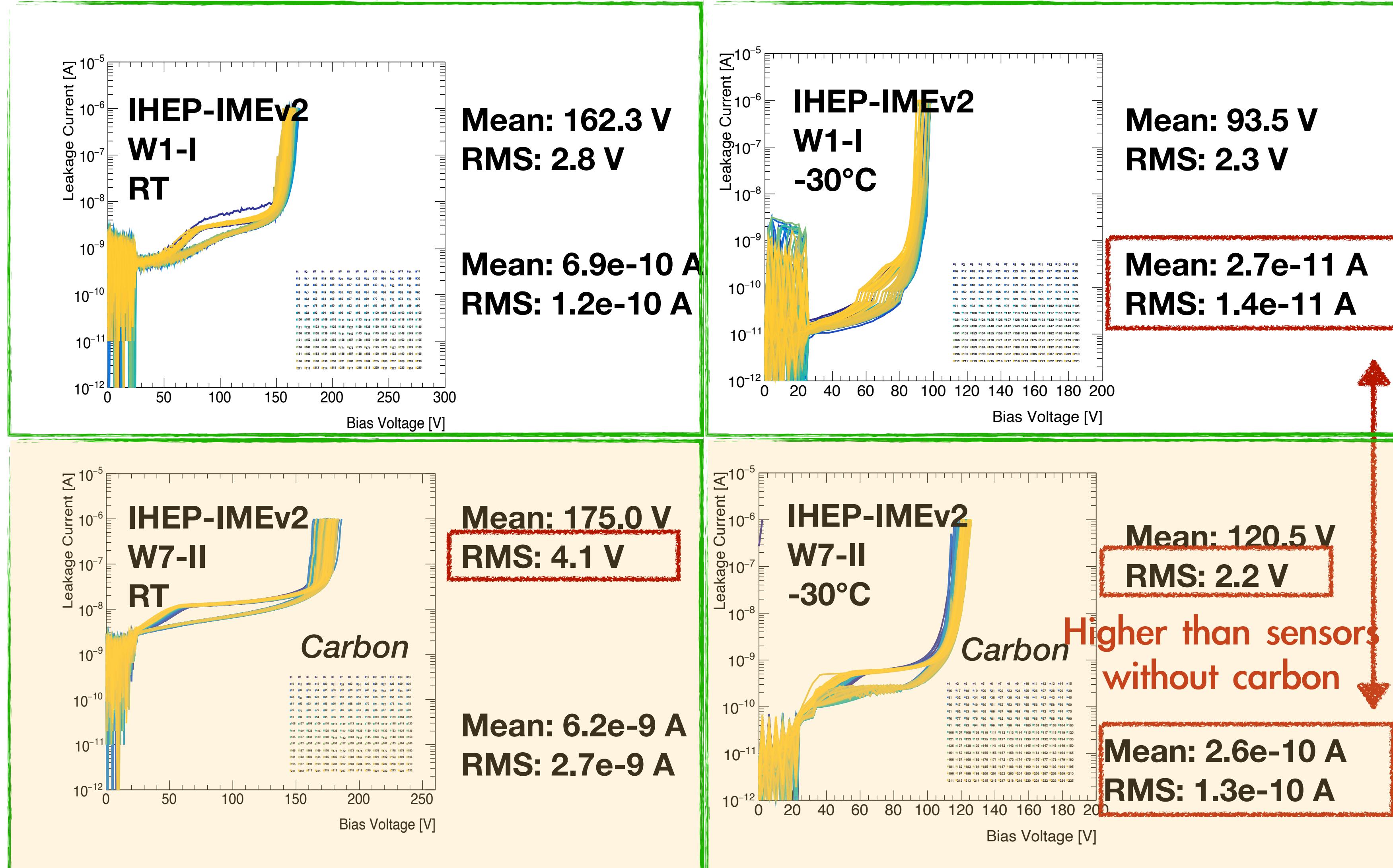


When carbon dose increase, the breakdown voltages decrease and the leakage currents increase.



Large array sensor before radiation

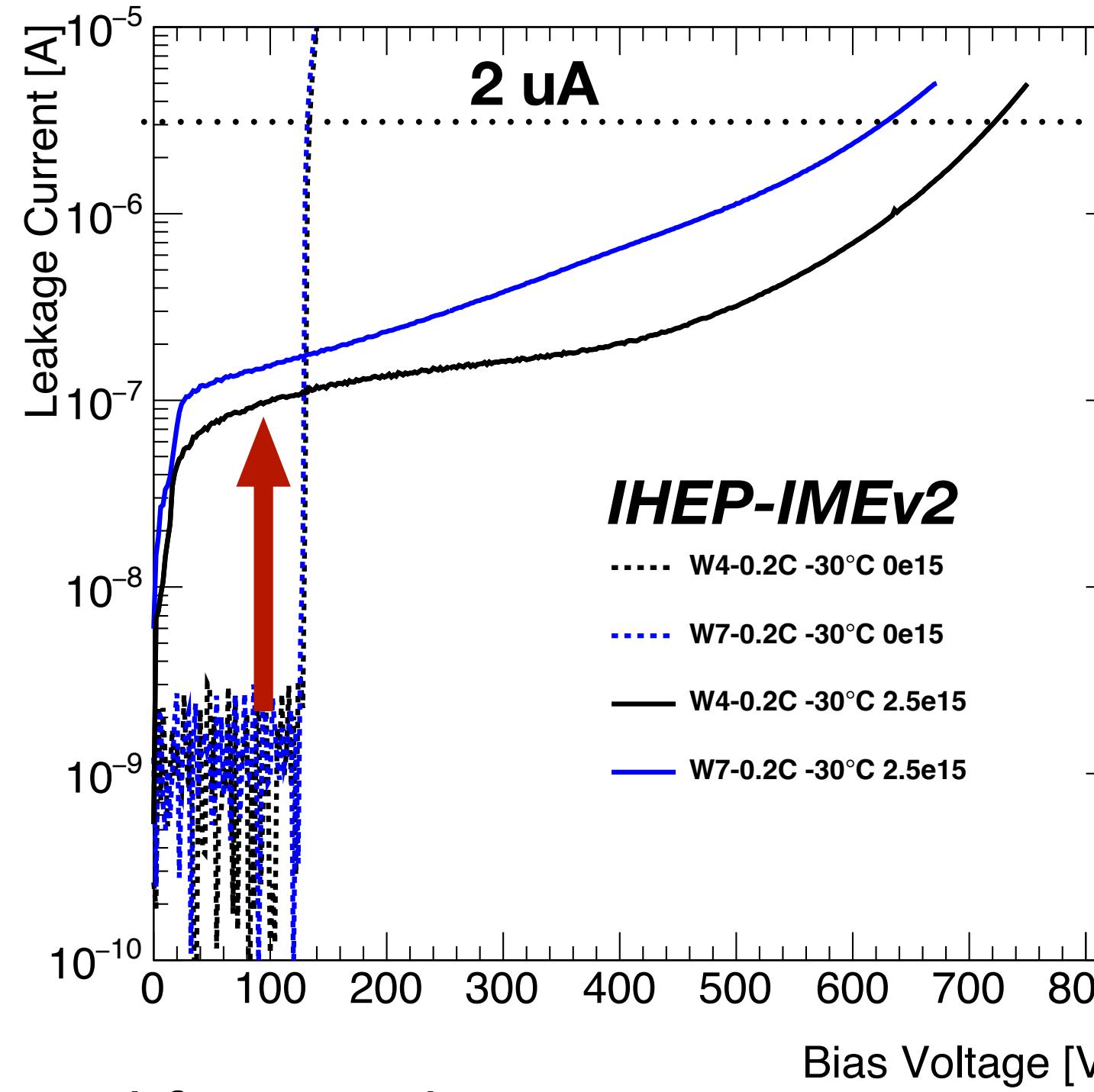
- Lower leakage current and breakdown voltage at -30°C
- Better uniformity at -30°C
- At -30°C, carbon implanted sensor still has higher leakage current.





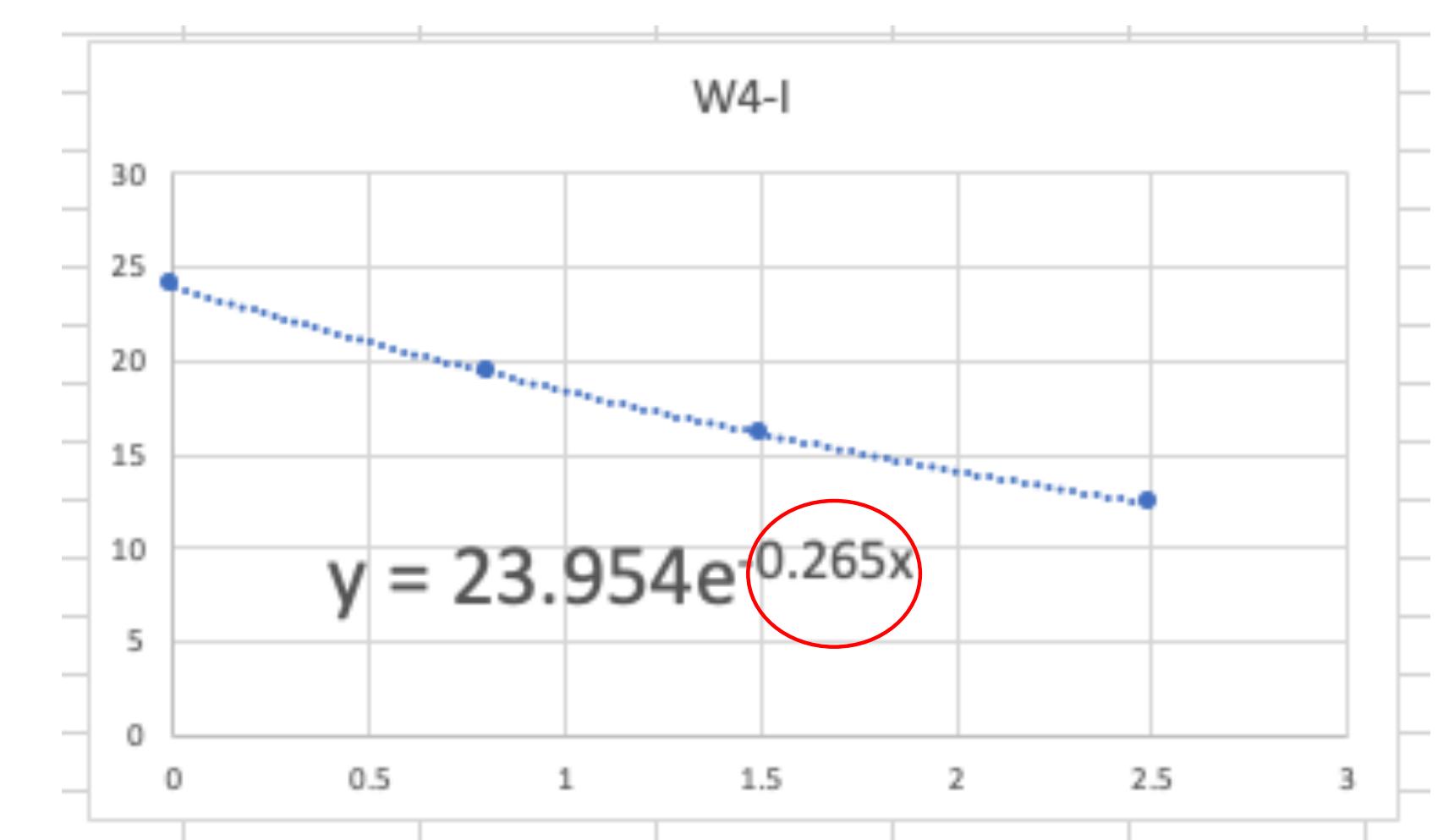
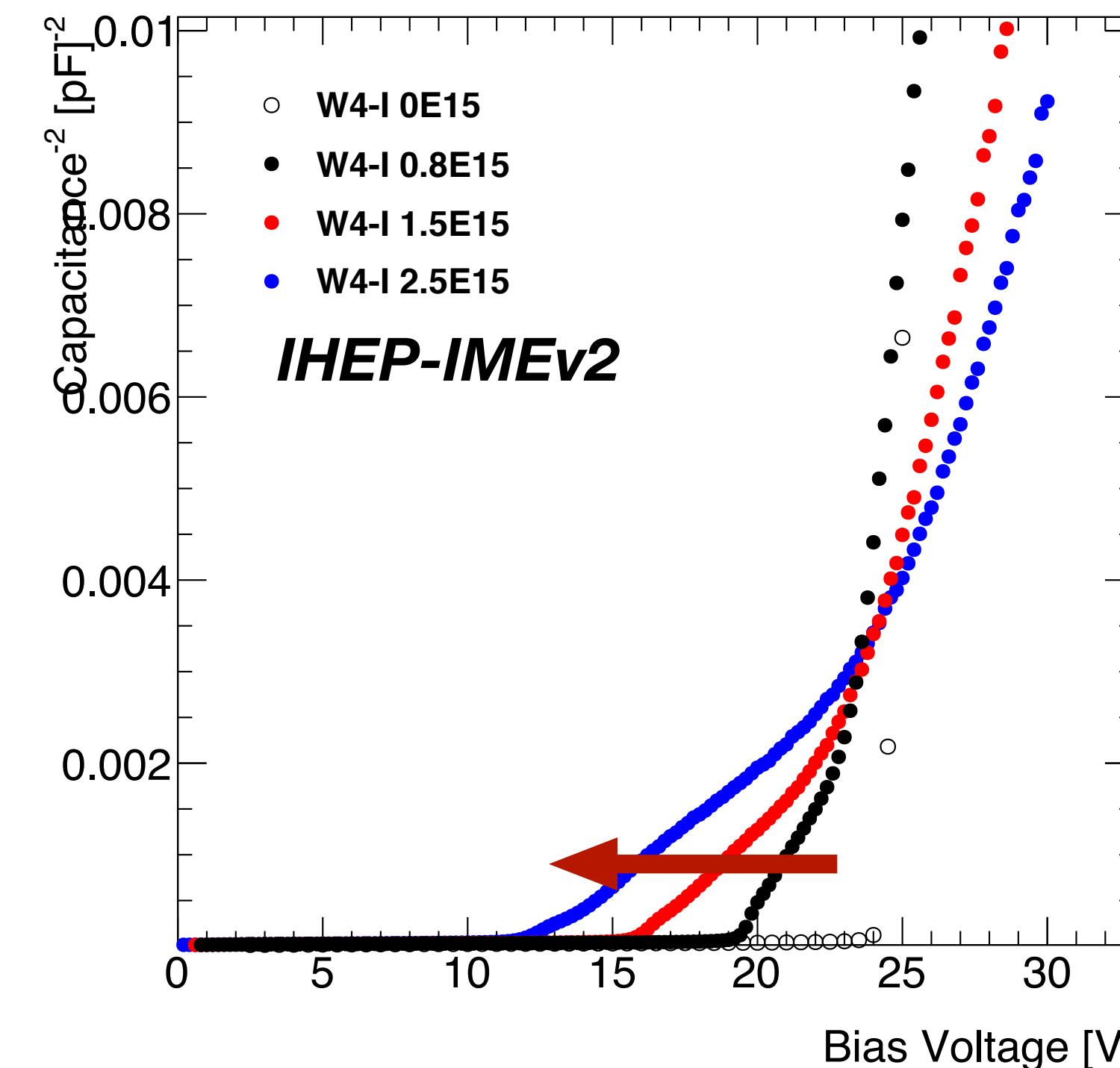
After radiation

IHEP-IMEv2



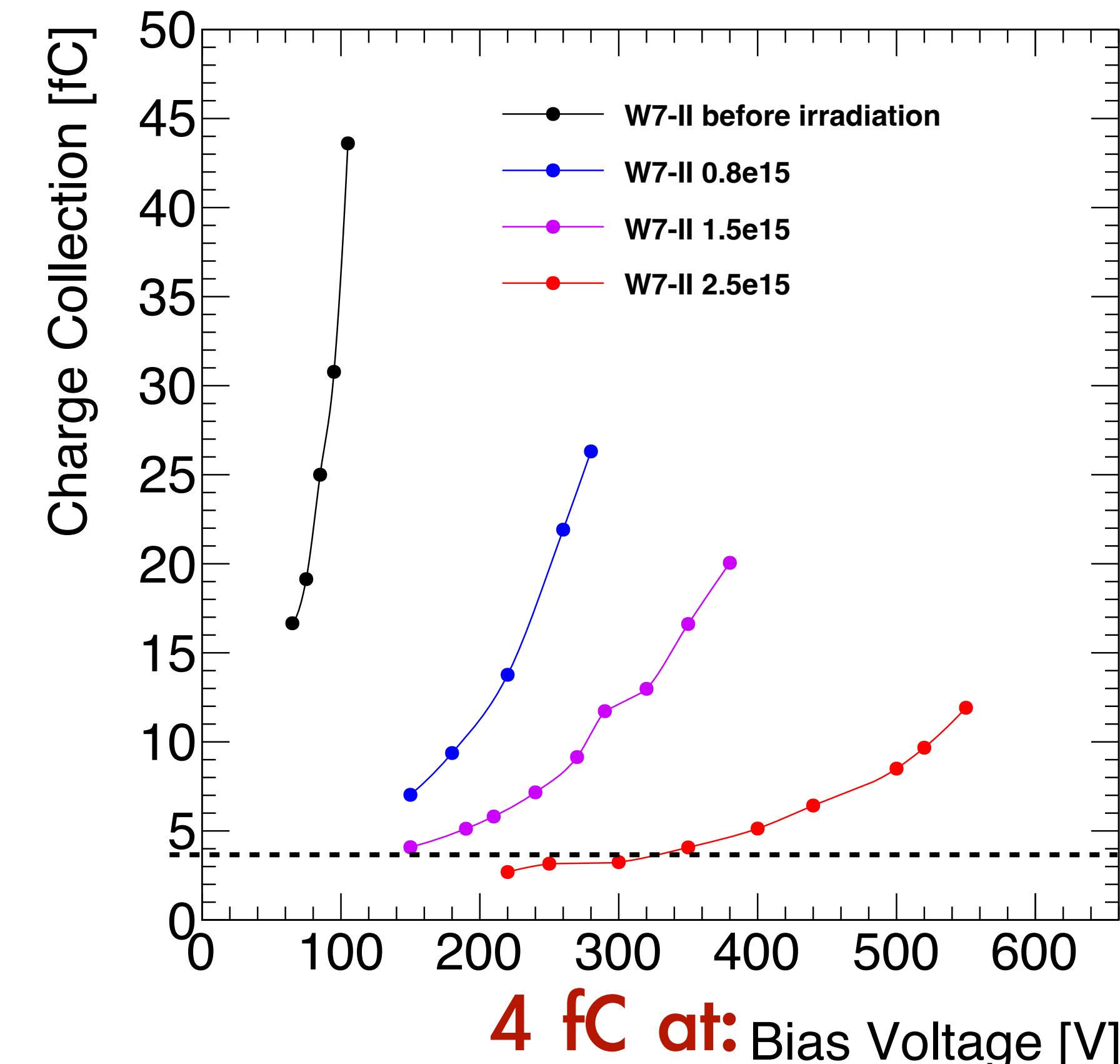
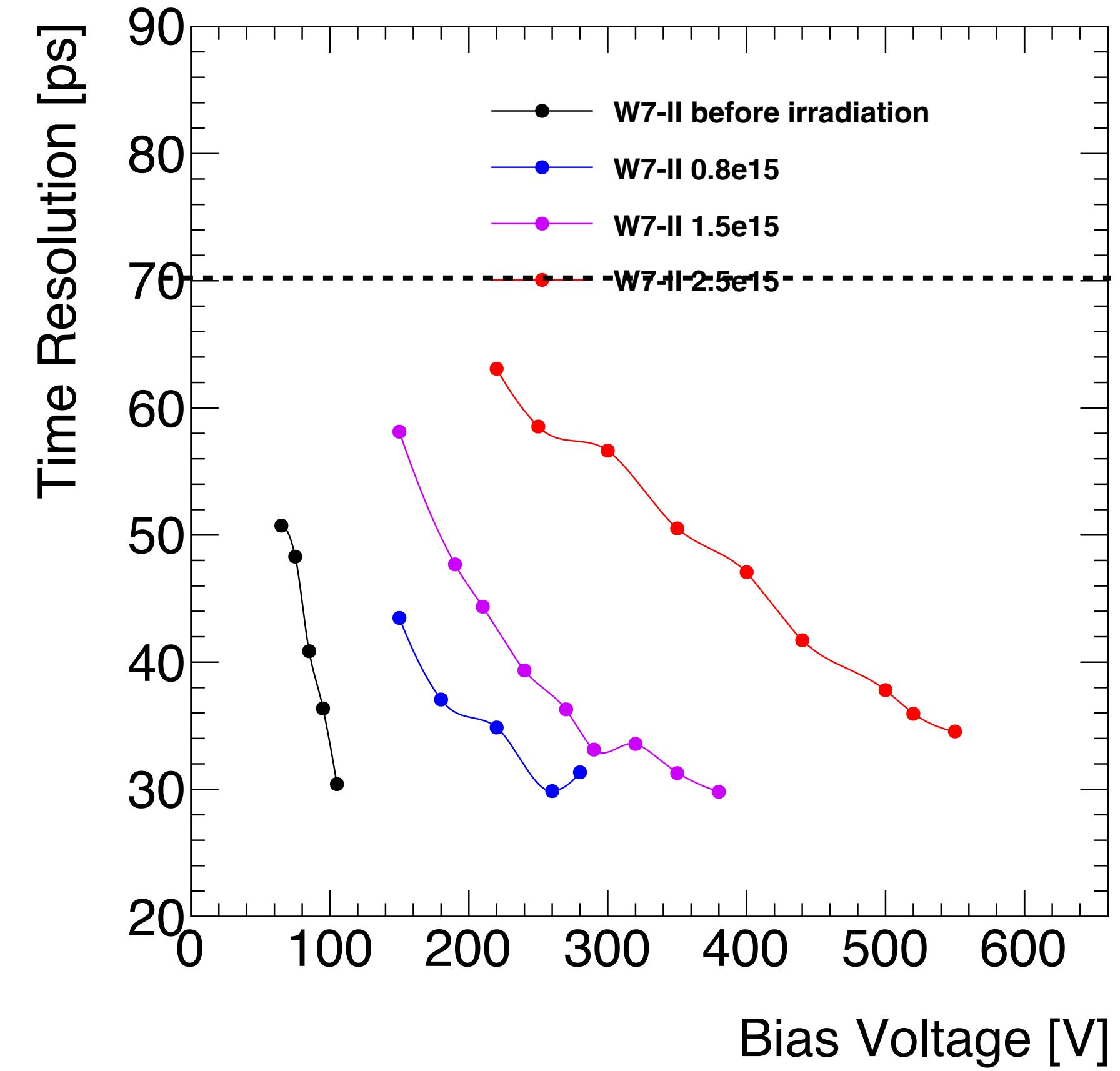
After irradiation:

- The leakage current increase $nA \rightarrow 100nA$
- The acceptor concentration is reduced
 - V_{gl} decrease with the irradiation fluence (Acceptor removal constant)
- The sensor needs to be operated at higher voltage, higher power consumption ($I < 2 \mu A$)





After radiation - Timing and charge



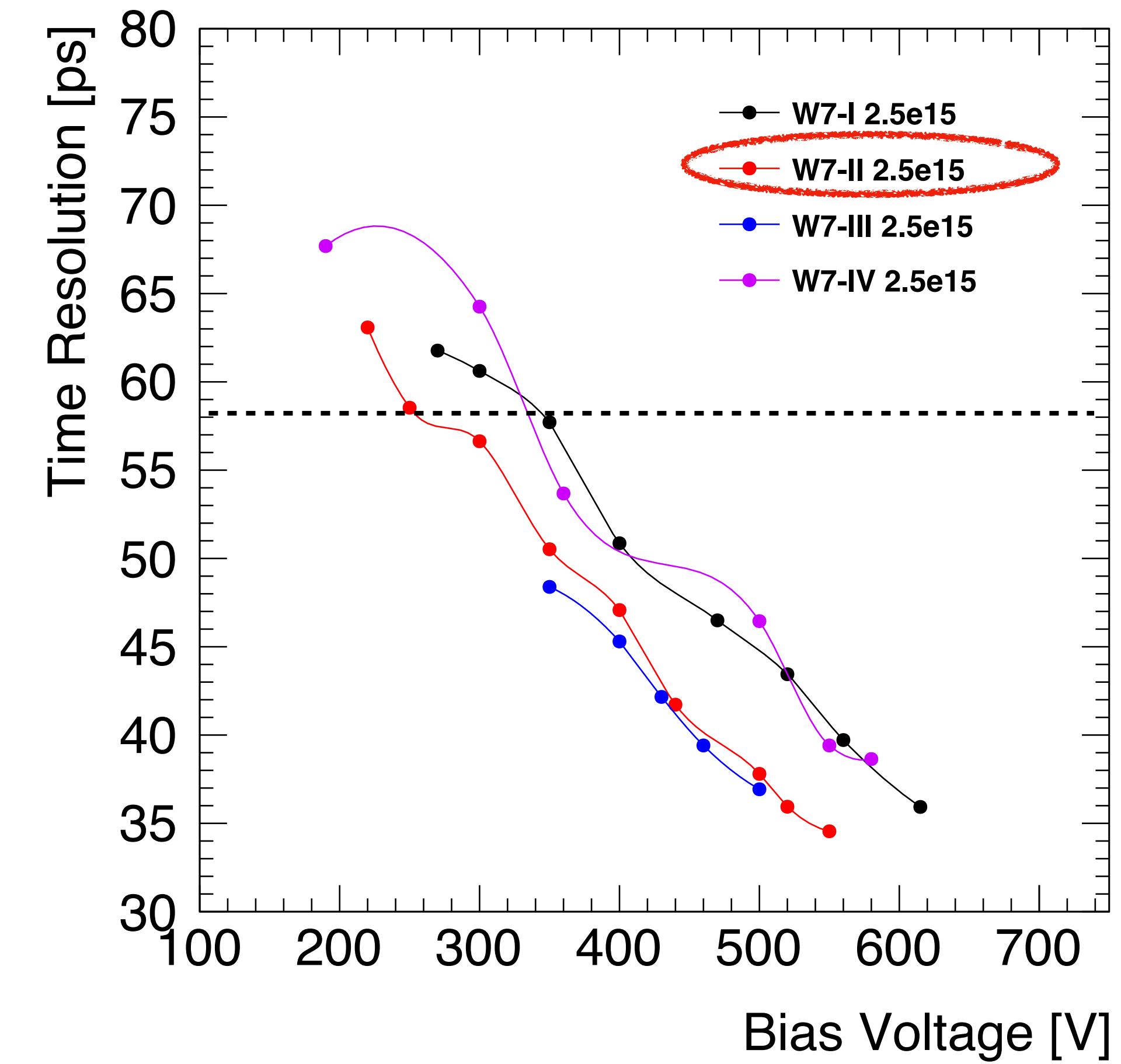
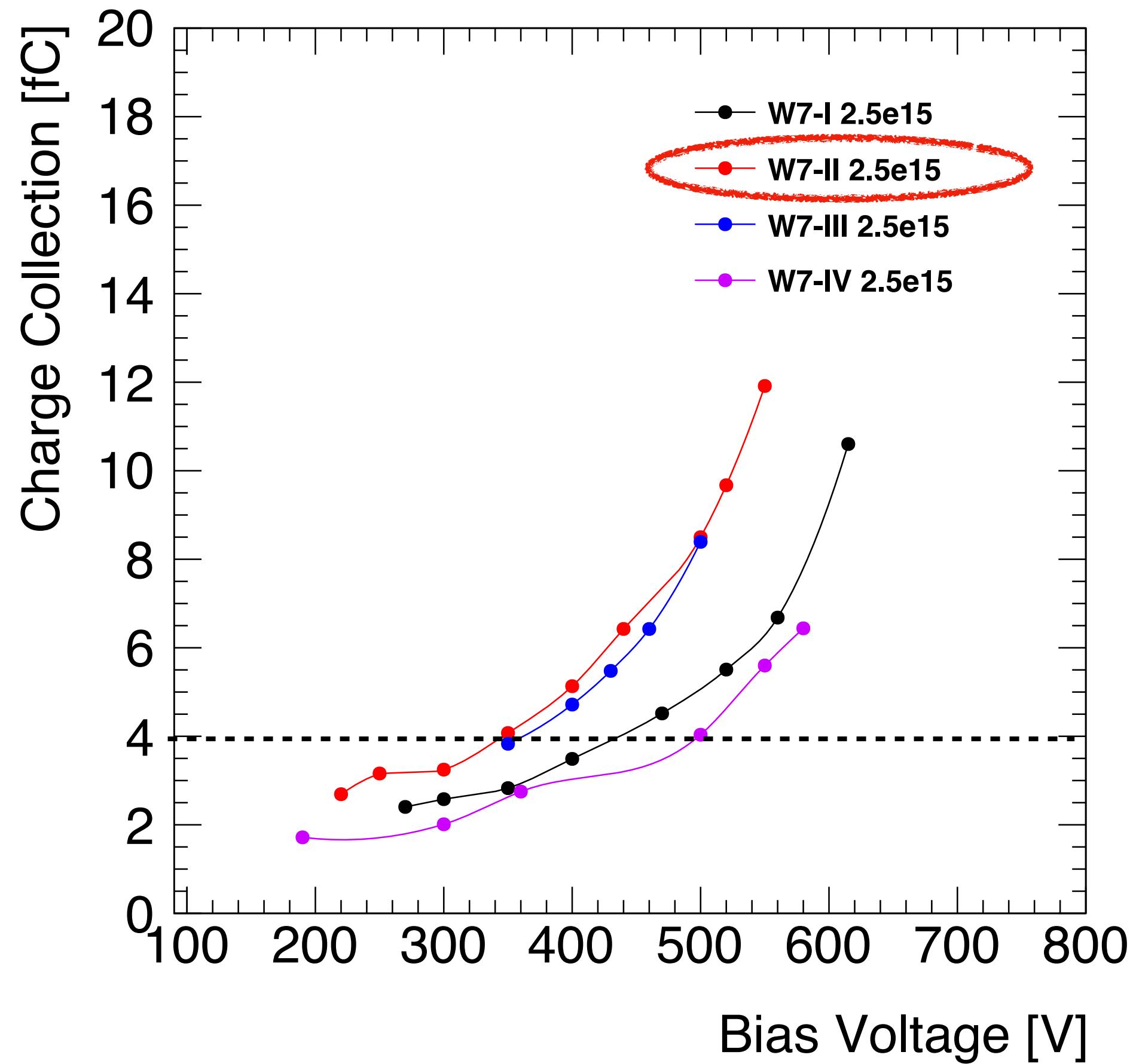
4 fC at: Bias Voltage [V]
W7-II(0.5C): 350 V 50.5 ps

- Time resolution and charge collection after radiation



After radiation - Carbon dose

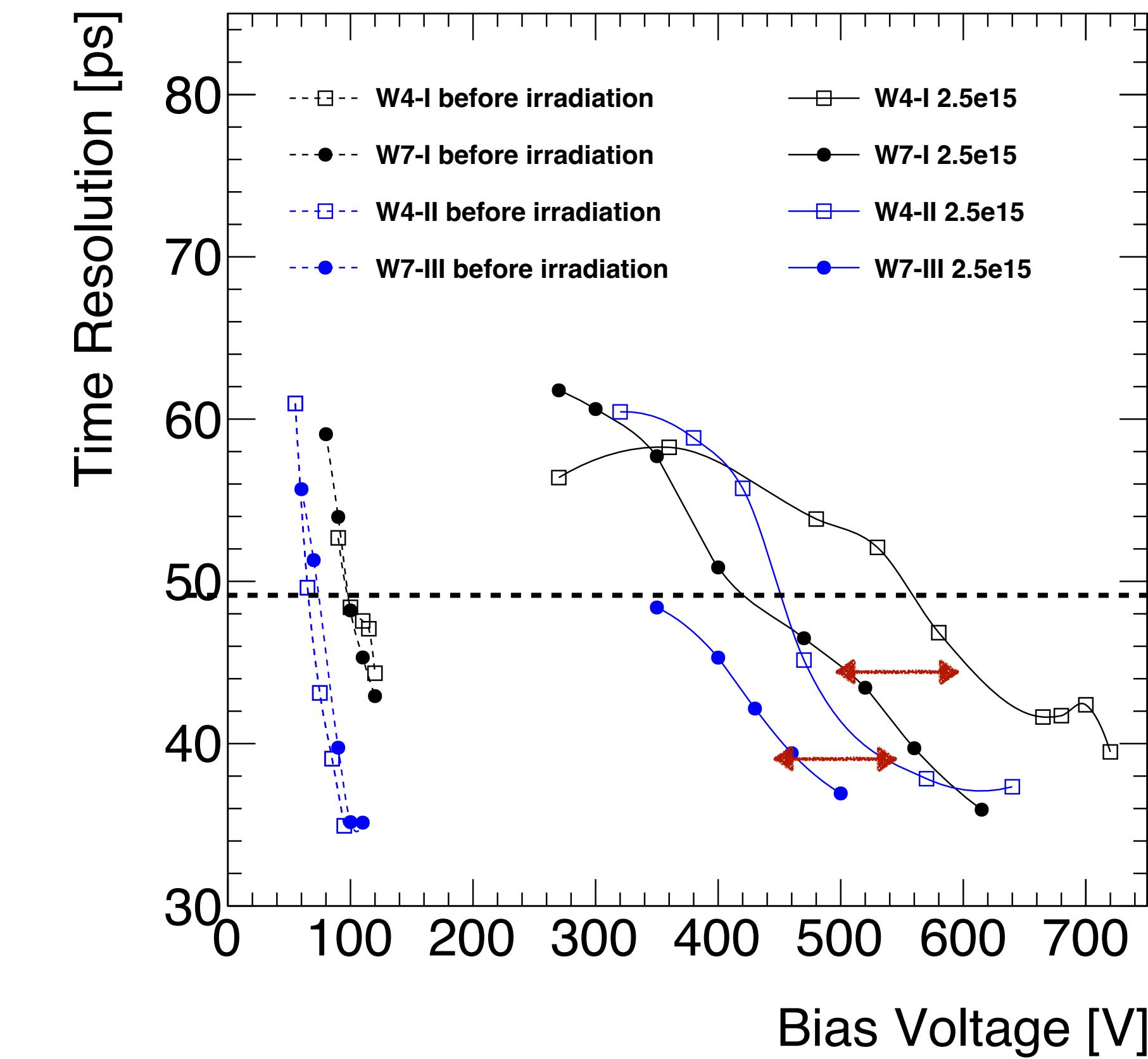
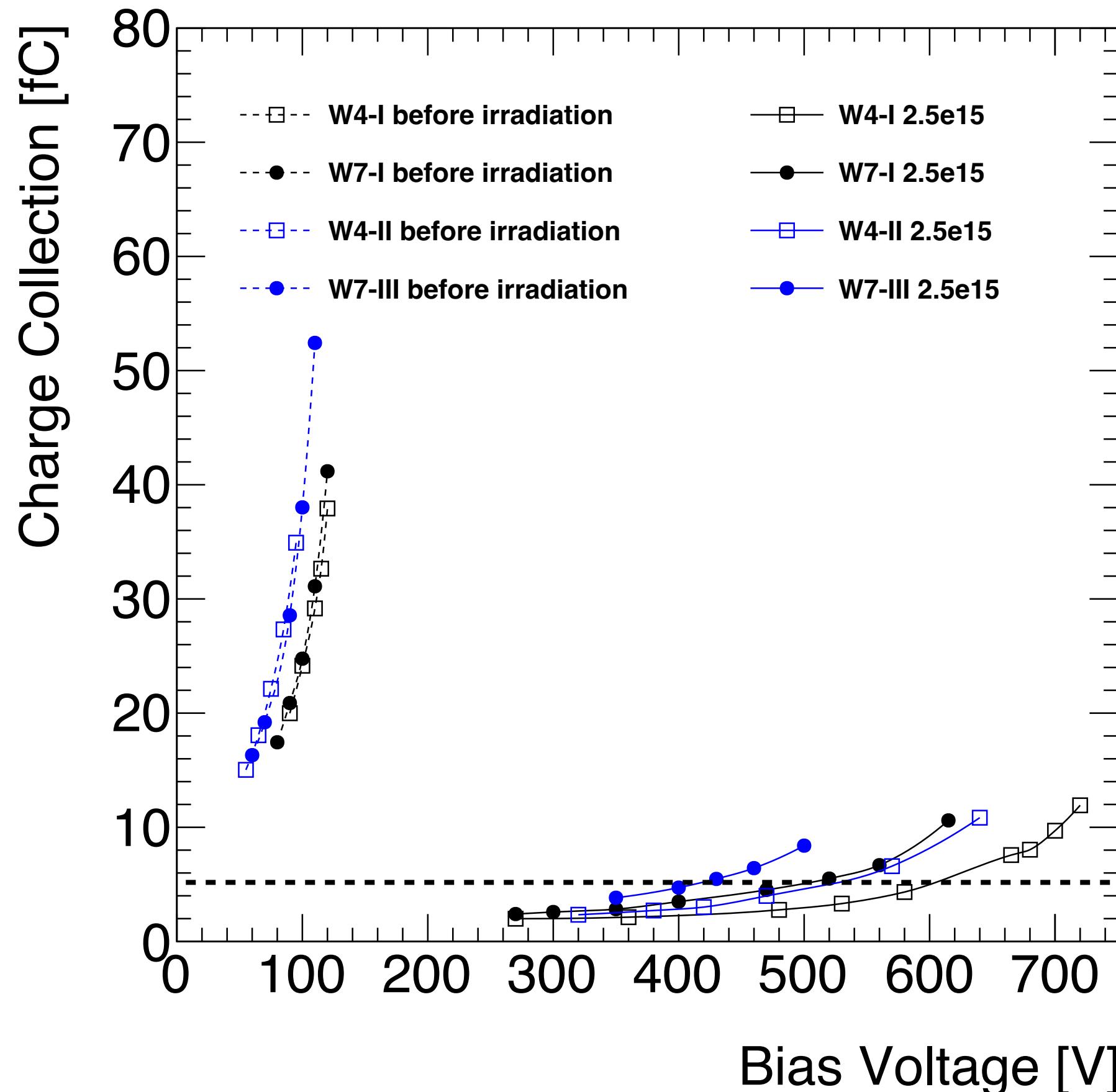
- Time resolution and charge collection of sensors with different carbon dose





After radiation - Thermal load

Time resolution and charge collection of sensors with same carbon dose but different thermal load



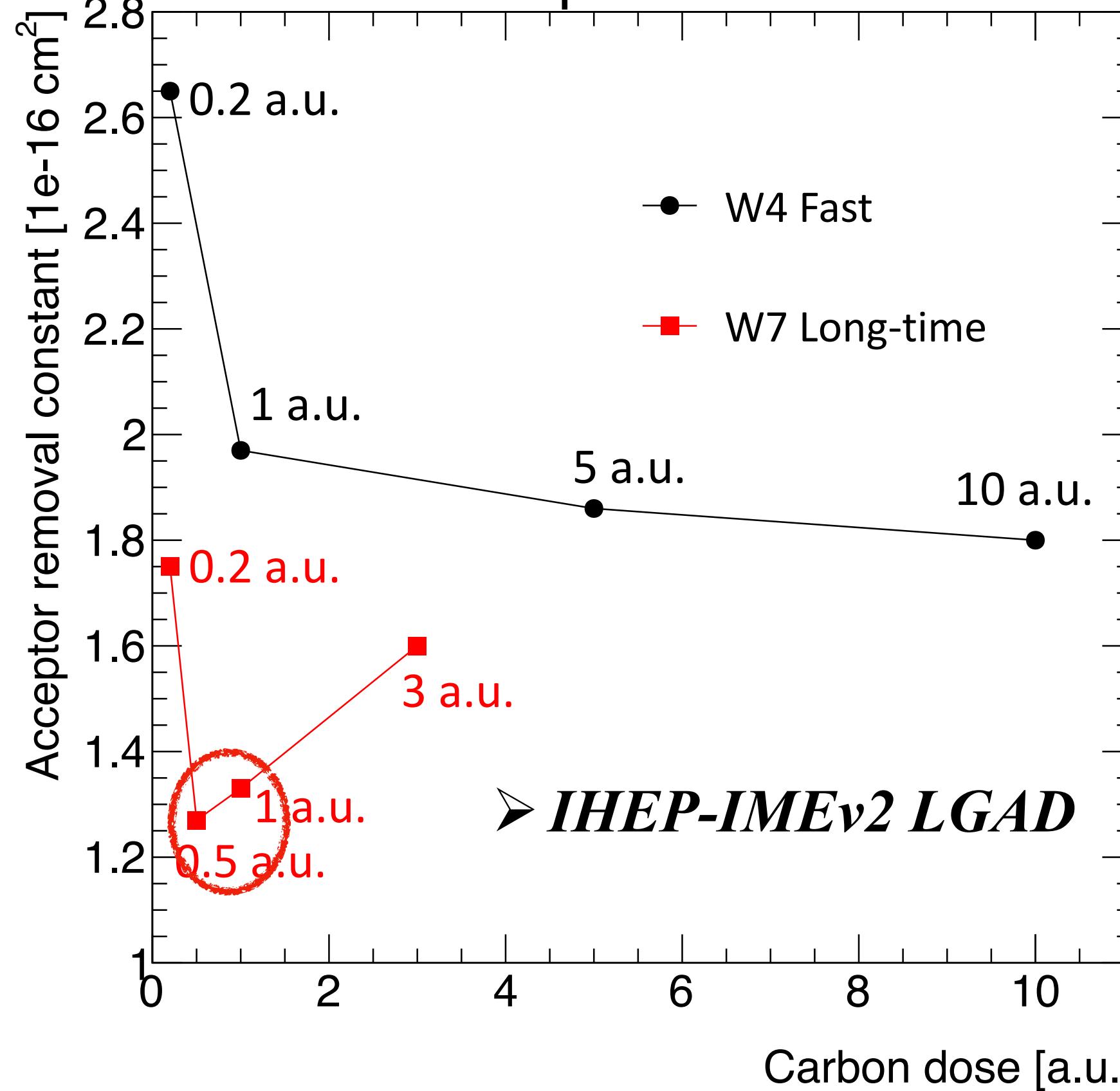
Long annealing sensors have better performance



After radiation

IHEP-IMEv2

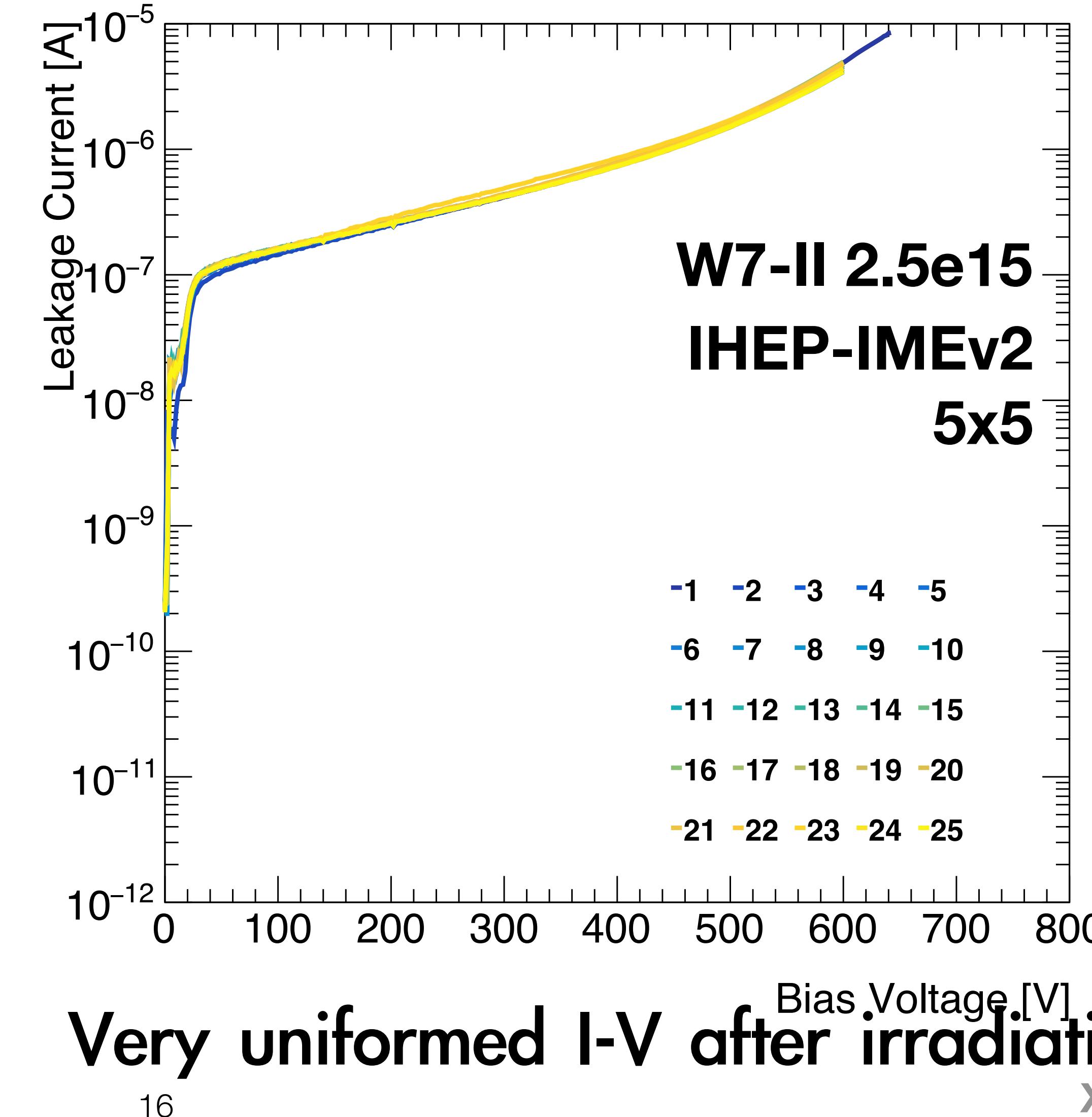
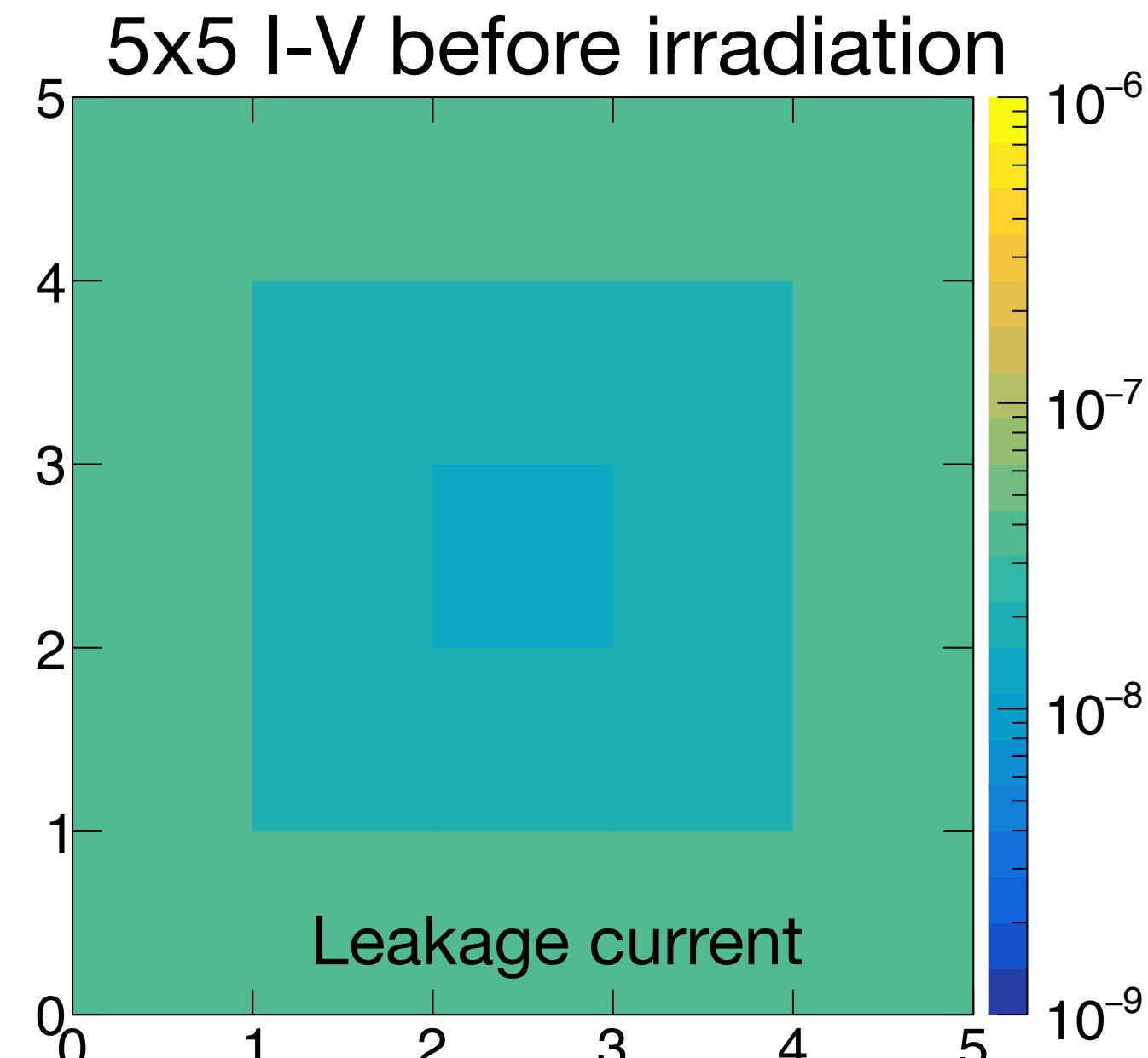
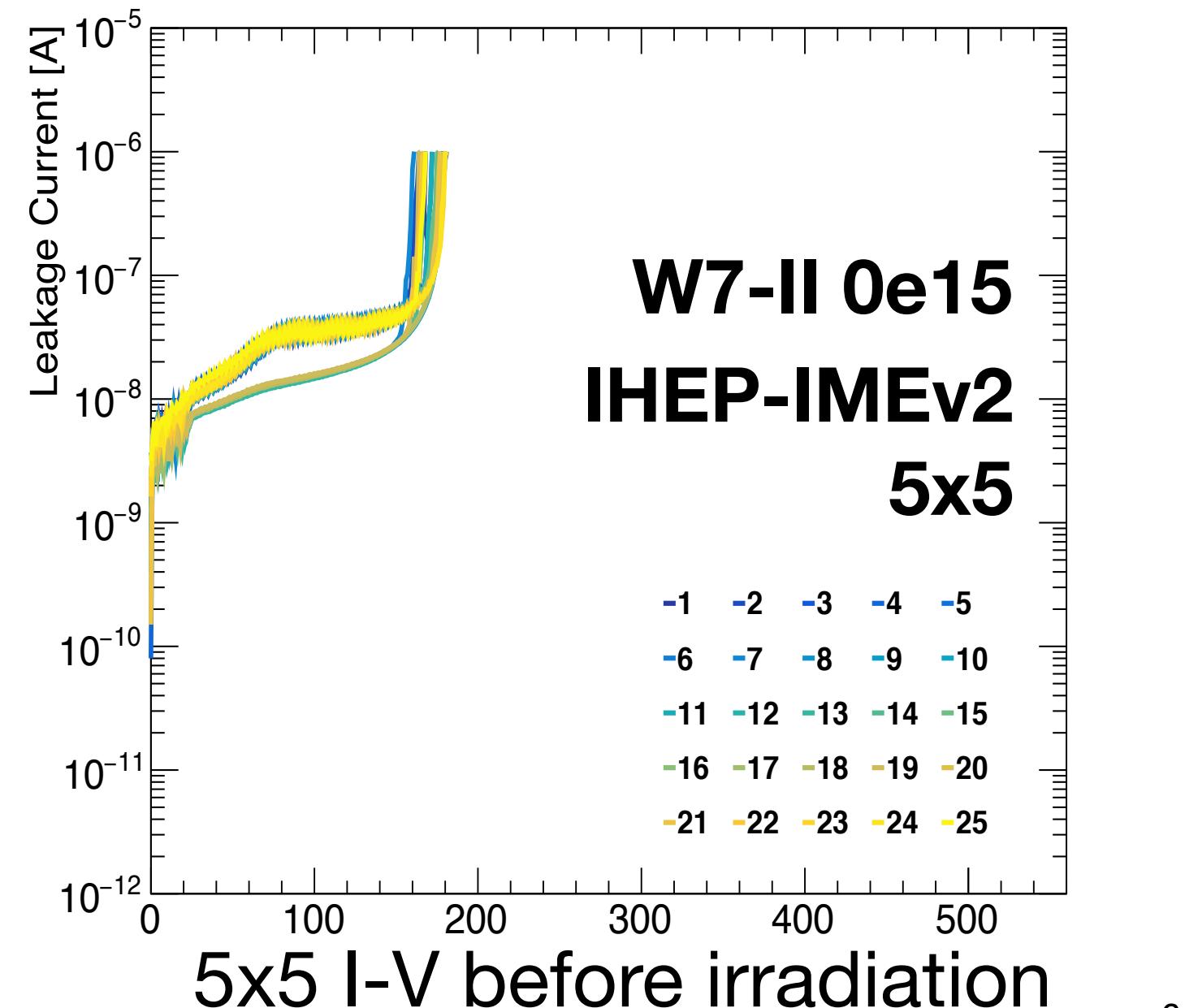
- Most acceptor removal constant below 2, the best (W7-II) is about 1.27.



Between 0.2C and 1C, long time annealing
the best recipe for irradiation hardness.



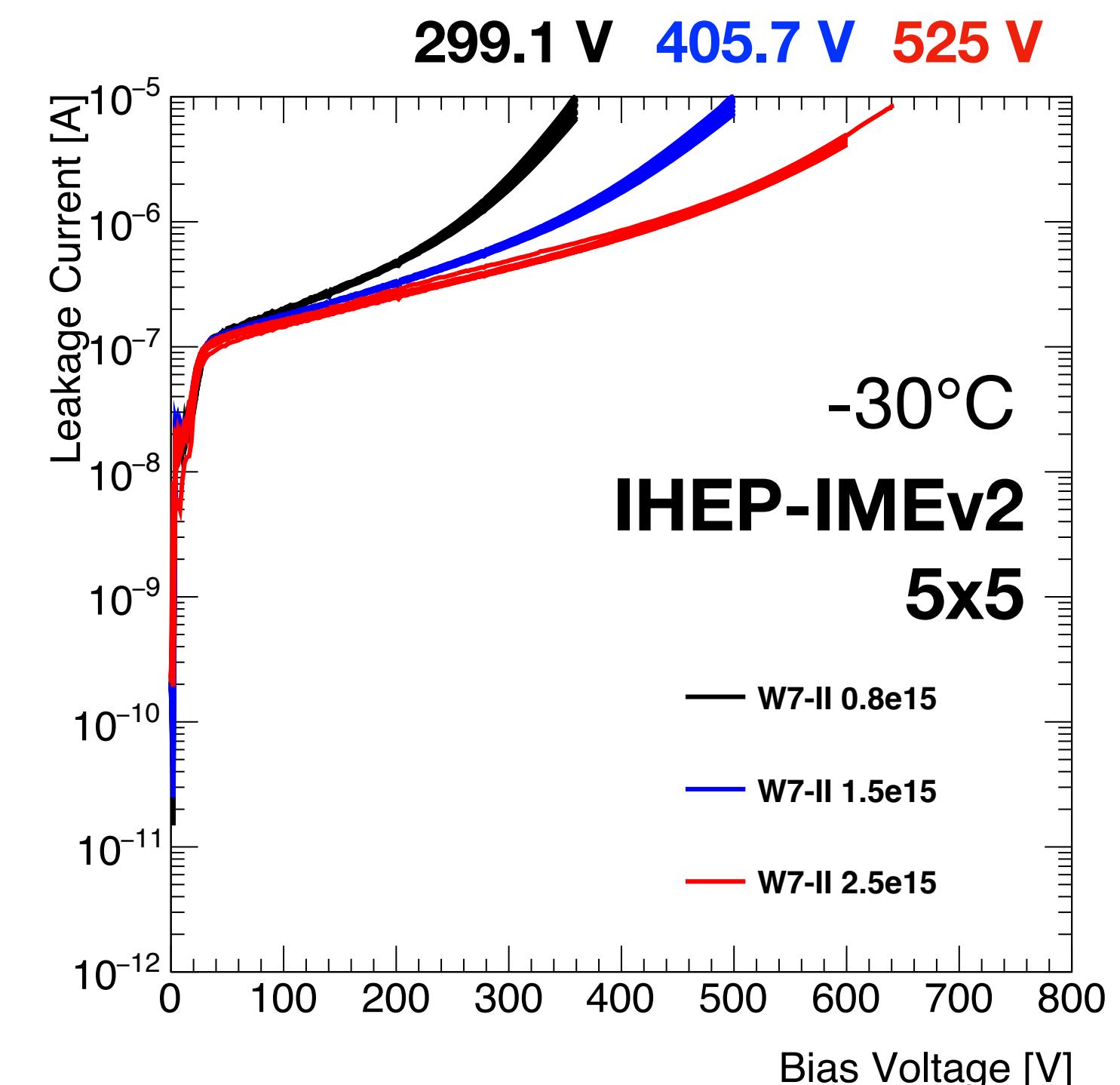
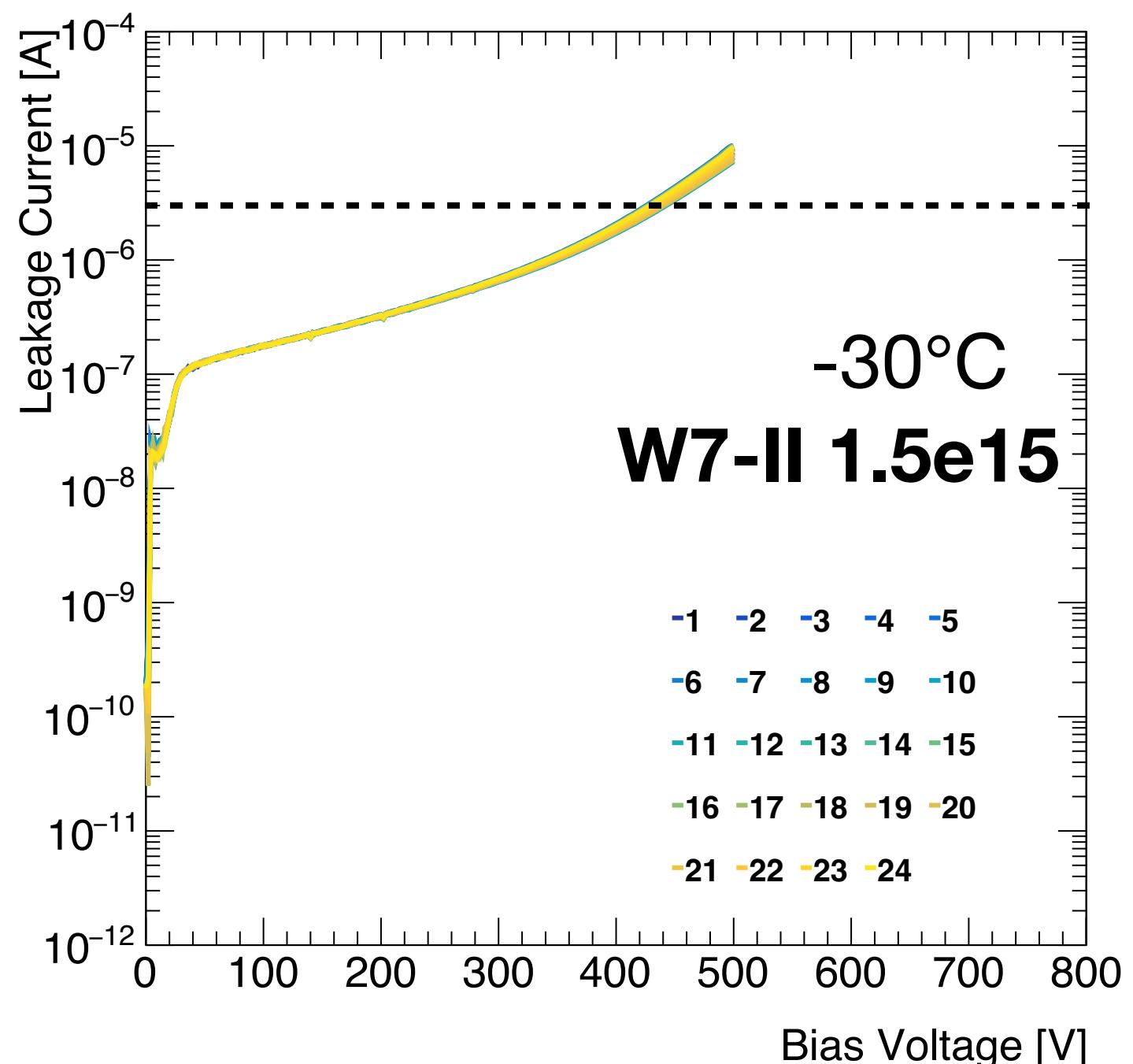
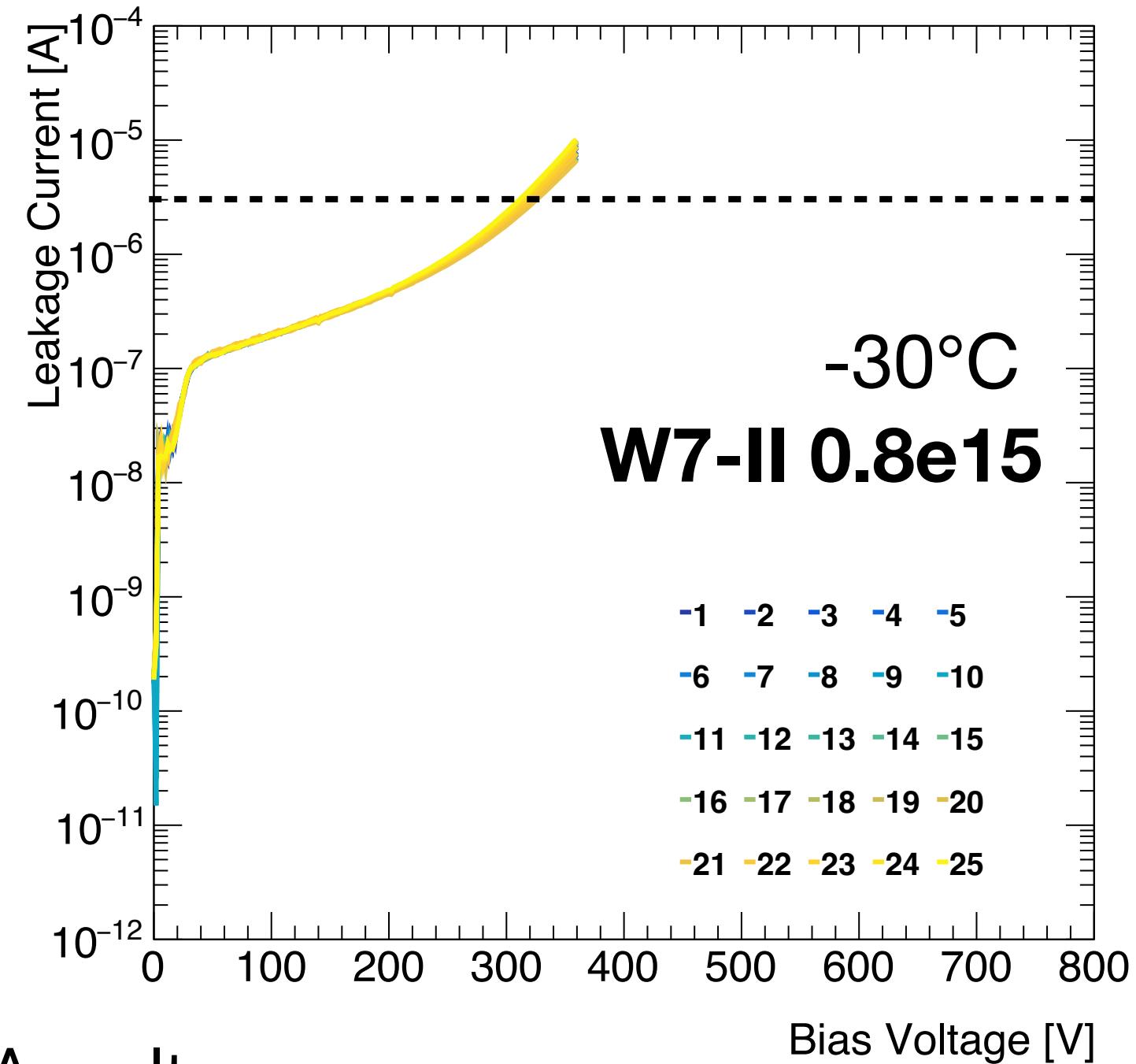
Large array sensor after irradiation





Large array sensor after radiation

Uniformed I-V after irradiation



2 uA voltage:

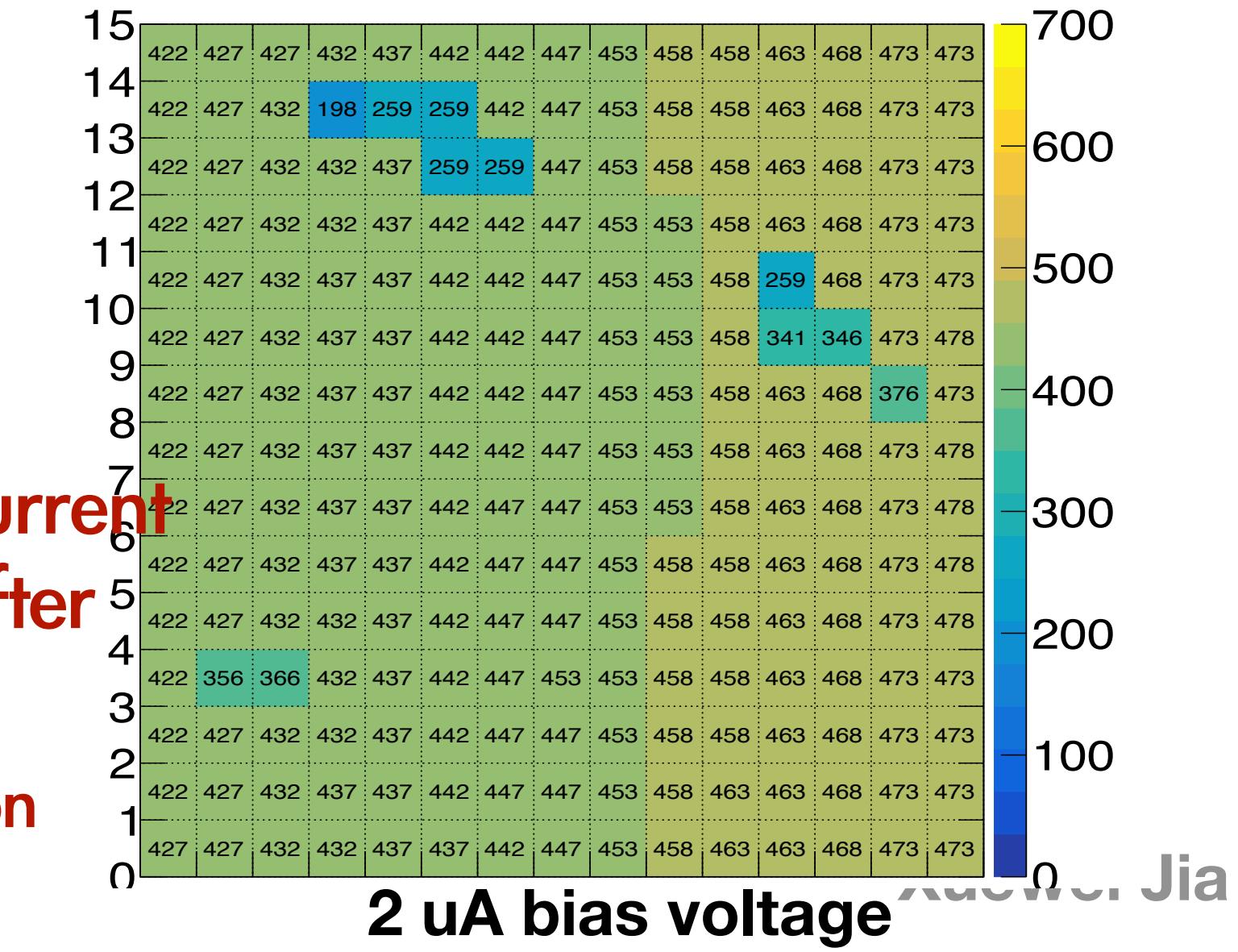
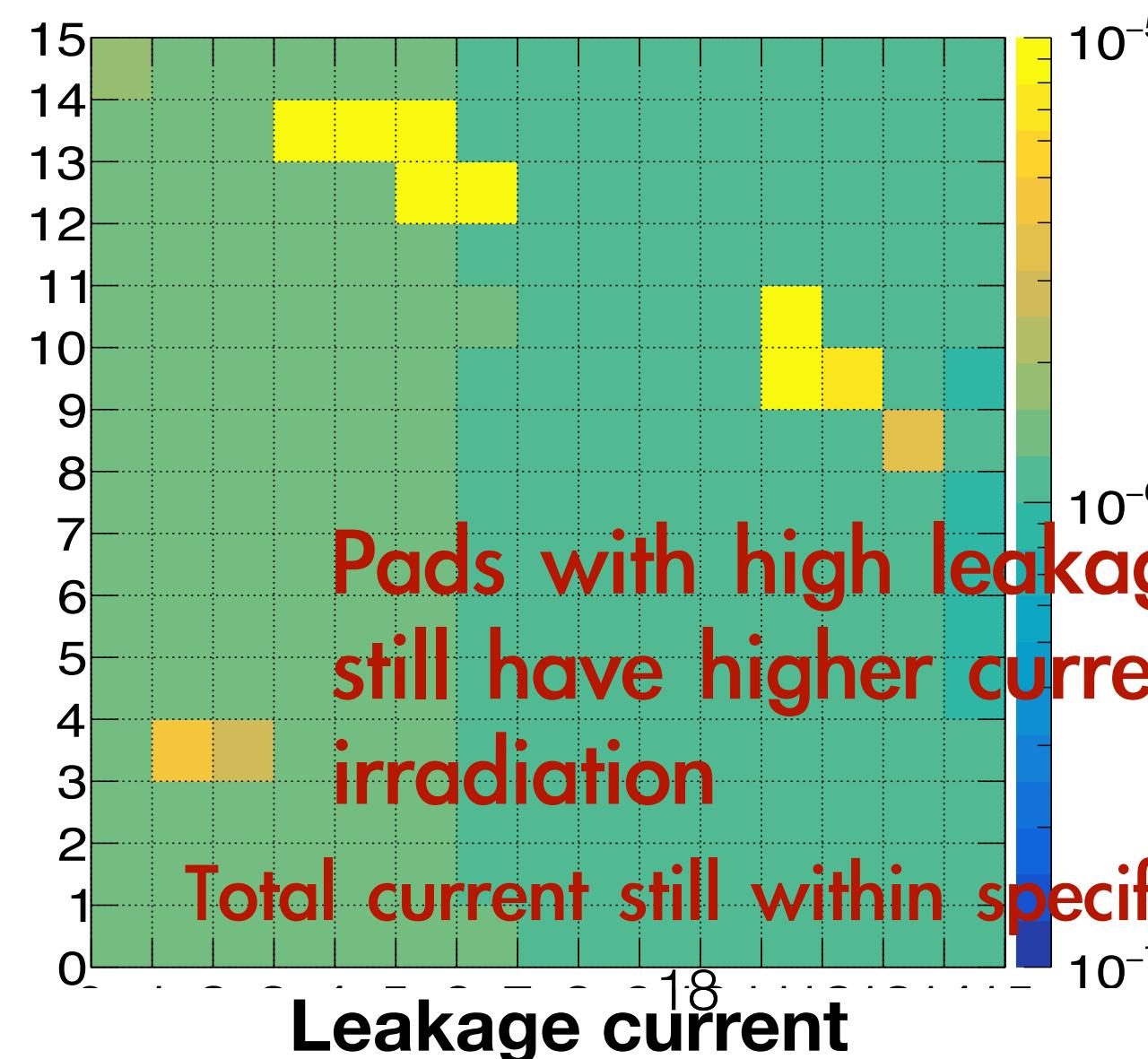
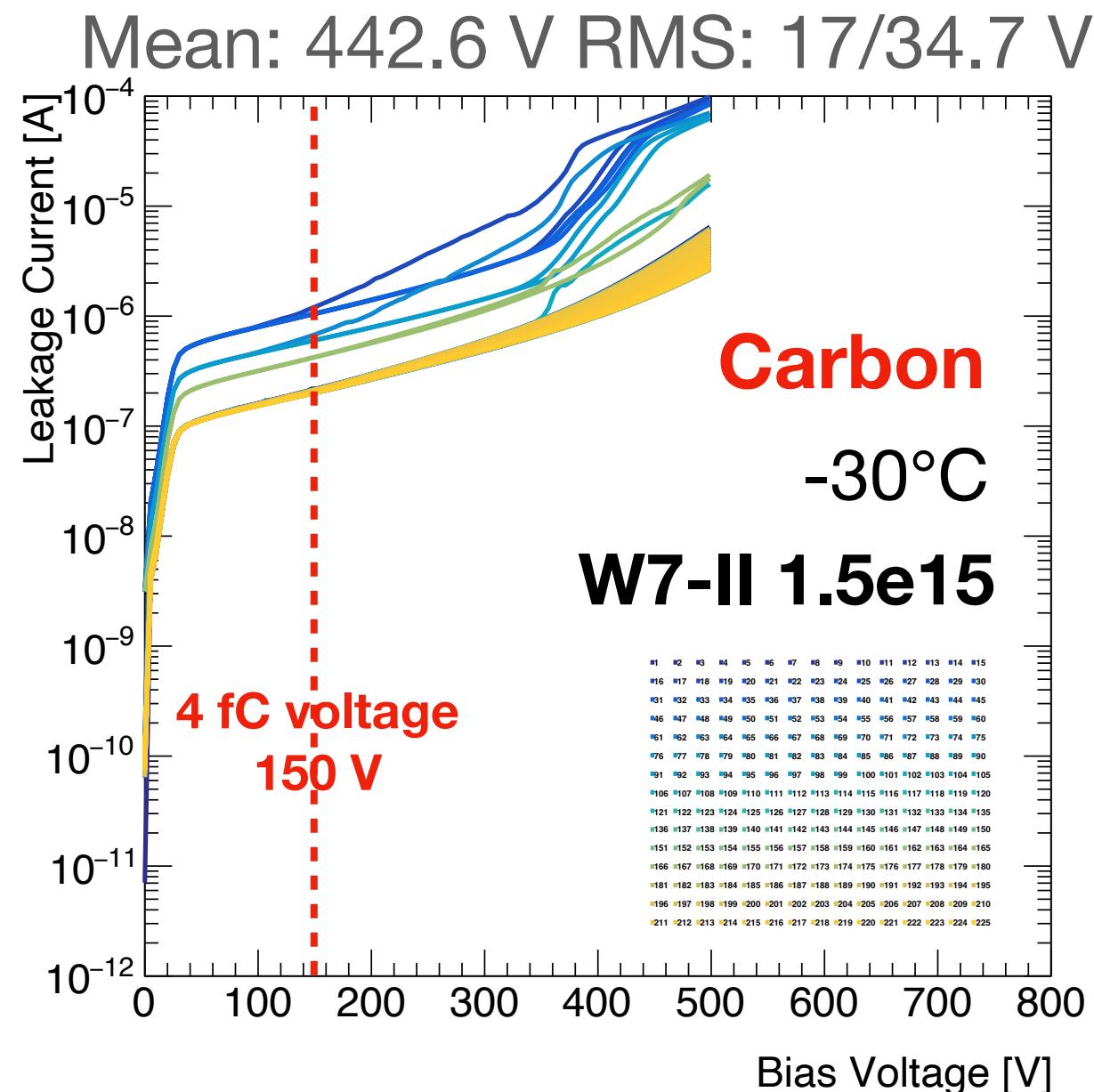
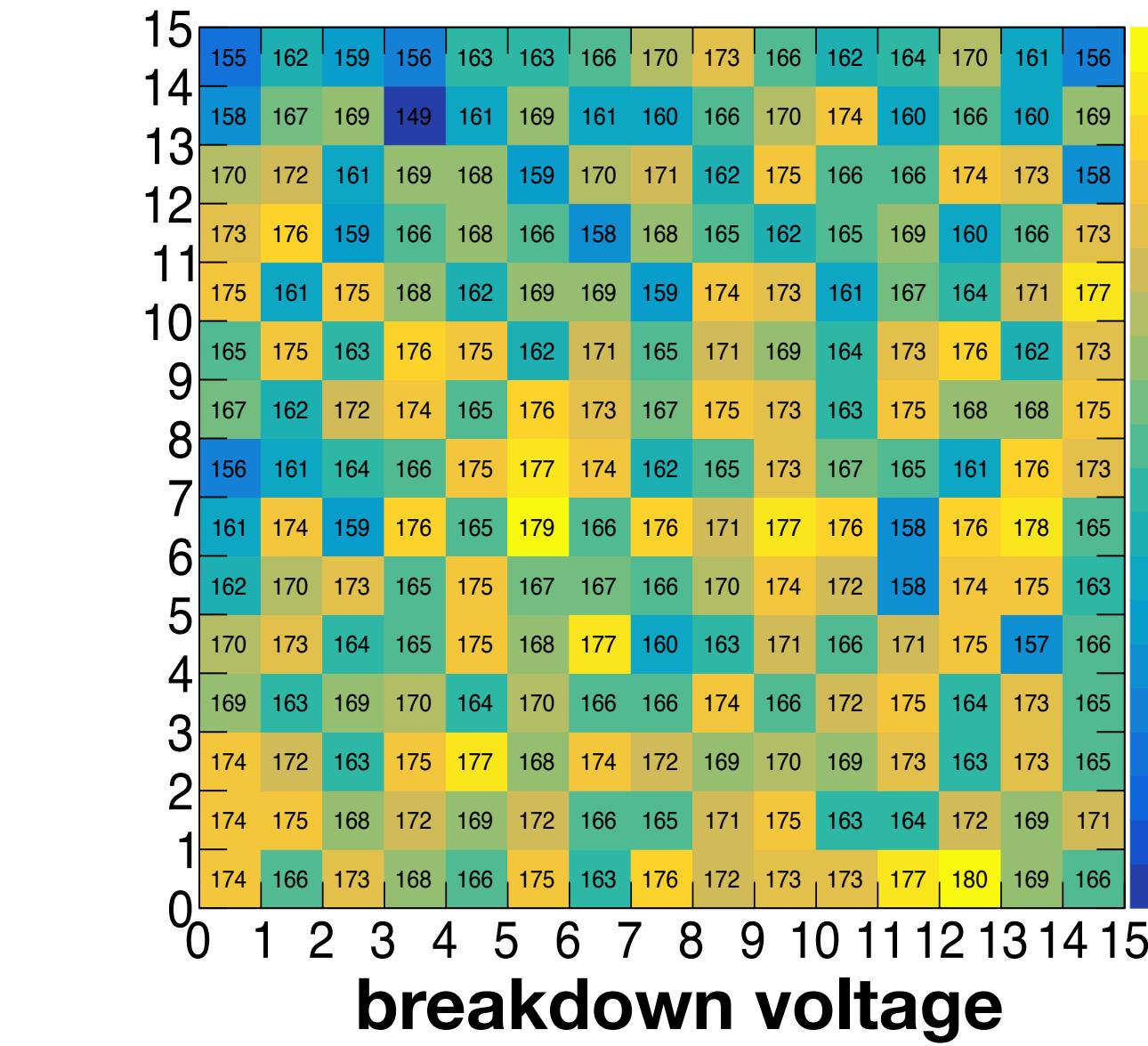
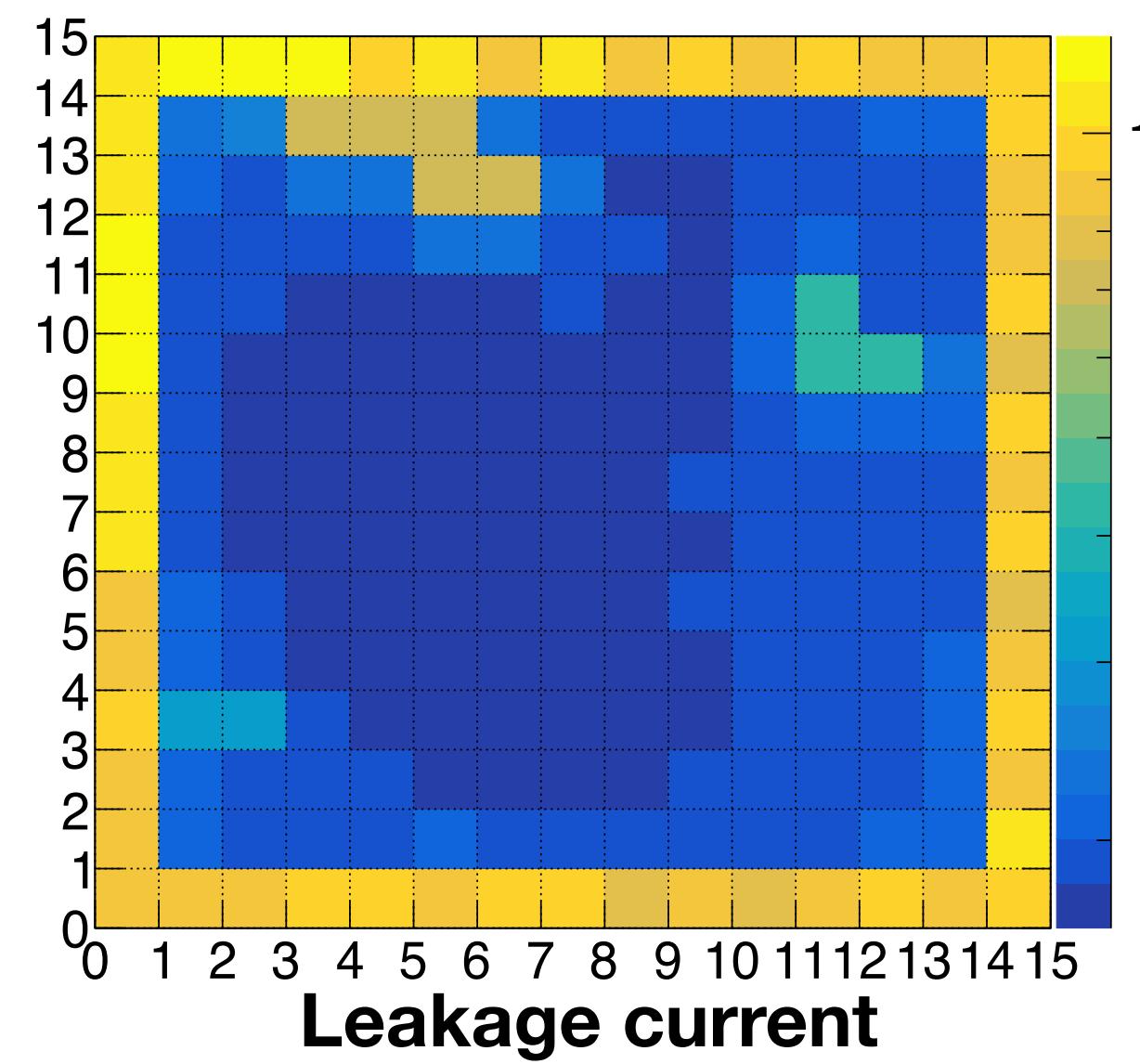
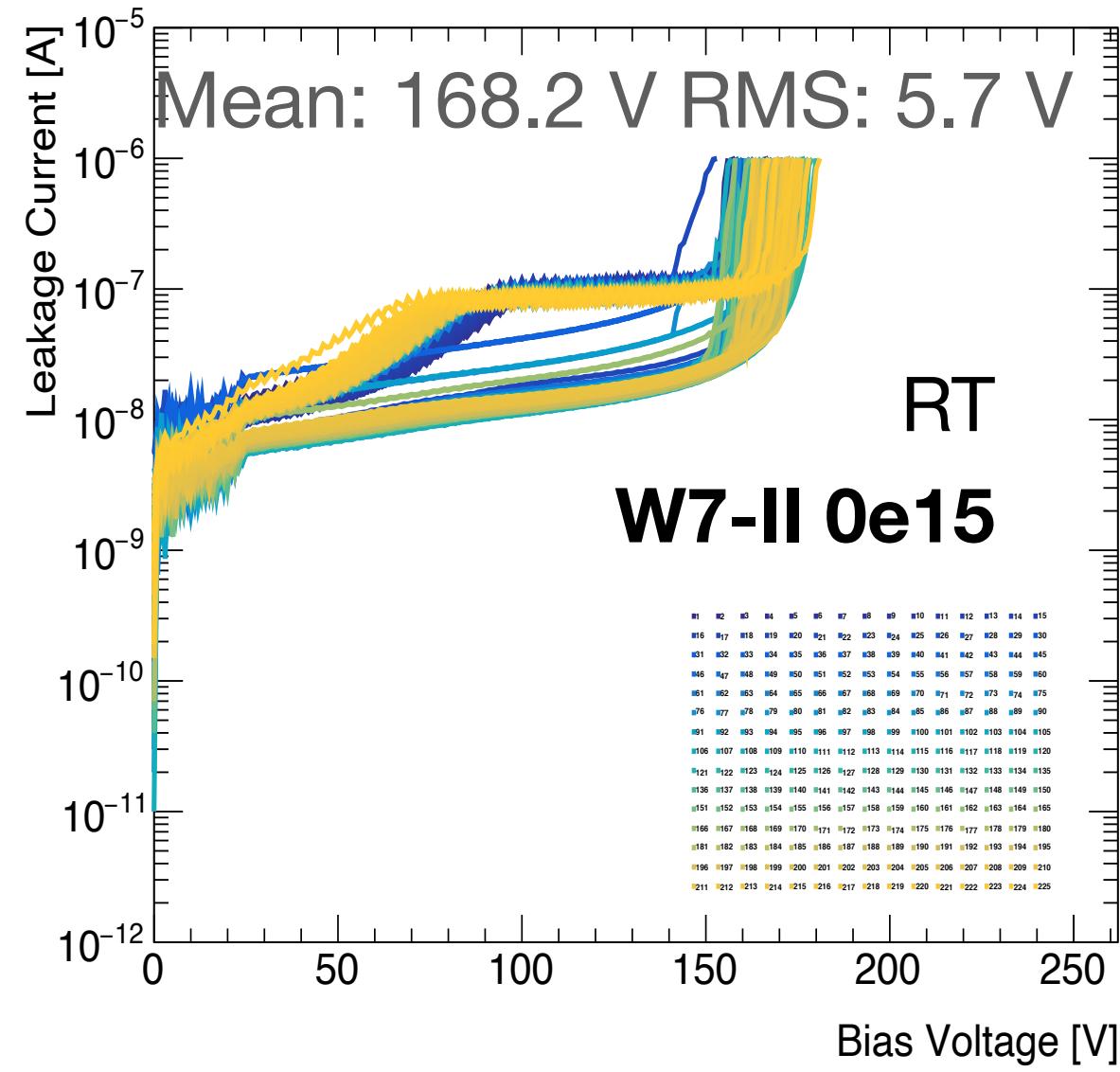
Mean: 299.1 V
RMS: 3.5 V

Mean: 405.7 V
RMS: 4.8 V

5x5 I-V after
different irradiation fluence

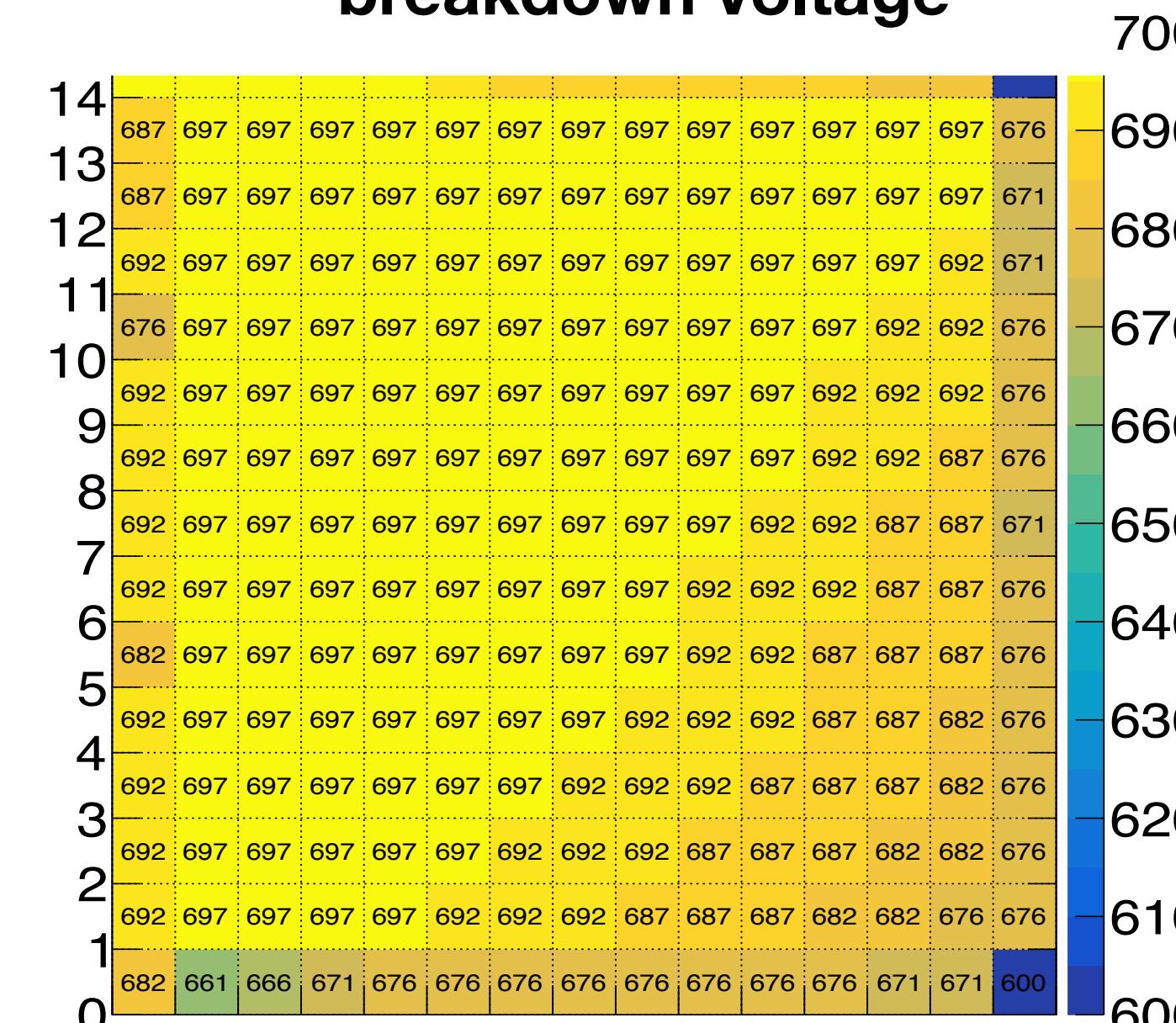
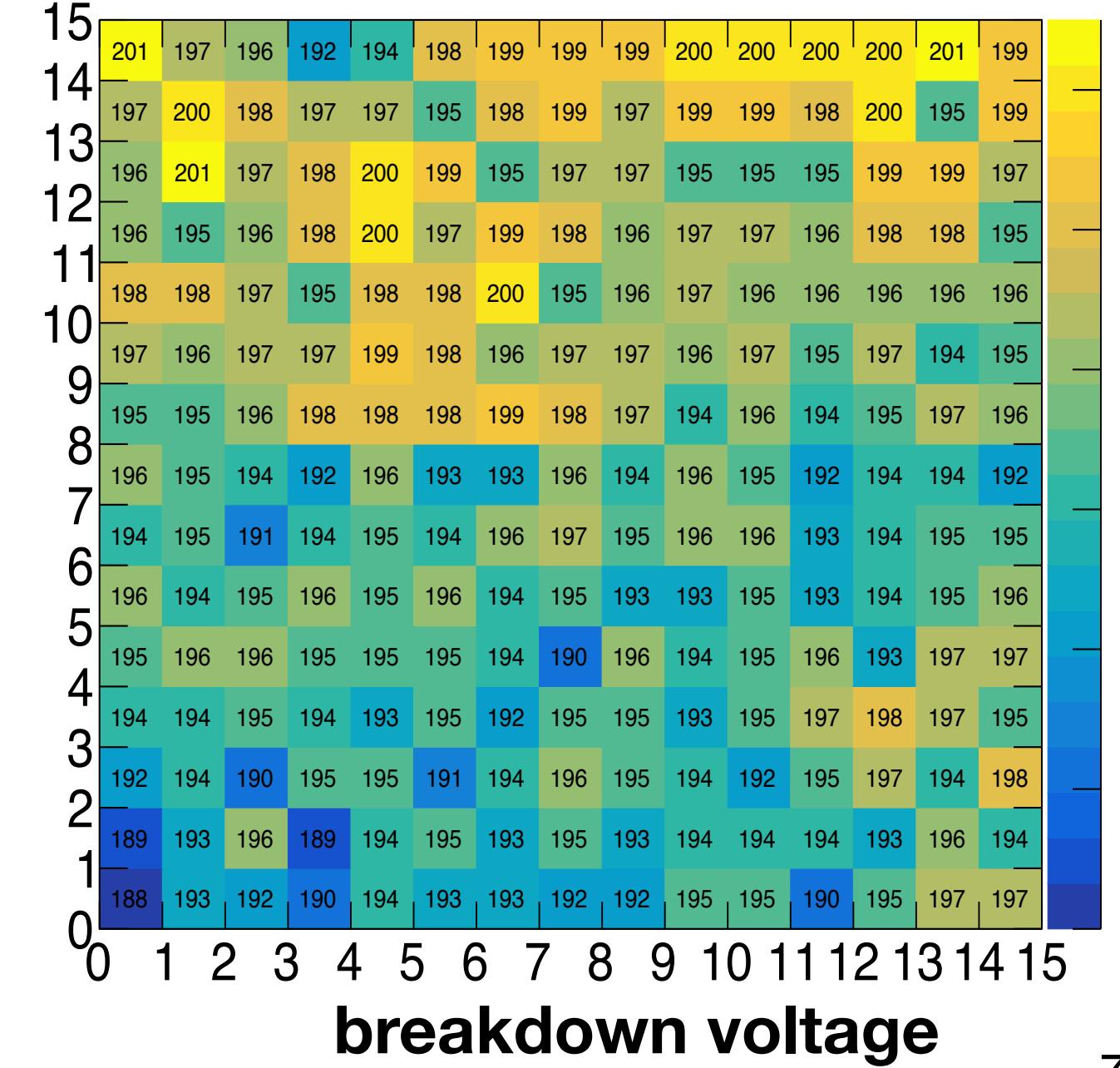
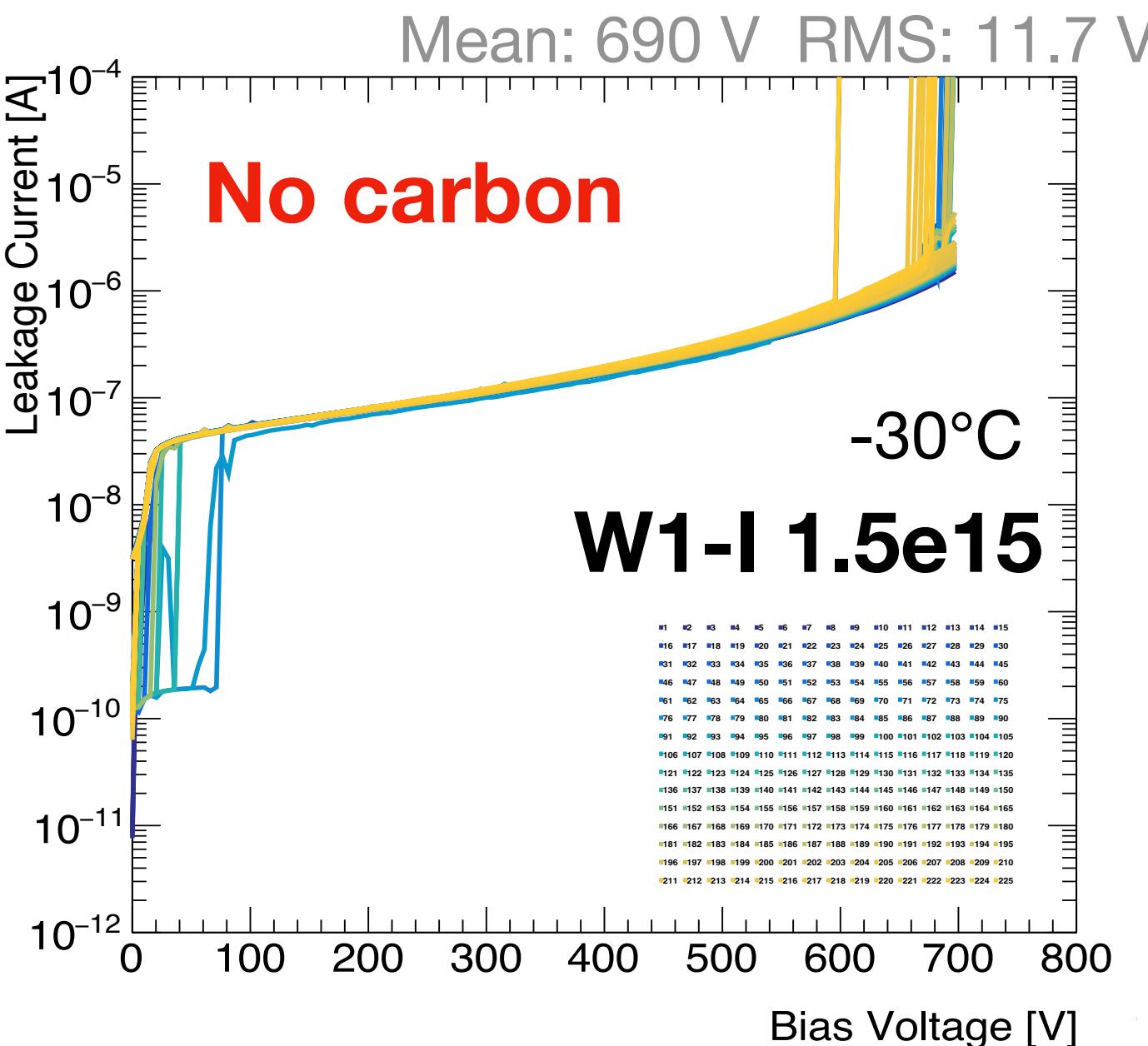
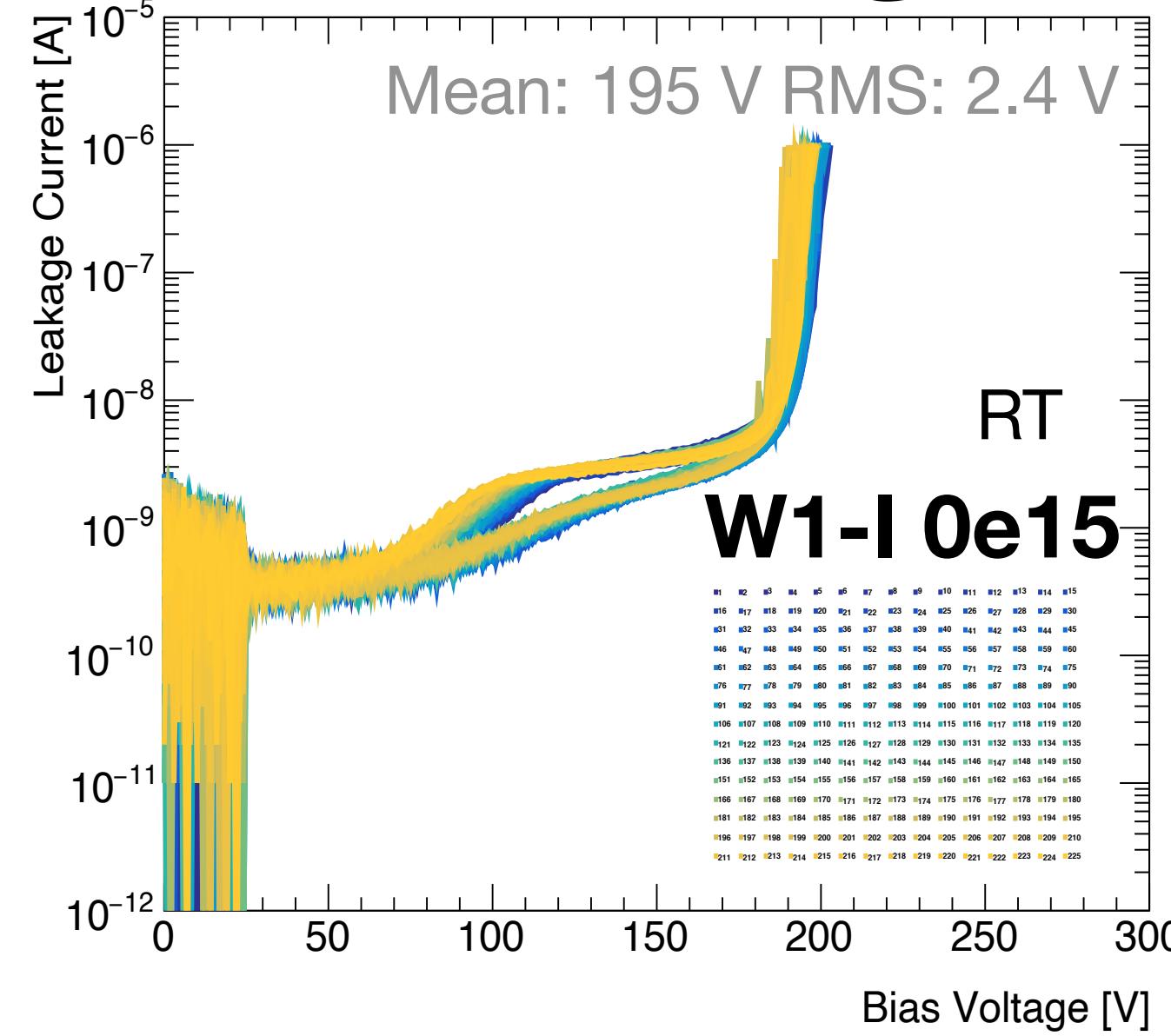


Large array sensor after radiation





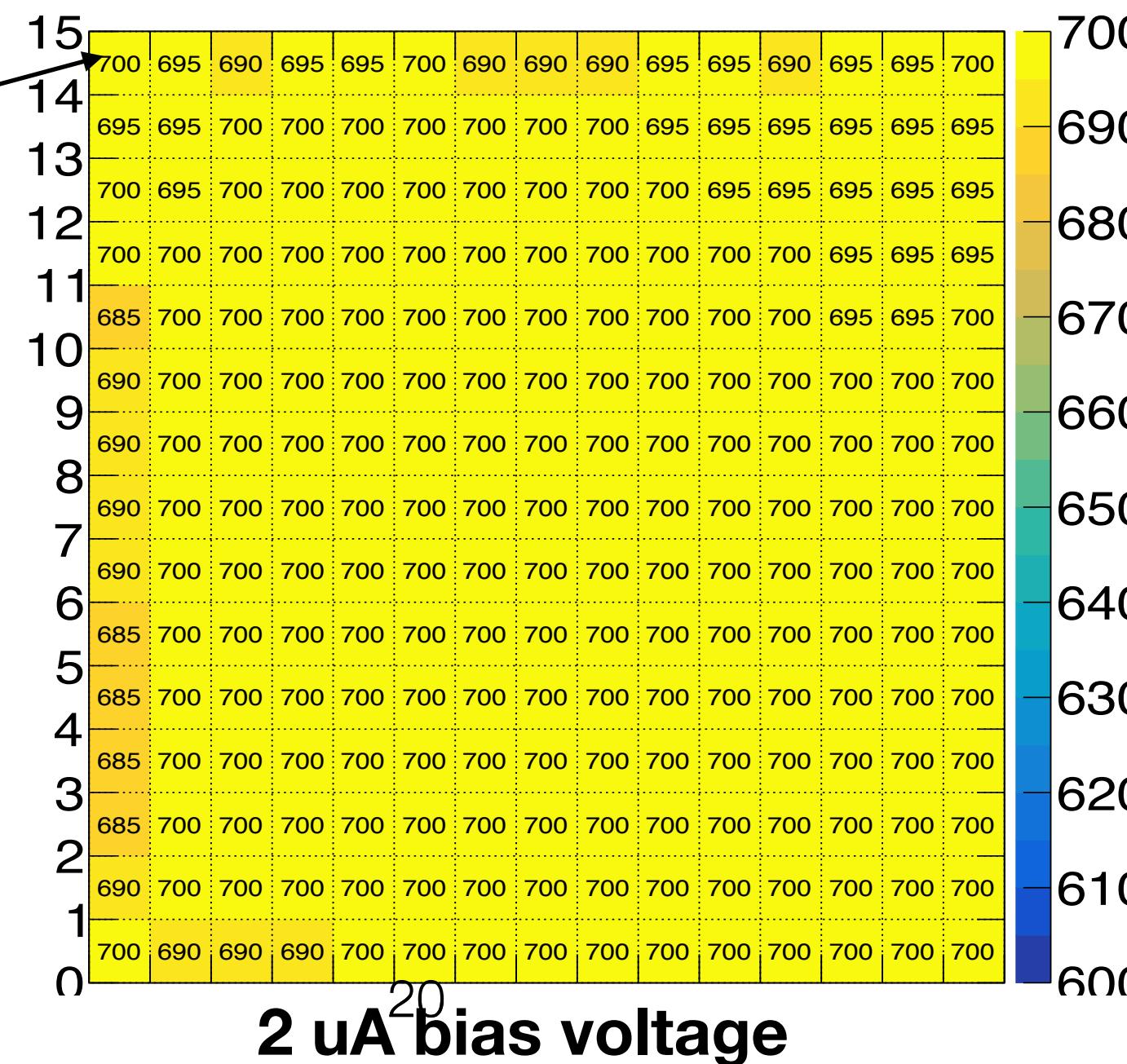
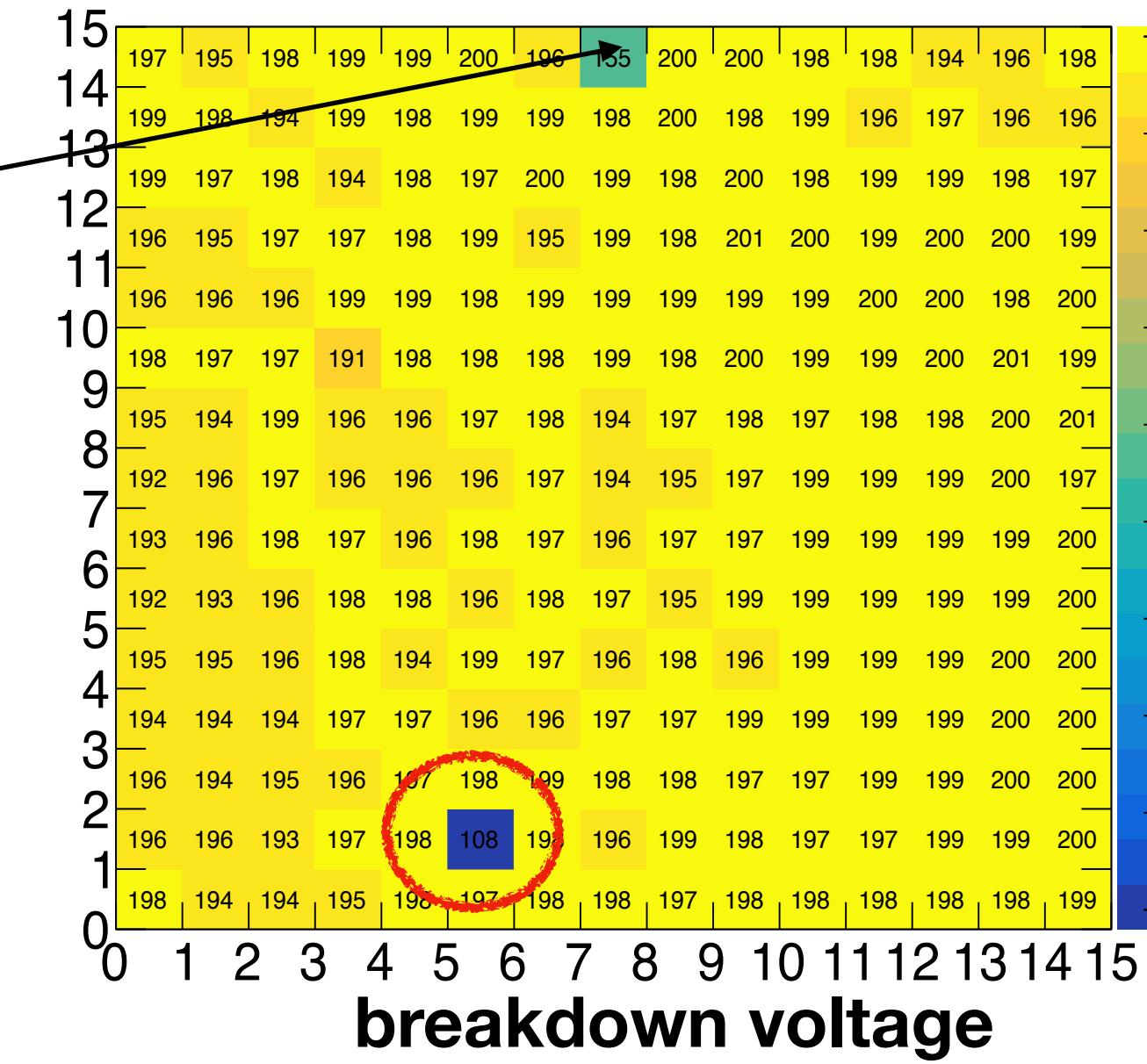
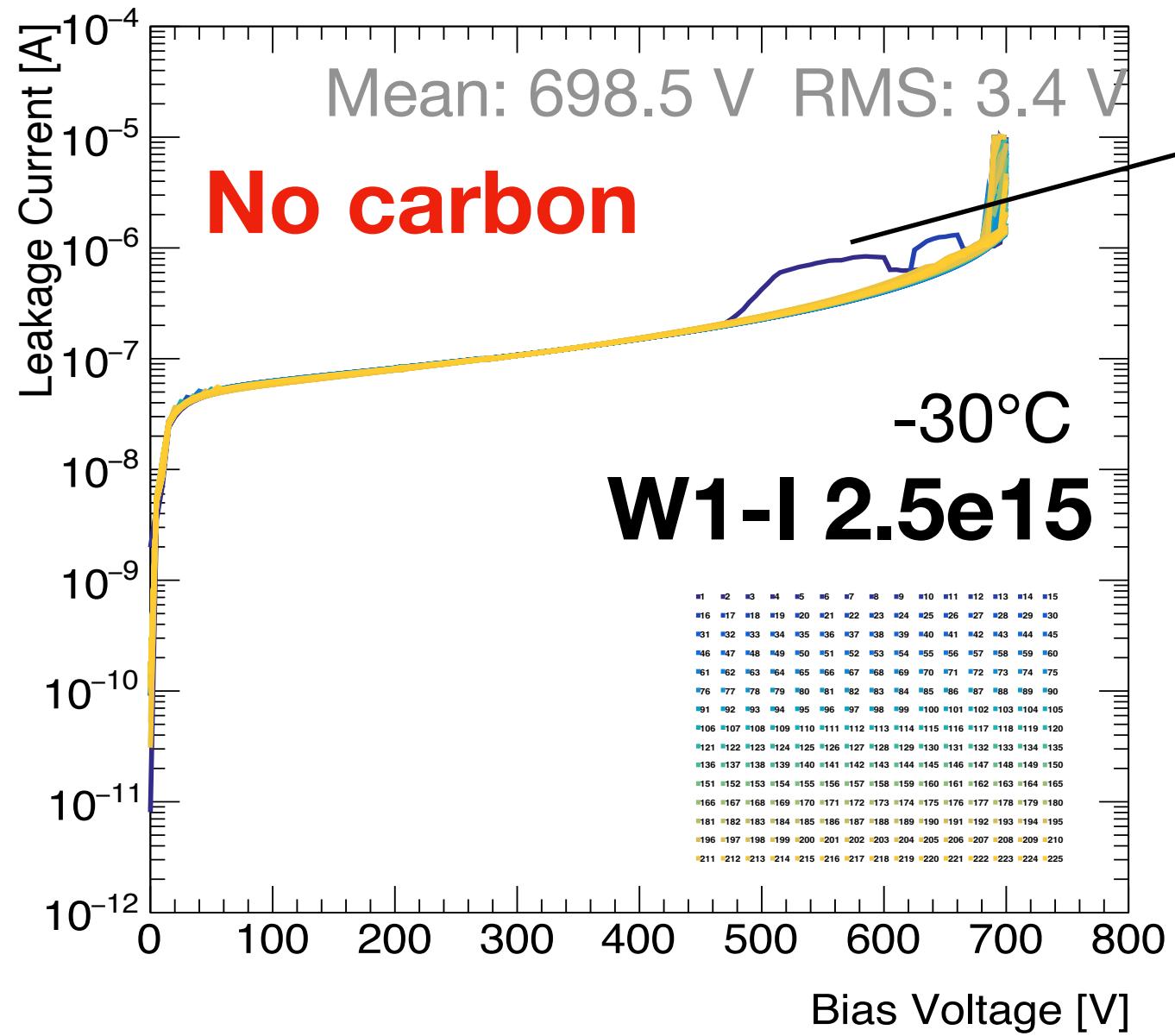
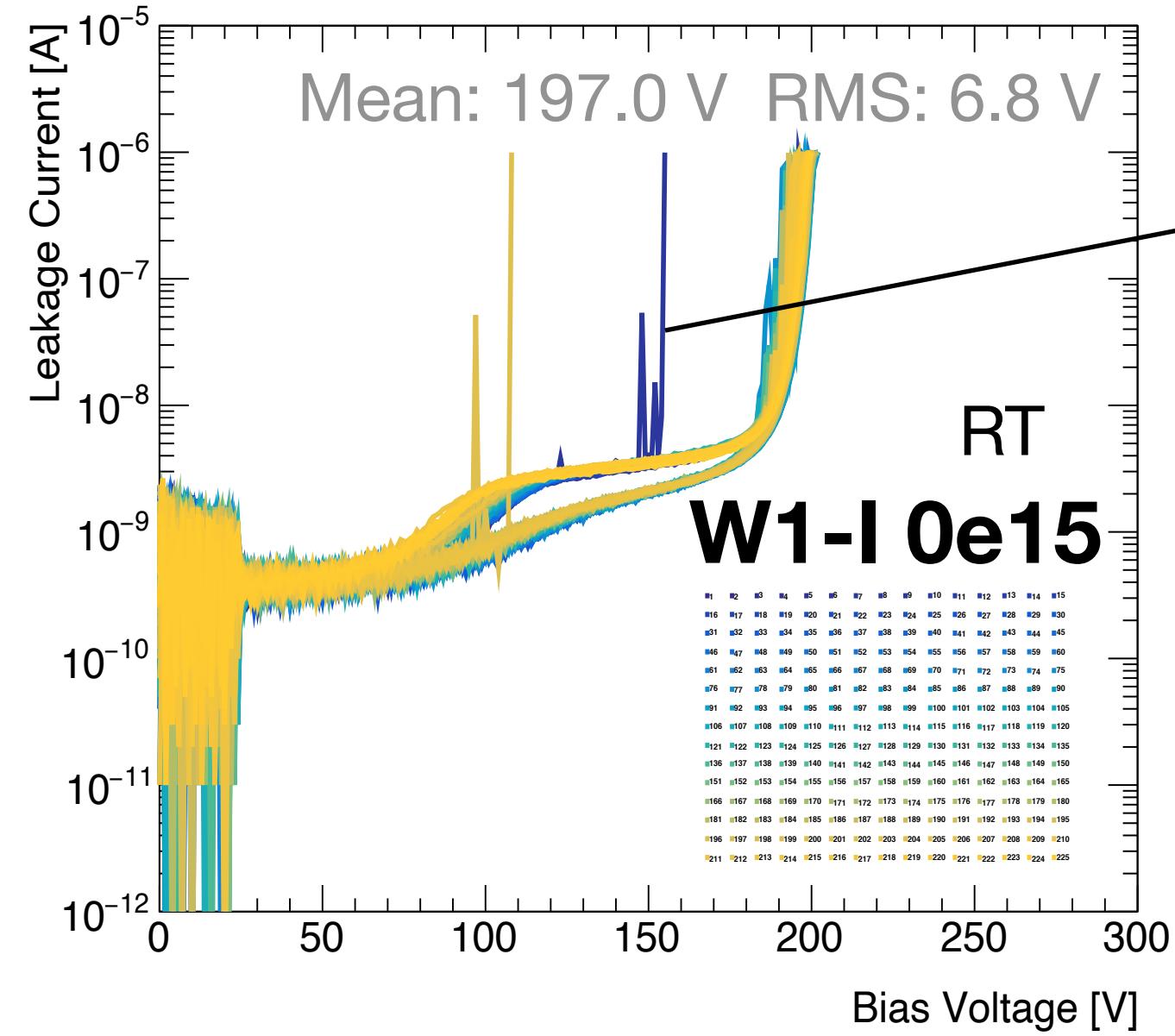
Large array sensor after radiation



- After 1.5×10^{15} , compared with the W7-II $2\mu A@405 V$, shows that carbon makes the sensor more radiation hard.
- More uniformed I-V after irradiation. $2 \mu A@ \sim 700 V$

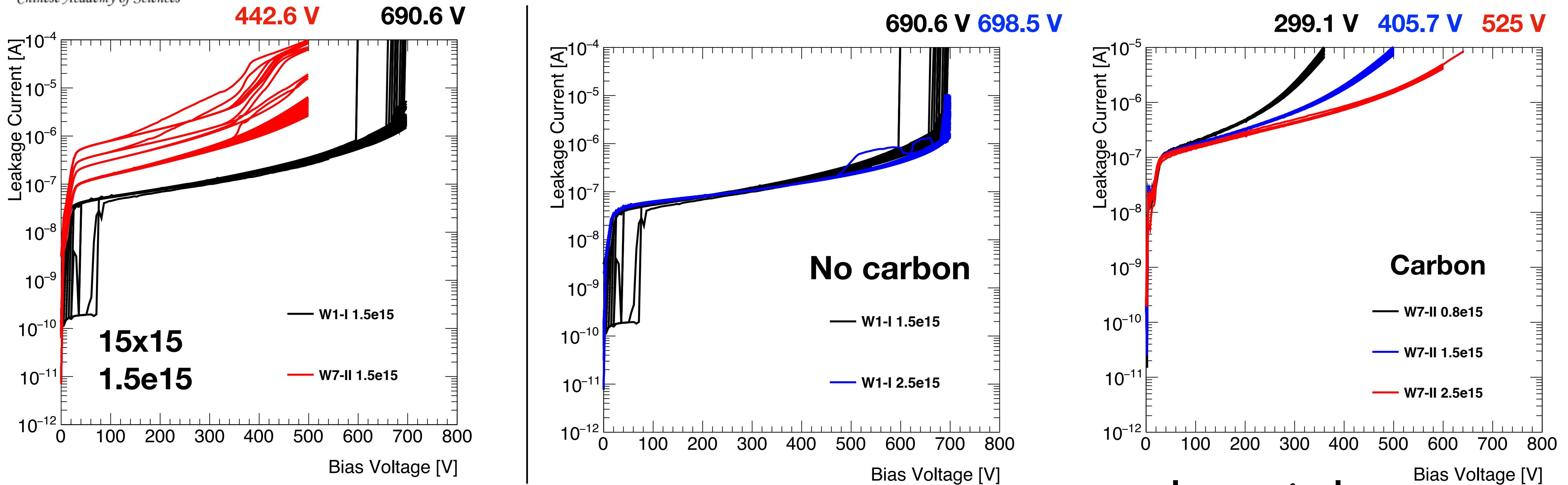


Large array sensor after radiation



- After irradiation I-V curves became more uniformed because of the acceptor removal. The sensor requires higher voltage to operate. (~ 700 V)
 - After 2.5×10^{15} , compared with the W7-II $2\mu\text{A}@525$ V, shows that carbon implantation make the sensor more irradiation hard.

Large array sensor after radiation



- Carbon implanted sensor have higher current after irradiation because of **less gain loss**.
- The working voltage of carbon implanted sensor is much lower.
- Sensor without carbon after different fluence radiation, the I-V difference is small, since most of the gain was lost.
- While the sensor with carbon implantation after different fluence radiation are quite different, since the more gain was kept after radiation. \longleftrightarrow Radiation hard

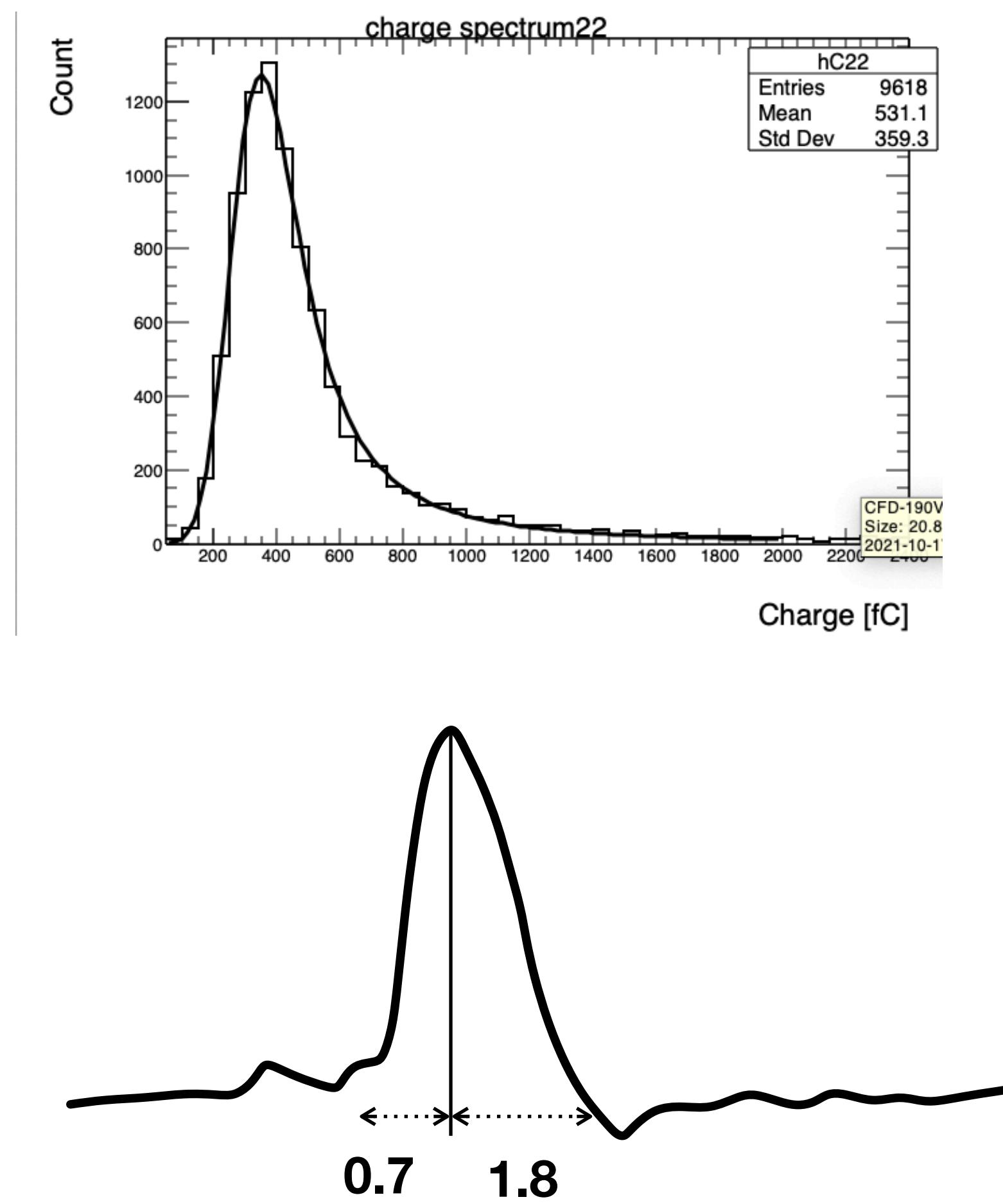
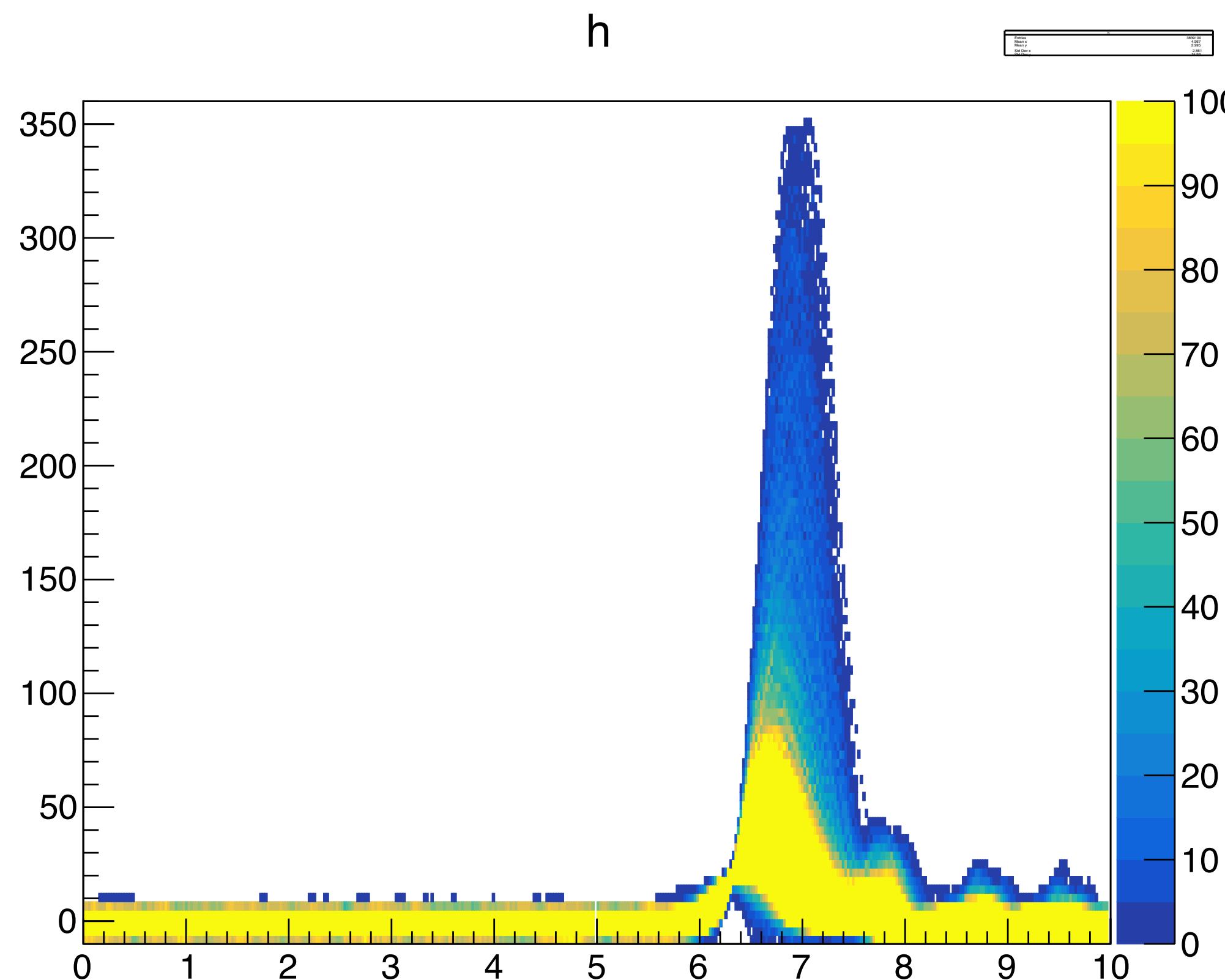


Summary

- IHEP-IME LGAD sensors showed promising results for the ATLAS HGTD project before and after irradiation. **Carbon implantation for the irradiation hardness was optimized.**
- Before irradiation:
 - When carbon dose increase: $\begin{cases} \text{the leakage current increase} \\ \text{the breakdown voltage decrease} \\ \text{the } V_{gl} \text{ increase} \end{cases}$
 - Best time resolution ~ 40 ps, charge collection >35 fC
 - Large array sensor satisfy the HGTD requirements
- After irradiation:
 - **IHEP-IMEv2 W7-II has the best performance** $\begin{cases} \text{- with acceptor removal 1.2.} \\ \text{- 4 fC@350V(2.5e15)/150V(1.5 e15), } \sim 50 \text{ ps.} \\ \text{- Satisfied all the requirements for HGTD including} \\ \text{the SEB one, within safety margin} \end{cases}$
 - Long annealing overall more radiation hard than fast annealing though before irradiation they are close.
 - Large array sensor have more uniformed I-V because of the gain loss, however the ones with carbon implantation can still keep some characteristics, validating the carbon's role in improving the radiation hardness.

Back-up

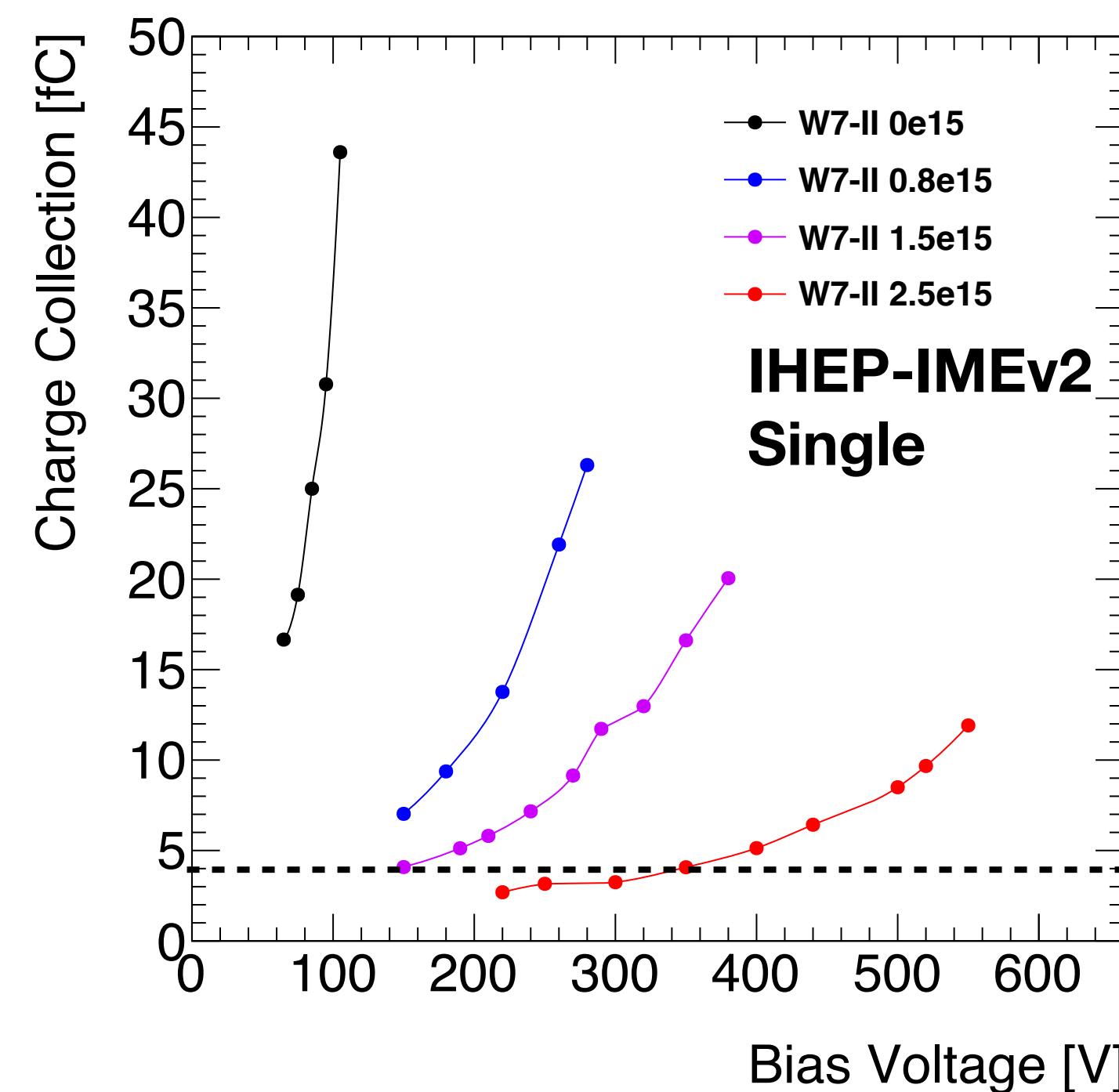
Charge



IHEP-IMEv2 Introduction

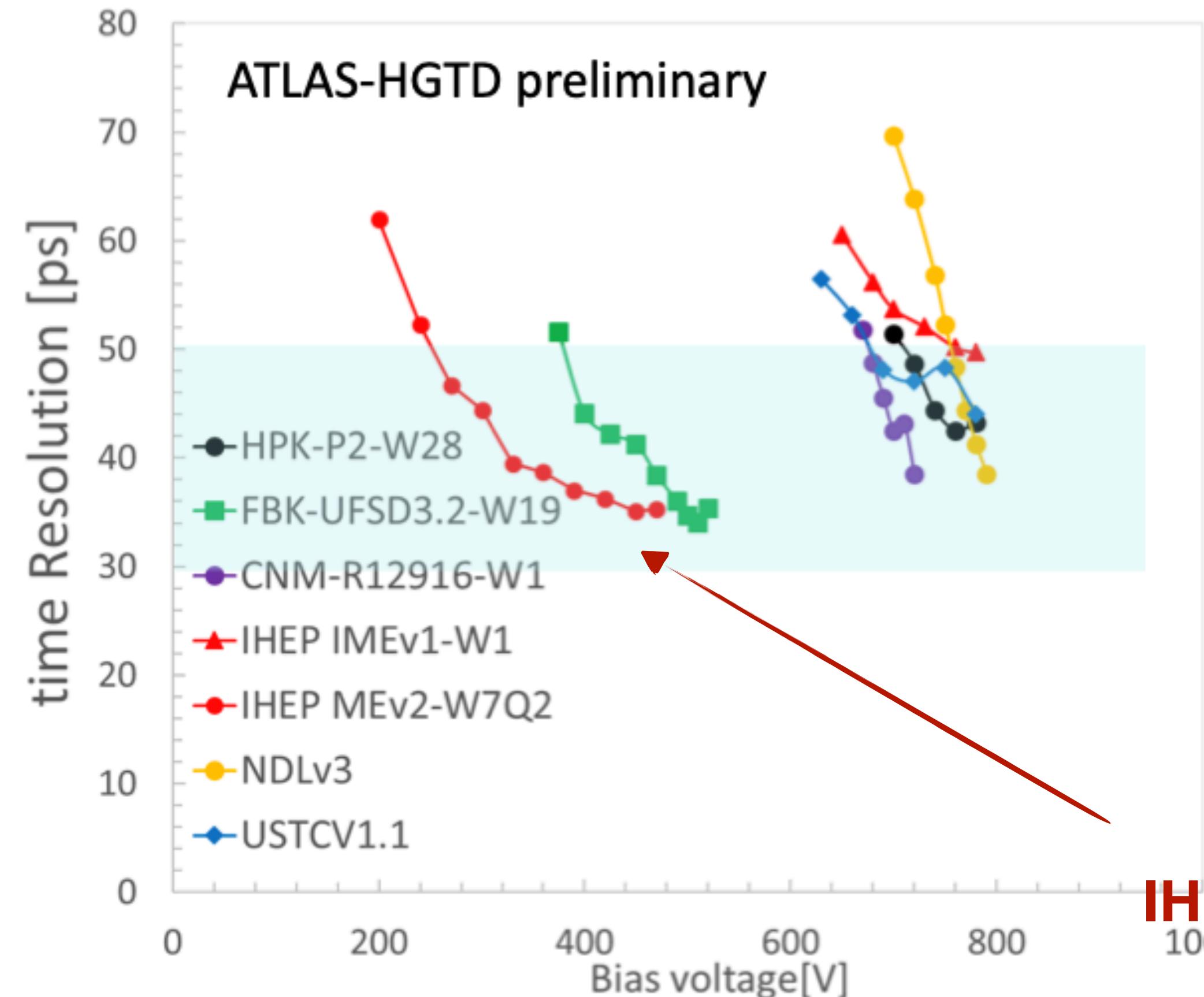
- IHEP-IMEv2:
 - W1 without carbon implantation
 - W7 carbon long annealing

**W7-II(0.5C) 4 fC@
~100 V (0.8e15); 150 V (1.5e15); 350 V (2.5e15)**

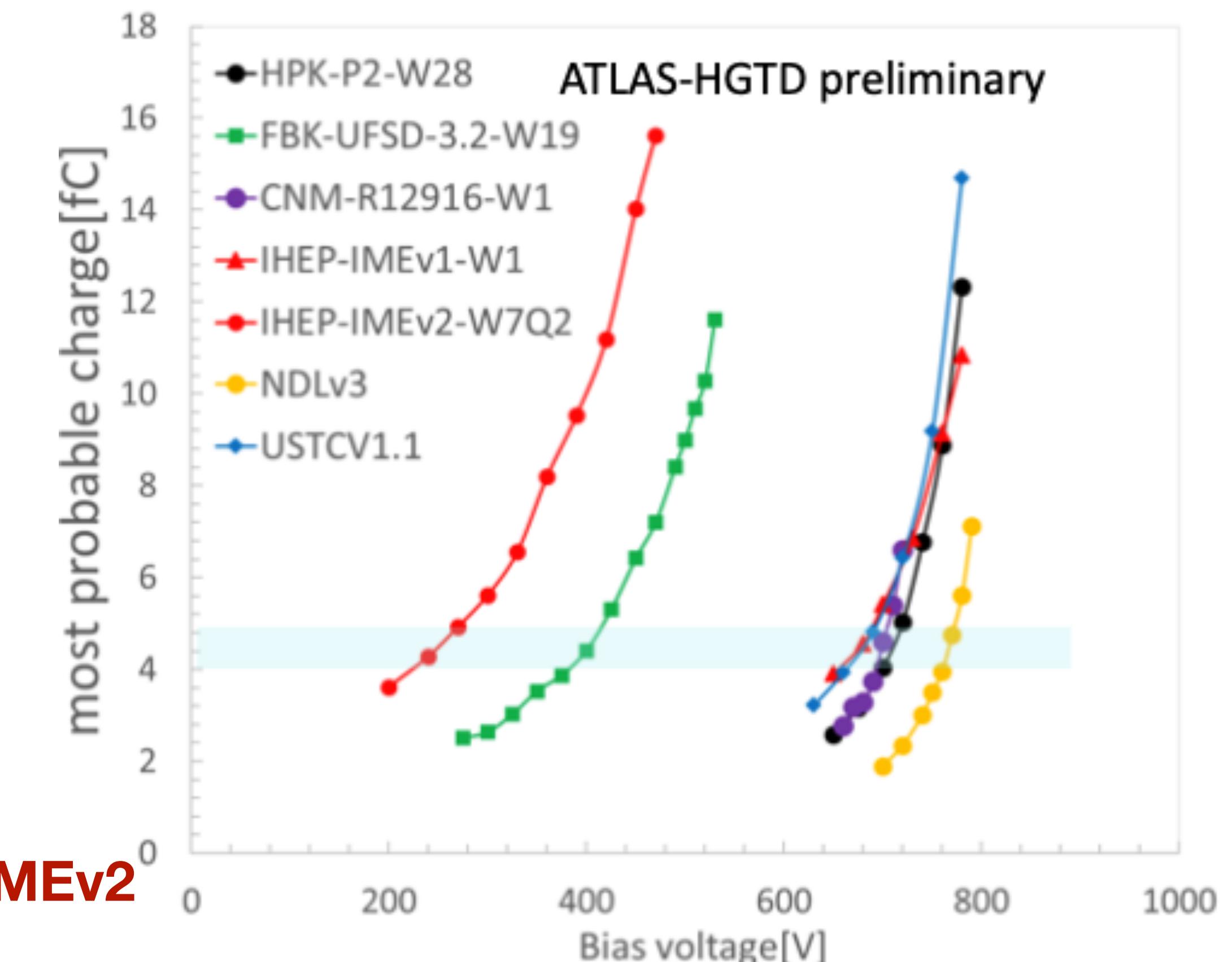


Carbonated sensor performance after irradiation

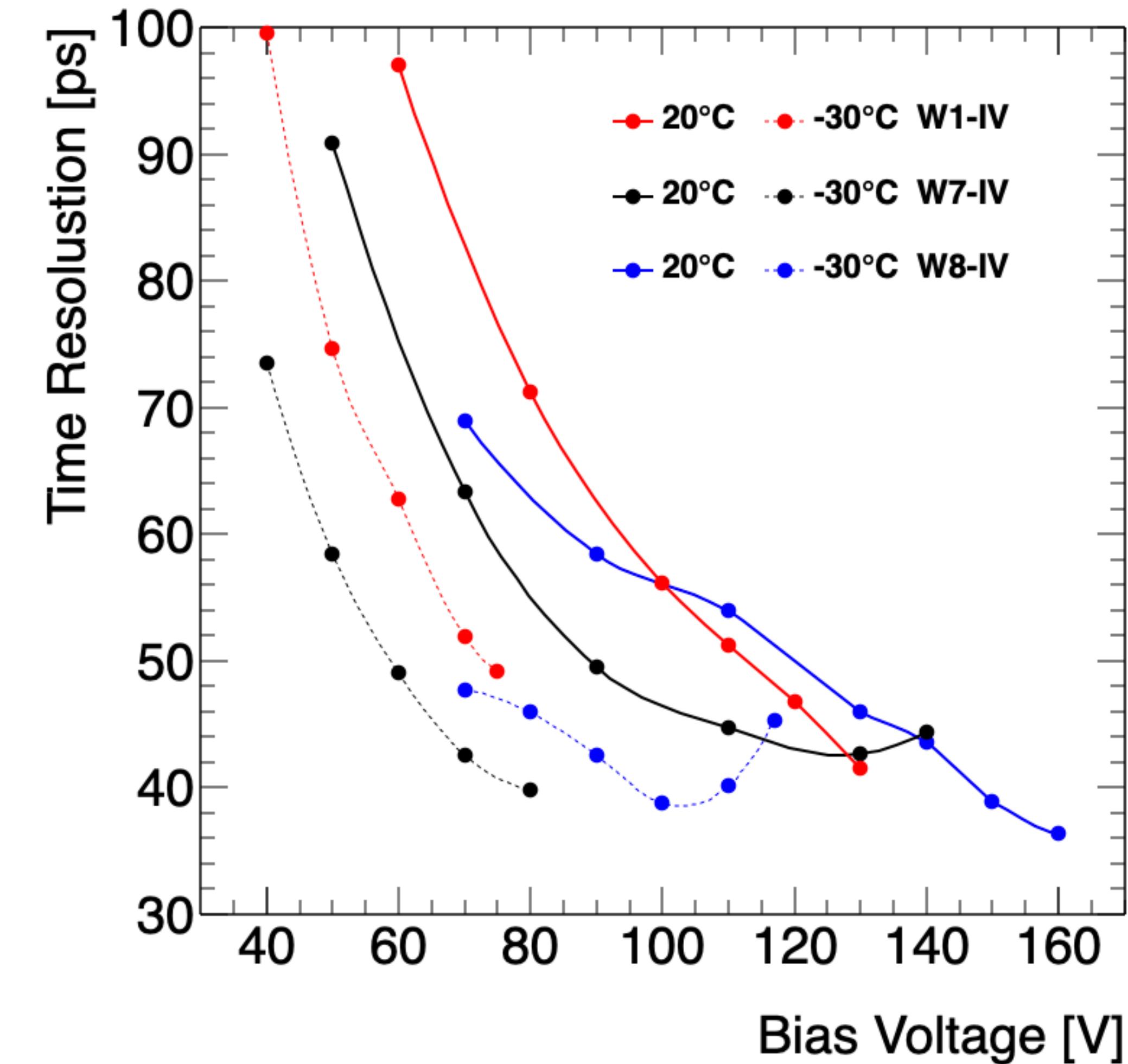
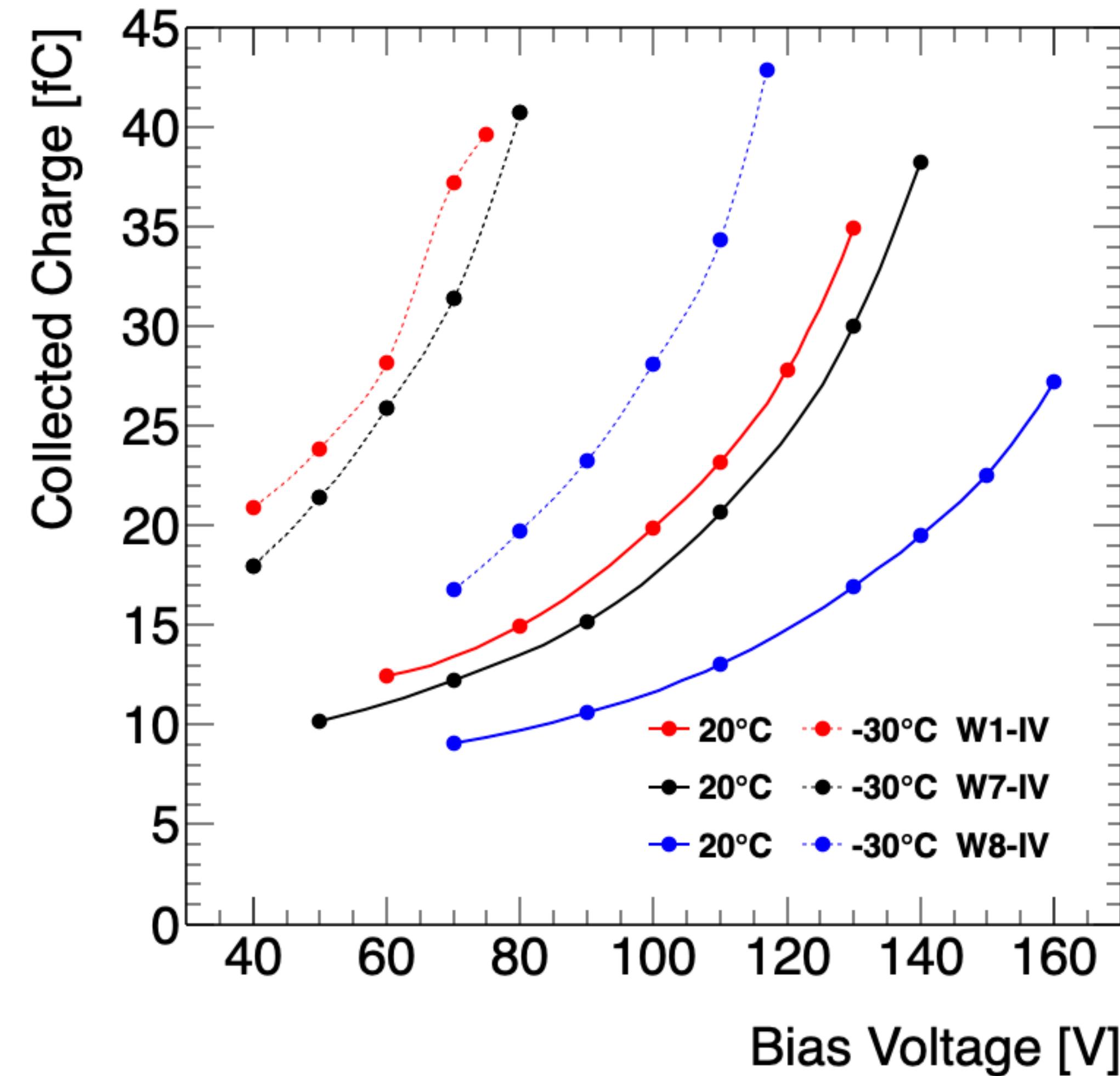
After 2.5×10^{15} irradiation:



IHEP-IMEv2

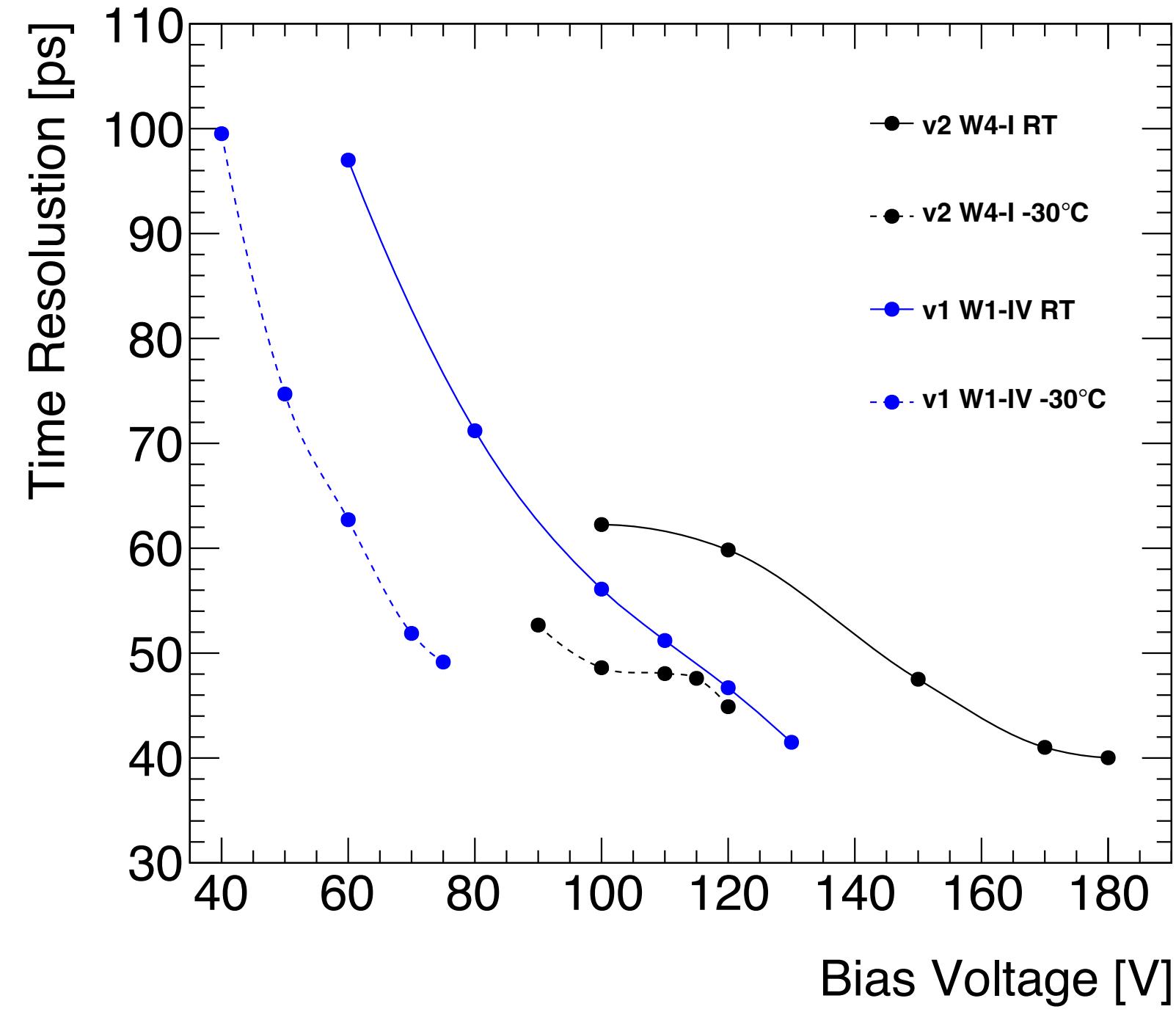


Lower operation voltage save more power.
Also good for mortality in the testbeam.

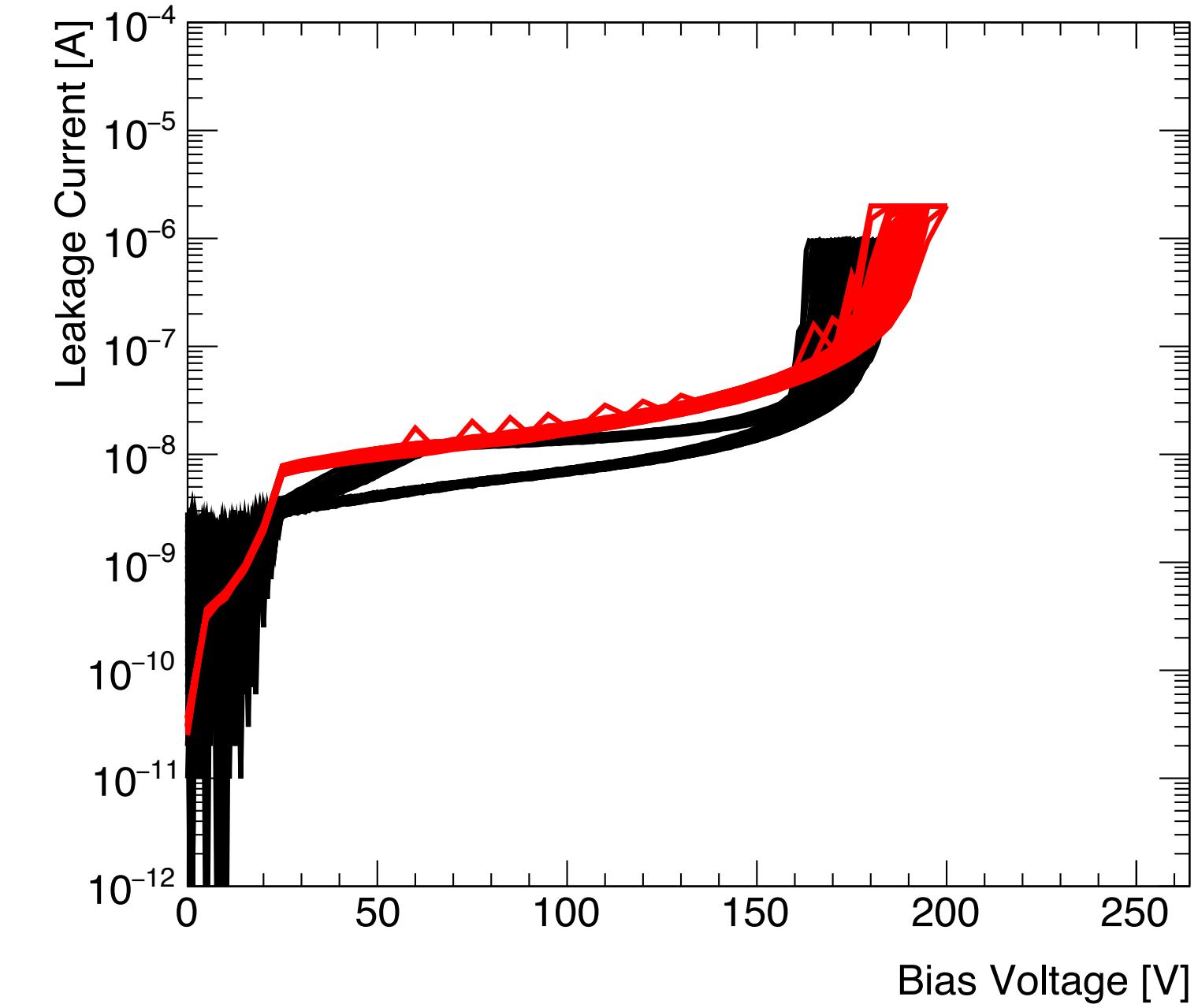
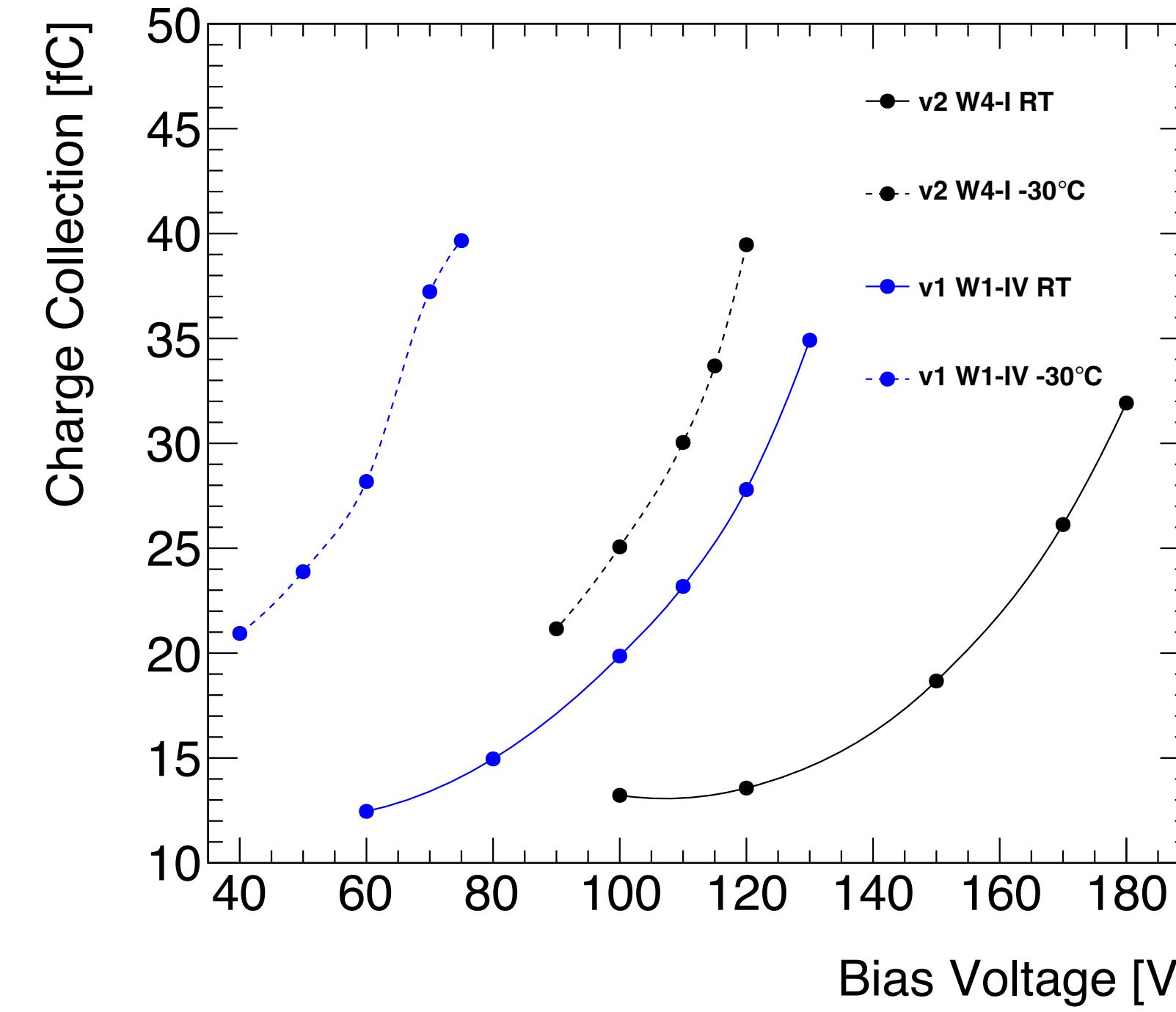




Before irradiation

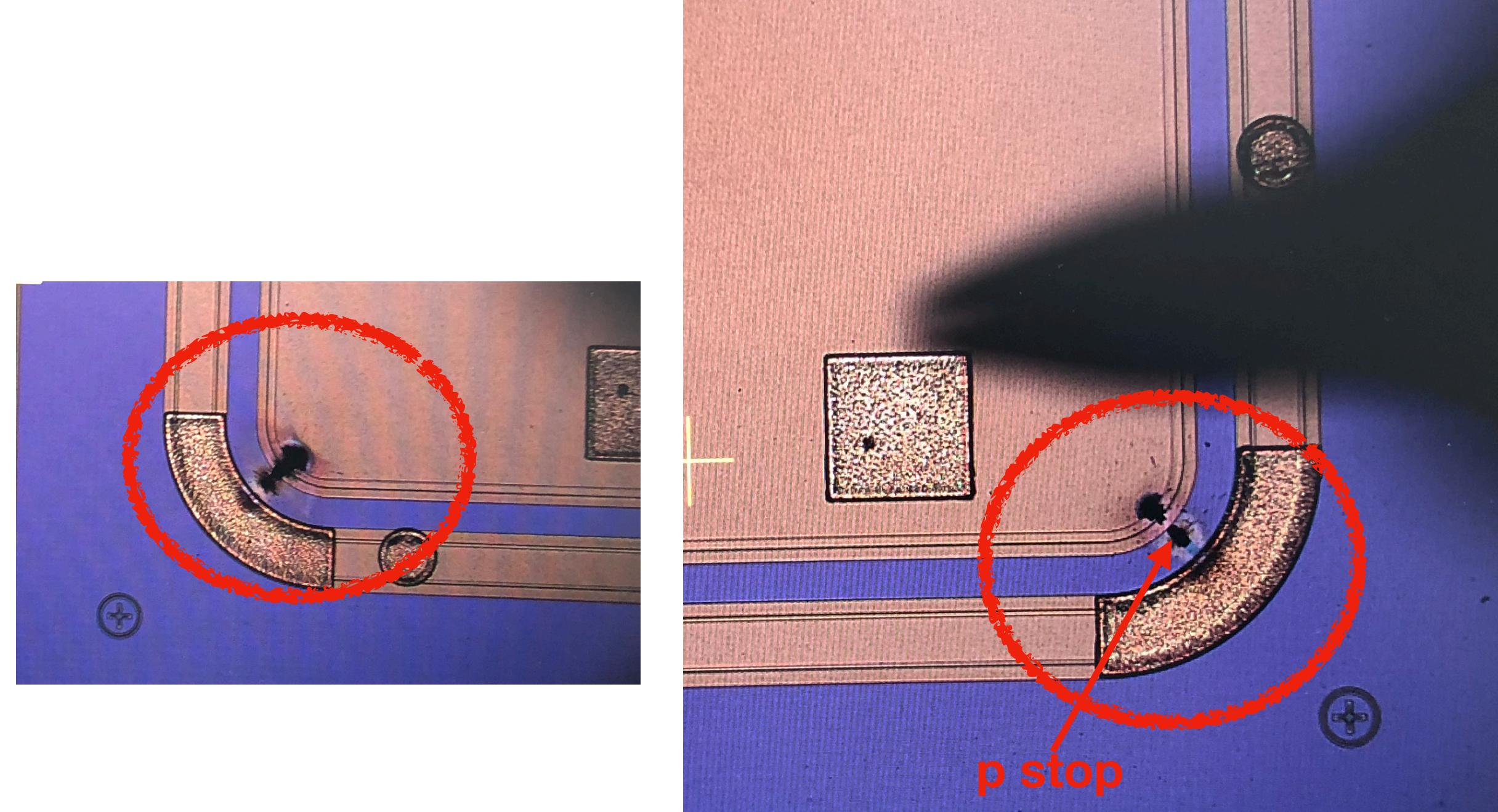
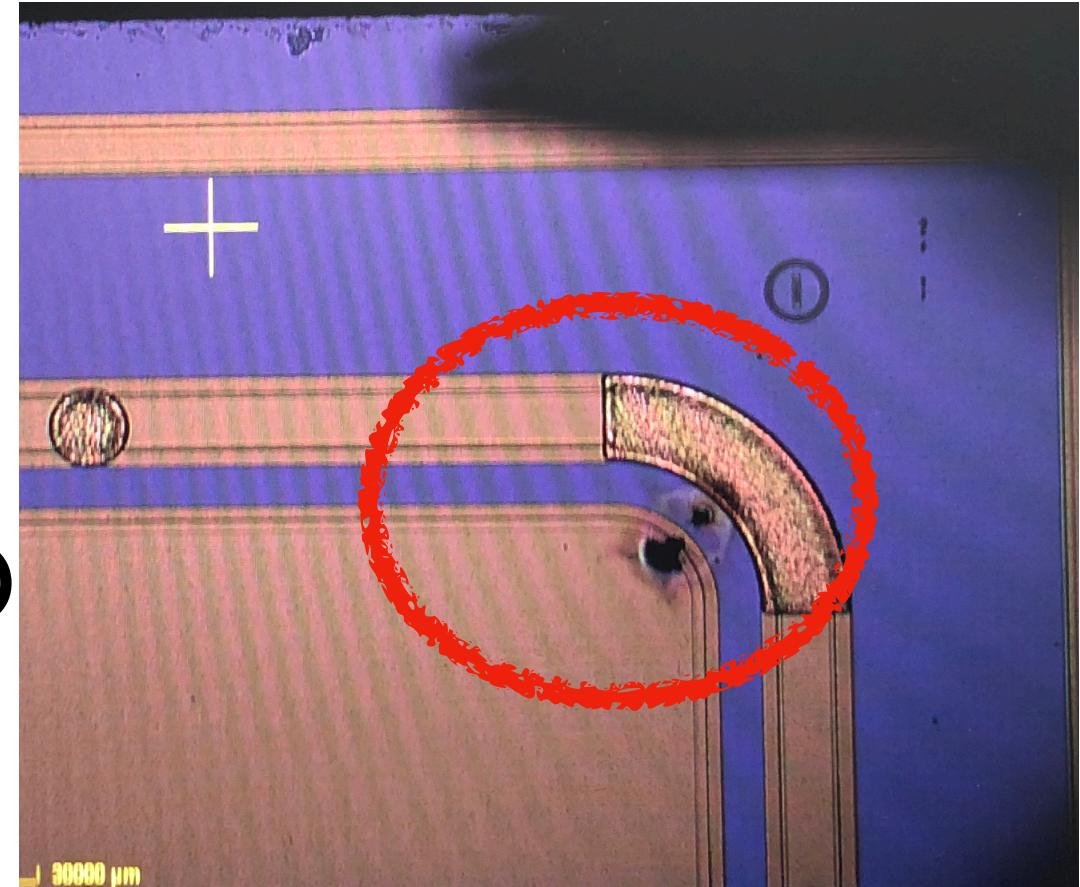
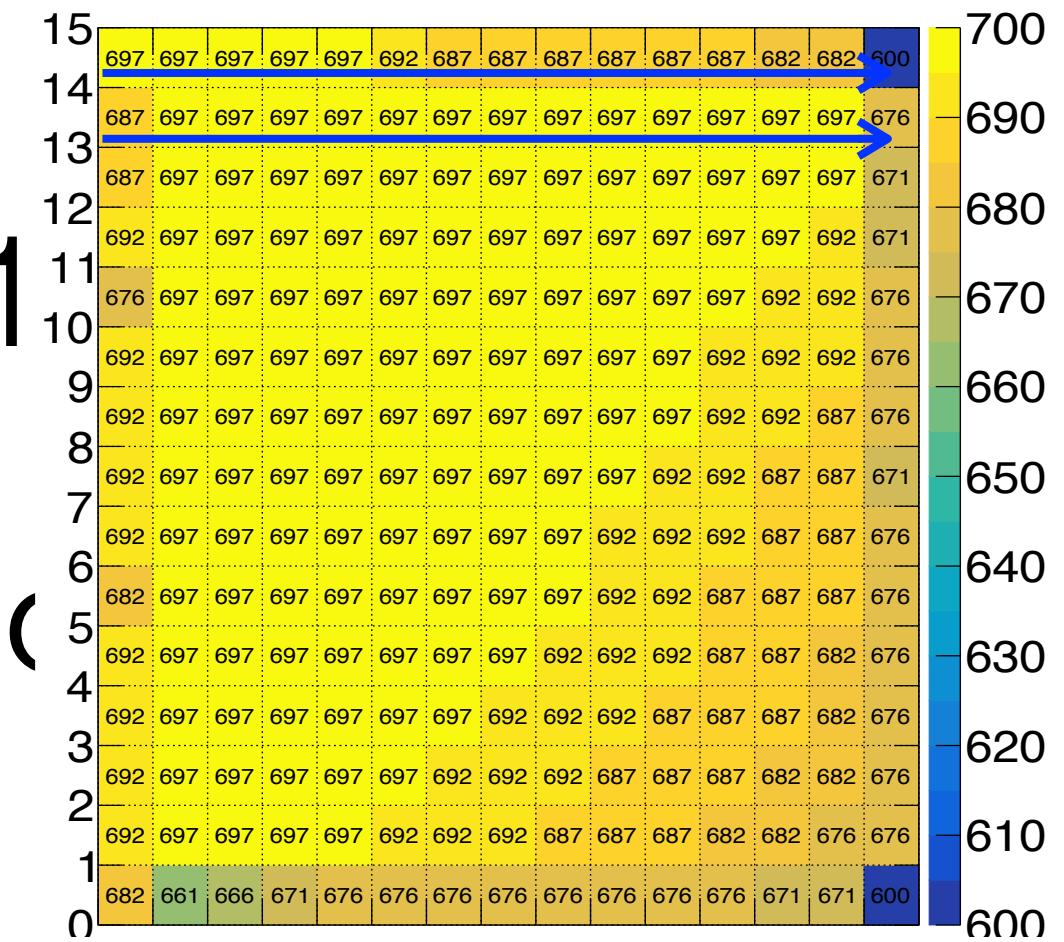


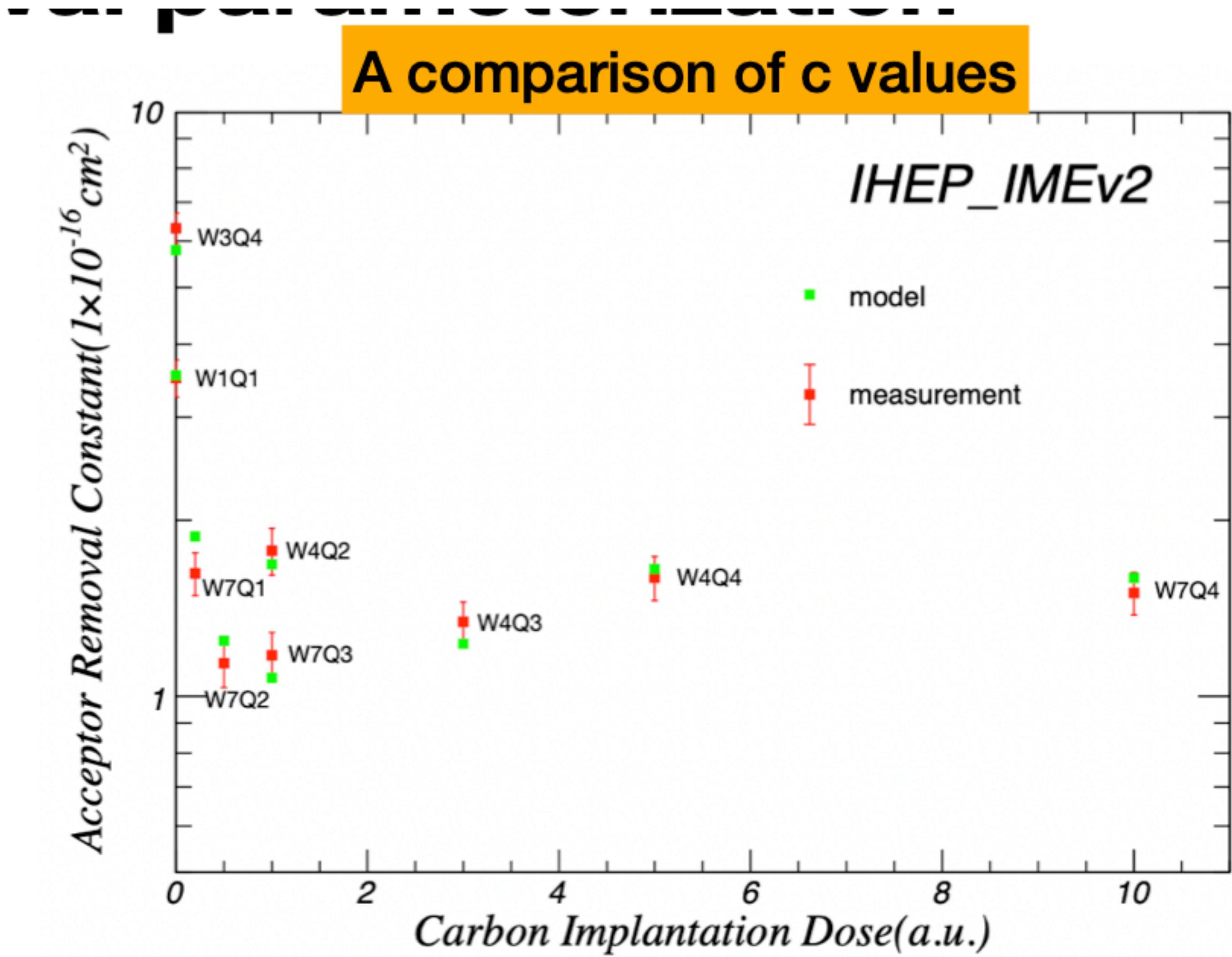
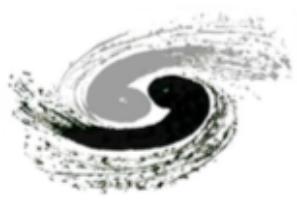
Before irradiation



15x15 I-V after irradiation

- W1-I, without carbon, after 1.5×10^{11} p/cm²
- The test started from the up left corner and went to the right corner row by row.
- (0,700V) 5V step
- In total took 2h13min
- Burn marks in the corner





- The modeled c factors have a good agreement with measurement.